HT48E06, HT48E10, HT48E30, HT48E50, HT48E70 I/O Type MTP MCU with EEPROM Handbook

First Edition

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Preface

Since Holtek Semiconductor's beginnings, the company has focused much of its design efforts in the area of microcontroller development. Although supplying a wide range of semiconductor devices, the microcontroller category has always been a key product category within the complete Holtek range, and one which will continue to expand as their devices increase in functionality and maturity. By capitalizing on the substantial accumulated skills within its dedicated microcontroller development department, Holtek has been able to release a comprehensive range of feature packed, high quality low-cost microcontroller devices for a wide range of application areas. Among the various categories, a key Holtek MCU area is the I/O Type MTP with EEPROM range of devices. Because of their inherent multi-programmable capabilities, these devices can be reprogrammed many times by the user, which when combined with Holtek's comprehensive range of development tools provide designers with a convenient and cost effective way of debug and product development. In addition the internal EEPROM Data Memory has the ability to retain data even after power is removed, an important feature for many of today's applications, where it is required to store information, such as product parameters, setup information or part number, etc.

This handbook is divided into three parts for user convenience. Most details regarding device information and specifications are located within Part I. Information related to microcontroller programming such as device instruction set, instruction definition, and assembly language directives is found within Part II. Part III relates to the Holtek range of Development Tools where information can be found on their installation and use.

By compiling all relevant data together in one handbook, it is anticipated that users of the Holtek range of I/O Type MTP microcontrollers with EEPROM will have at their disposal a useful, complete and easy to use means to efficiently implement their microcontroller applications. Holtek's efforts to combine information on device specifications, programming and development tools into one publication have produced a handbook which with careful use by the user should result in trouble free designs and the maximum benefit being gained from the many features of Holtek microcontroller devices. We recommend that users regularly check our website for the latest updates to our handbook and also welcome feedback and comments from our customers regarding further improvements.





Part I

Microcontroller Profile





Chapter 1

Hardware Structure

1

This section is the main datasheet part of the I/O Type MTP microcontroller with EEPROM handbook and contains all the parameters and information related to the device hardware. The information contained provides designers with details on all the main hardware features of the I/O Type MTP MCU with EEPROM series which together with the programming section contains the information to enable swift and successful implementation of user microcontroller applications. By proper consultation of the relevant parts of this section, users can ensure that they make the most efficient use of the flexible and multi-function multi-programmable features within the I/O Type MTP microcontroller with EEPROM series.

Introduction

The HT48E06, HT48E10, HT48E30, HT48E50 and HT48E70 are 8-bit high-performance, RISC architecture microcontroller devices specifically designed for multiple I/O control product applications. Device flexibility is enhanced with their internal special features such as power-down and wake-up functions, oscillator options, buzzer driver, etc. These features combine to ensure applications require a minimum of external components and therefore reduce overall product costs. Having the advantages of low-power consumption, high-performance, I/O flexibility as well as low-cost, these devices have the versatility to suit a wide range of application possibilities such as industrial control, consumer products, subsystem controllers, etc. Many features are common to all devices, however, they differ in areas such as I/O pin count, RAM and Program Memory capacity, timer number and size, etc.

The HT48E06, HT48E10, HT48E30, HT48E50 and HT48E70 devices, with their multi-programmable ability and internal EEPROM offer the advantages of permitting easy and efficient program updates using the Holtek range of development and programming tools, allowing a means for fast and low-cost product development cycles.



Features

Technology Features

- High-performance RISC Architecture
- Operating Voltage: f_{SYS}=4MHz: 2.2V~5.5V

f_{SYS}=8MHz: 3.3V~5.5V

• Power Consumption:

3mA Typical at 5V 4MHz

Maximum of $3\mu\text{A}$ Standby Current at 3V with WDT Disabled

• Temperature Range:

Operating Temperature -40°C to 85°C (Industrial Grade)

Storage Temperature -50°C to 125°C

Kernel Features

• MTP Program Memory:

1024×14 (HT48E06, HT48E10)

2048×14 (HT48E30)

4096×15 (HT48E50)

8192×16 (HT48E70)

• EEPROM Data Memory:

128×8 (HT48E06, HT48E10, HT48E30)

256×8 (HT48E50, HT48E70)

• RAM Data Memory:

64×8 (HT48E06, HT48E10)

96×8 (HT48E30)

160×8 (HT48E50)

224×8 (HT48E70)

- Table Read Function
- Multi-level Hardware Stack:

2-level (HT48E06)

4-level (HT48E10, HT48E30)

6-level (HT48E50)

16-level (HT48E70)

- Bit Manipulation Instructions
- 63 Powerful Instructions
- All Instructions Implemented in 1 or 2 Machine Cycles



Peripheral Features

- From 13 to 56 Bidirectional I/O with Pull-high Options
- External Interrupt Input
- Event Counter Input
- Full Timer Functions with Prescaler and Interrupt
- Watchdog Timer (WDT)
- Power Down and Wake-up Feature for Power Saving Operation
- PFD/Buzzer Driver Outputs
- Crystal and RC System Oscillator
- Low Voltage Reset (LVR) Feature for Brown-out Protection
- Programming Interface
- Full Suite of Supported Hardware and Software Tools Available

Selection Table

The series of I/O Type MTP microcontrollers with EEPROM include a comprehensive range of features, some of which are standard and some of which are device dependent. Most features are common to all devices, the main features distinguishing them are Program Memory, Data Memory, Data EEPROM capacity, I/O count and timer functions. To assist users in their selection of the most appropriate device for their application, the following table, which summarises the main features of each device, is provided.

Part No.	VDD	Program Memory	Data Memory	Data EEPROM	I/O	Timer	Interrupt	Stack	Package Types
HT48E06	2.2V~5.5V	1K×14	64×8	128×8	13	8-bit×1	2	2	18DIP/SOP, 20SSOP
HT48E10	2.2V~5.5V	1K×14	64×8	128×8	19	8-bit×1	2	4	24SKDIP/SOP
HT48E30	2.2V~5.5V	2K×14	96×8	128×8	23	8-bit×1	2	4	24SKDIP/SOP, 28SKDIP/SOP
HT48E50	2.2V~5.5V	4K×15	160×8	256×8	33	8-bit×1 16-bit×1	3	6	28SKDIP/SOP, 48SSOP
HT48E70	2.2V~5.5V	8K×16	224×8	256×8	56	16-bit×2	3	16	48SSOP, 64QFP

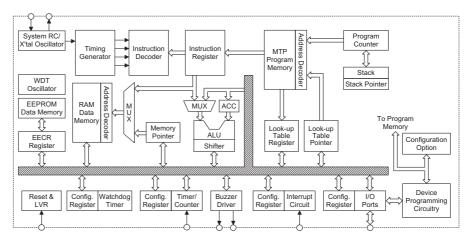
Note

For devices that exist in more than one package formats, the table reflects the situation for the larger package.

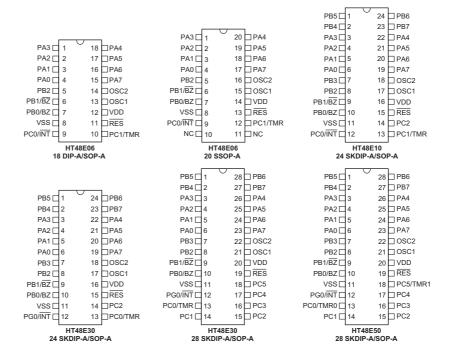


Block Diagram

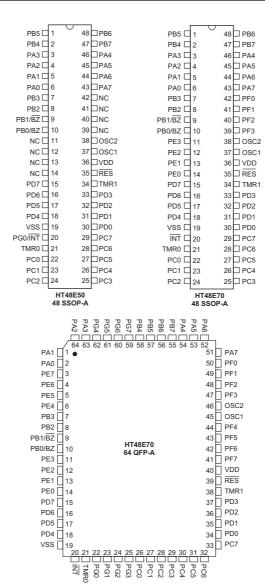
The following block diagram illustrates the main functional blocks of the I/O Type MTP microcontroller with EEPROM series of devices.



Pin Assignment









Pin Description

HT48E06

Pin Name	I/O	Configuration Option	Description
PA0~PA7	I/O	Pull-high Wake-up	Bidirectional 8-bit input/output port. Each pin can be configured as a wake-up input by configuration option. Software instructions determine if the pin is a CMOS output or Schmitt Trigger input. A configuration option determines if all pins on this port have pull-high resistors.
PB0/BZ PB1/BZ PB2	I/O	Pull-high I/O or BZ/BZ	Bidirectional 3-bit input/output port. Software instructions determine if the pin is a CMOS output or Schmitt Trigger input. A configuration option determines if all pins on this port have pull-high resistors. Pins PB0 and PB1 are pin-shared with BZ and $\overline{\text{BZ}}$, respectively.
PC0/INT PC1/TMR	I/O	Pull-high	Bidirectional 2-bit input/output port. Software instructions determine if the pin is a CMOS output or Schmitt Trigger input. A configuration option determines if all pins on this port have pull-high resistors. PC0 is pin-shared with the external interrupt pin INT and PC1 is pin-shared with the external timer input pin TMR.
OSC1 OSC2	I 0	Crystal or RC	OSC1, OSC2 are connected to an external RC network or external crystal, determined by configuration option, for the internal system clock. If the RC system clock option is selected, pin OSC2 can be used to measure the system clock at 1/4 frequency.
RES	ı	_	Schmitt Trigger reset input. Active low.
VDD	_	_	Positive power supply
VSS	_	_	Negative power supply, ground

- **Note** 1. Each pin on PA can be programmed through a configuration option to have a wake-up function.
 - 2. Individual pins cannot be selected to have pull-high resistors. If the pull-high configuration is chosen for a particular port, then all input pins on this port will be connected to pull-high resistors.



Pin Name	I/O	Configuration Option	Description
PA0~PA7	I/O	Pull-high Wake-up Schmitt Trigger	Bidirectional 8-bit input/output port. Each pin can be configured as a wake-up input by configuration option. Software instructions determine if the pin is a CMOS output or input. Configuration options determine if all pins on this port have pull-high resistors and if the inputs are Schmitt Trigger or non-Schmitt Trigger.
PB0/BZ PB1/BZ PB2~PB7	I/O	Pull-high I/O or BZ/BZ	Bidirectional 8-bit input/output port. Software instructions determine if the pin is a CMOS output or Schmitt Trigger input. A configuration option determines if all pins on this port have pull-high resistors. Pins PB0 and PB1 are pin-shared with BZ and $\overline{\text{BZ}}$, respectively.
PC0/INT PC1/TMR PC2	I/O	Pull-high	Bidirectional 3-bit input/output port. Software instructions determine if the pin is a CMOS output or Schmitt Trigger input. A configuration option determines if all pins on this port have pull-high resistors. Pin PC0 is pin-shared with external interrupt pin $\overline{\text{INT}}$ and PC1 shared with external timer pin TMR.
OSC1 OSC2	I 0	Crystal or RC	OSC1, OSC2 are connected to an external RC network or external crystal, determined by configuration option, for the internal system clock. If the RC system clock option is selected, pin OSC2 can be used to measure the system clock at 1/4 frequency.
RES	ı	_	Schmitt Trigger reset input. Active low.
VDD	_	_	Positive power supply
vss	_	_	Negative power supply, ground

Note

- 1. Each pin on PA can be programmed through a configuration option to have a wake-up function.
- 2. Individual pins cannot be selected to have pull-high resistors. If the pull-high configuration is chosen for a particular port, then all input pins on this port will be connected to pull-high resistors.



Pin Name	I/O	Configuration Option	Description
PA0~PA7	I/O	Pull-high Wake-up Schmitt Trigger	Bidirectional 8-bit input/output port. Each pin can be configured as a wake-up input by configuration option. Software instructions determine if the pin is a CMOS output or input. Configuration options determine if all pins on this port have pull-high resistors and if the inputs are Schmitt Trigger or non-Schmitt Trigger.
PB0/BZ PB1/BZ PB2~PB7	I/O	Pull-high I/O or BZ/BZ	Bidirectional 8-bit input/output port. Software instructions determine if the pin is a output or Schmitt Trigger input. A configuration option determines if all pins on this port have pull-high resistors. Pins PB0 and PB1 are pin-shared with BZ and $\overline{\rm BZ}$, respectively.
PC0/TMR PC1~PC5	I/O	Pull-high	Bidirectional 6-bit input/output port. Software instructions determine if the pin is a output or Schmitt Trigger input. A configuration option determines if all pins on this port have pull-high resistors. PC0 is pin-shared with external timer pin TMR.
PG0/INT	I/O	Pull-high	Bidirectional 1-bit input/output port. Software instructions determine if the pin is a CMOS output or Schmitt Trigger input. A configuration option determines if the pin has a pull-high resistor. PG0 is pin-shared with external interrupt pin $\overline{\text{INT}}$.
OSC1 OSC2	I 0	Crystal or RC	OSC1, OSC2 are connected to an external RC network or external crystal, determined by configuration option, for the internal system clock. If the RC system clock option is selected, pin OSC2 can be used to measure the system clock at 1/4 frequency.
RES	ı	_	Schmitt Trigger reset input. Active low.
VDD	_	_	Positive power supply
vss	_	_	Negative power supply, ground

Note

- 1. Each pin on PA can be programmed through a configuration option to have a wake-up function.
- Individual pins cannot be selected to have pull-high resistors. If the pull-high configuration is chosen for a particular port, then all input pins on this port will be connected to pull-high resistors.
- 3. Pins PC1 and PC3~PC5 only exist on the 28-pin package. On the 24-pin package, these pins are not available.



Pin Name	I/O	Configuration Option	Description
PA0~PA7	I/O	Pull-high Wake-up Schmitt Trigger	Bidirectional 8-bit input/output port. Each pin can be configured as a wake-up input by configuration option. Software instructions determine if the pin is a CMOS output or input. Configuration options determine if all pins on this port have pull-high resistors and if the inputs are Schmitt Trigger or non-Schmitt Trigger.
PB0/BZ PB1/BZ PB2~PB7	I/O	Pull-high I/O or BZ/BZ	Bidirectional 8-bit input/output port. Software instructions determine if the pin is a CMOS output or Schmitt Trigger input. A configuration option determines if all pins on this port have pull-high resistors. Pins PB0 and PB1 are pin-shared with BZ and $\overline{\text{BZ}}$, respectively.
PC0/TMR0 PC5/TMR1 PC1~PC4 PC6~PC7	I/O	Pull-high	Bidirectional 8-bit input/output port. Software instructions determine if the pin is a CMOS output or Schmitt Trigger input. A configuration option determines if all pins on this port have pull-high resistors. TMR0 and TMR1 are pin-shared with PC0 and PC5 respectively in the 28-pin package.
PD0~PD7	I/O	Pull-high	Bidirectional 8-bit input/output port. Software instructions determine if the pin is a CMOS output or Schmitt Trigger input. Configuration options determine if all pins on this port have pull-high resistors.
PG0/INT	I/O	Pull-high	Bidirectional 1-bit input/output ports. Software instructions determine if the pin is a CMOS output or Schmitt Trigger input. A configuration option determines if the pin has a pull-high resistor. PG0 is pin-shared with external interrupt pin $\overline{\text{INT}}$.
TMR0	ı	_	Schmitt Trigger input for Timer/Event Counter 0 (48-pin package only)
TMR1	ı	_	Schmitt Trigger input for Timer/Event Counter 1 (48-pin package only)
OSC1 OSC2	0	Crystal or RC	OSC1, OSC2 are connected to an external RC network or external crystal, determined by configuration option, for the internal system clock. If the RC system clock option is selected, pin OSC2 can be used to measure the system clock at 1/4 frequency.
RES	ı		Schmitt Trigger reset input. Active low.
VDD	_	_	Positive power supply
vss	_	_	Negative power supply, ground



- **Note** 1. Each pin on PA can be programmed through a configuration option to have a wake-up function.
 - 2. Individual pins cannot be selected to have pull-high resistors. If the pull-high configuration is chosen for a particular port, then all input pins on this port will be connected to pull-high resistors.
 - 3. On the 48-pin package Port C has no shared pins. All of Port C pins exist as I/Os as the TMR0 and TMR1 are independent pins.
 - 4. Pins PC6 and PC7 only exist on the 48-pin package.
 - 5. Port D is only present on the 48-pin package.

Pin Name	I/O	Configuration Option	Description	
PA0~PA7	I/O	Pull-high Wake-up Schmitt Trigger	Bidirectional 8-bit input/output port. Each pin can be configured as a wake-up input by configuration option. Software instructions determine if the pin is a CMOS output or input. Configuration options determine if all pins on this port have pull-high resistors and if the inputs are Schmitt Trigger or non-Schmitt Trigger.	
PB0/BZ PB1/BZ PB2~PB7 PC0~PC7 PD0~PD7 PE0~PE7 PF0~PF7 PG0~PG7	I/O	Pull-high I/O or BZ/BZ	Bidirectional 8-bit input/output ports. Software instructions of termine if the pin is a CMOS output or Schmitt Trigger input. configuration option for each port determines if all pins on the relevant port have pull-high resistors. Pins PB0 and PB1 apin-shared with BZ and $\overline{\text{BZ}}$, respectively.	
ĪNT	ı	_	External interrupt Schmitt Trigger input.	
TMR0	ı	_	Schmitt Trigger input for Timer/Event Counter 0	
TMR1	ı		Schmitt Trigger input for Timer/Event Counter 1	
OSC1 OSC2	1 0	Crystal or RC	OSC1, OSC2 are connected to an external RC network or external crystal, determined by configuration option, for the internal system clock. If the RC system clock option is selected, pin OSC2 can be used to measure the system clock at 1/4 frequency.	
RES	I		Schmitt Trigger reset input. Active low.	
VDD	_		Positive power supply	
VSS		_	Negative power supply, ground	



- **Note** 1. Each pin on PA can be programmed through a configuration option to have a wake-up function.
 - 2. Individual pins cannot be selected to have pull-high resistors. If the pull-high configuration is chosen for a particular port, then all input pins on this port will be connected to pull-high
 - 3. Pins PE4~PE7 and pins PF4~PF7 only exist on the 64-pin package.
 - 4. Port G only exists on the 64-pin package.

Absolute Maximum Ratings

Supply Voltage	V _{SS} -0.3V to V _{SS} +6.0V
Input Voltage	V_{SS} -0.3V to V_{DD} +0.3V
Storage Temperature	50°C to 125°C
Operating Temperature	40°C to 85°C
I _{OL} Total	150mA
I _{OH} Total	–100mA
Total Power Dissipation	500mW

These are stress ratings only. Stresses exceeding the range specified under Absolute Maximum Ratings may cause substantial damage to the device. Functional operation of this device at other conditions beyond those listed in the specification is not implied and prolonged exposure to extreme conditions may affect device reliability.

D.C. Characteristics

HT48E06, HT48E10, HT48E30

Ta=25°C

C. mahal	Downston		Test Conditions	Min	T	Max	Unit	
Symbol	Parameter	V_{DD}	Conditions	Min.	Тур.	Max.	Oill	
V _{DD}	Operating Voltage	_	f _{SYS} =4MHz	2.2	_	5.5	V	
טט •	Operating voltage	_	f _{SYS} =8MHz	3.3	_	5.5	V	
I _{DD1}	Operating Current – Crystal OSC	3V	No load, f _{sys} =4MHz	_	0.6	1.5	mA	
IDD1		5V	No load, ISYS-4WII IZ	_	2	4	mA	
ı	0 " 0 1 50 000		No load, f _{sys} =4MHz	_	0.8	1.5	mA	
I _{DD2}	Operating Current – RC OSC	5V	110 load, ISYS-4IVII IZ	_	2.5	4	mA	
I _{DD3}	Operating Current – Crystal OSC or RC OSC		No load, f _{SYS} =8MHz	_	4	8	mA	
	Standby Current –	3V	No load avetem HALT	_	_	5	μΑ	
I _{STB1}	WDT Clock Enabled*	5V	No load, system HALT	_	_	10	μΑ	
ı	Standby Current –	3V	No load ayatam HALT	_	_	1	μΑ	
I _{STB2}	WDT Clock Disabled*	5V	No load, system HALT	_	_	2	μΑ	
V _{IL1}	Input Low Voltage for I/O Ports		_	0		0.3V _{DD}	V	
V _{IH1}	Input High Voltage for I/O Ports	_	_	0.7V _{DD}	_	V _{DD}	V	
V _{IL2}	RES Input Low Voltage	_	_	0	_	0.4V _{DD}	V	



I/O Type MTP MCU with EEPROM

Ta=25°C

Cumb al	Parameter		Test Conditions	Min.	Turn	Max.	Unit
Symbol	Parameter	V _{DD}	Conditions	wiin.	Тур.	wax.	
V _{IH2}	RES Input High Voltage	_	_	$0.9V_{DD}$	_	V _{DD}	V
V _{LVR}	Low Voltage Reset	_	LVR enabled	2.7	3	3.3	V
Iol	I/O Port Sink Current	3V	V _{OL} =0.1V _{DD}	4	8	_	mA
I OL		5V	VOL-O.1 VDD	10	20	_	mA
IoH	I/O Port Source Current	3V	V _{OH} =0.9V _{DD}	-2	-4	_	mA
IOH	1/O Port Source Current	5V	VOH-0.9 VDD	-5	-10	_	mA
R _{PH}	Pull-high Resistance	3V		20	60	100	kΩ
IXPH		5V	_	10	30	50	kΩ

Note

HT48E50, HT48E70

Compleal	Parameter		Test Conditions	Min.	Tres	Max.	Unit
Symbol	Parameter	V_{DD}	Conditions	wiin.	Тур.	wax.	Unit
V _{DD}	0	_	f _{SYS} =4MHz	2.2	_	5.5	V
V DD	Operating Voltage	_	f _{SYS} =8MHz	3.3	_	5.5	V
	0	3V	No load, f _{sys} =4MHz	_	1	2	mA
I _{DD1}	Operating Current – Crystal OSC	5V	NO IOAU, ISYS-4IVITIZ	_	3	5	mA
	0ti0t	3V	No load, f _{sys} =4MHz	_	1	2	mA
I _{DD2}	Operating Current – RC OSC	5V	1NO IOAU, ISYS-4IVITIZ	_	2.5	4	mA
I _{DD3}	Operating Current – Crystal OSC or RC OSC	5V	No load, f _{SYS} =8MHz	_	4	8	mA
	Standby Current –	3V	No local acceptant HALT	_	_	5	μΑ
I _{STB1}	WDT Clock Enabled*	5V	No load, system HALT	_	_	10	μΑ
I _{STB2}	Standby Current –	3V	No load, system HALT	_	_	1	μΑ
ISTB2	WDT Clock Disabled*	5V	No load, system HALT	_	_	2	μΑ
V _{IL1}	Input Low Voltage for I/O Ports	_	_	0	_	0.3V _{DD}	V
V _{IH1}	Input High Voltage for I/O Ports	_	_	0.7V _{DD}	_	V _{DD}	V
V _{IL2}	RES Input Low Voltage	_	_	0	_	0.4V _{DD}	V
V _{IH2}	RES Input High Voltage	_	_	0.9V _{DD}	_	V _{DD}	V
V _{LVR}	Low Voltage Reset	_	LVR enabled	2.7	3	3.3	V
	I/O Port Sink Current	3V	V _{OI} = 0.1V _{DD}	4	8	_	mA
I _{OL}	I/O Port Sink Current	5V	V _{OL} -U.IV _{DD}	10	20	_	mA
Іон	I/O Port Source Current		V _{OH} =0.9V _{DD}	-2	-4	_	mA
IOH			VOH-O.3 V DD	-5	-10		mA
R _{PH}	Pull-high Resistance	3V		20	60	100	kΩ
I VPH	Full-High Resistance	5V	_	10	30	50	kΩ

Note

^{*} Tests conducted with I/O's setup as outputs at a low value, for all devices.

^{*} Tests conducted with I/O's setup as outputs at a low value, for all devices.



A.C. Characteristics

Ta=25°C

C	Downworton		Test Conditions	M:	T		1114
Symbol	Parameter	V _{DD}	Conditions	Min.	Тур.	Max.	Unit
f	System Clack Crystal OSC	_	2.2V~5.5V	400	_	4000	kHz
f _{SYS}	System Clock – Crystal OSC	_	3.3V~5.5V	400	_	8000	kHz
_	Timer I/P Frequency – TMR	_	2.2V~5.5V	0	_	4000	kHz
f _{TIMER}		_	3.3V~5.5V	0	_	8000	kHz
	Watchdog Oscillator Period	3V		45	90	180	μS
t _{WDTOSC}		5V	_	32	65	130	μS
	Watchdog Time-out Period –	3V	Mithaut MDT procedur	11	23	46	ms
t _{WDT1}	WDT Internal Clock Source	5V	Without WDT prescaler	8	17	33	ms
t _{WDT2}	Watchdog Time-out Period – Instruction Clock Source			_	1024	_	t _{SYS} *
t _{RES}	External Reset Low Pulse Width	_	_	1	_	_	μS
t _{SST}	System Start-up Timer Period	_	Wake-up from HALT	_	1024	_	t _{SYS} *
t _{LVR}	Low Voltage Reset Time	_	_	1	_	_	ms
t _{INT}	Interrupt Pulse Width	_	_	1		_	μS

 $t_{SYS} = 1/f_{SYS}$

EEPROM A.C. Characteristics

Cumbal	Davamatav	V _{cc} =5	V±10%	V _{cc} =2.2	2V±10%	Unit
Symbol	Parameter	Min.	Max.	Min.	Max.	Unit
f _{SK}	Clock Frequency	0	2	0	1	MHz
t _{SKH}	SK High Time	250	_	500	_	ns
t _{SKL}	SK Low Time	250	_	500	_	ns
t _{CSS}	CS Setup Time	50	_	100	_	ns
t _{CSH}	CS Hold Time	0	_	0	_	ns
t _{CDS}	CS Deselect Time	250	_	250	_	ns
t _{DIS}	DI Setup Time	100	_	200	_	ns
t _{DIH}	DI Hold Time	100	_	200	_	ns
t _{PD1}	DO Delay to "1"	_	250	_	500	ns
t _{PD0}	DO Delay to "0"	_	250	_	500	ns
t _{SV}	Status Valid Time	_	250	_	250	ns
t _{HZ}	DO Disable Time	100	_	200	_	ns
t _{PR1}	Write Cycle Time Per Word 1	_	2	_	5	ms
t _{PR2}	Write Cycle Time Per Word 2	_	10	_	10	ms



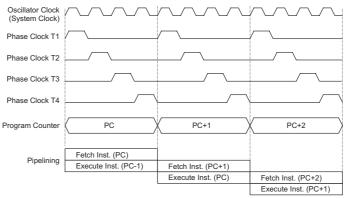
System Architecture

A key factor in the high-performance features of the Holtek range of I/O Type MTP microcontrollers with EEPROM is attributed to the internal system architecture. The range of devices take advantage of the usual features found within RISC microcontrollers providing increased speed of operation and enhanced performance. The pipelining scheme is implemented in such a way that instruction fetching and instruction execution are overlapped, hence instructions are effectively executed in one cycle, with the exception of branch or call instructions. An 8-bit wide ALU is used in practically all operations of the instruction set. It carries out arithmetic operations, logic operations, rotation, increment, decrement, branch decisions, etc. The internal data path is simplified by moving data through the Accumulator and the ALU. Certain internal registers are implemented in the Data Memory and can be directly or indirectly addressed. The simple addressing methods of these registers along with additional architectural features ensure that a minimum of external components is required to provide a functional I/O control system with maximum reliability and flexibility. This makes these devices suitable for low-cost, high-volume production for controller applications requiring from 1K up to 8K words of Program Memory and from 64 to 224 bytes of RAM data storage.

Clocking and Pipelining

The main system clock, derived from either a Crystal/Resonator or RC oscillator is subdivided into four internally generated non-overlapping clocks, T1~T4. The Program Counter is incremented at the beginning of the T1 clock during which time a new instruction is fetched. The remaining T2~T4 clocks carry out the decoding and execution functions. In this way, one T1~T4 clock cycle forms one instruction cycle. Although the fetching and execution of instructions takes place in consecutive instruction cycles, the pipelining structure of the microcontroller ensures that instructions are effectively executed in one instruction cycle. The exception to this are instructions where the contents of the Program Counter are changed, such as subroutine calls or jumps, in which case the instruction will take one more instruction cycle to execute.

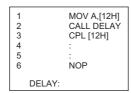
Note When the RC oscillator is used, OSC2 is freed for use as a T1 phase clock synchronizing pin. This T1 phase clock has a frequency of f_{SYS}/4 with a 1:3 high/low duty cycle.



System Clocking and Pipelining



For instructions involving branches, such as jump or call instructions, two machine cycles are required to complete instruction execution. An extra cycle is required as the program takes one cycle to first obtain the actual jump or call address and then another cycle to actually execute the branch. The requirement for this extra cycle should be taken into account by programmers in timing sensitive applications.



Fetch Inst. 1	Execute Inst. 1			
	Fetch Inst. 2	Execute Inst. 2		
		Fetch Inst. 3	Flush Pipeline	
			Fetch Inst. 6	Execute Inst. 6
				Fetch Inst. 7

Program Counter

During program execution, the Program Counter is used to keep track of the address of the next instruction to be executed. It is automatically incremented by one each time an instruction is executed except for instructions, such as "JMP" or "CALL" that demand a jump to a non-consecutive Program Memory address. For the I/O Type MTP MCU with EEPROM series of microcontrollers, note that the Program Counter width varies with the Program Memory capacity depending upon which device is selected. However, it must be noted that only the lower 8 bits, known as the Program Counter Low Register, are directly addressable by the user.

When executing instructions requiring jumps to non-consecutive addresses such as a jump instruction, a subroutine call, interrupt or reset, etc., the microcontroller manages program control by loading the required address into the Program Counter. For conditional skip instructions, once the condition has been met, the next instruction, which has already been fetched during the present instruction execution, is discarded and a dummy cycle takes its place while the correct instruction is obtained.

The lower byte of the Program Counter, known as the Program Counter Low Register or PCL, is available for program control and is a readable and writable register. By transferring data directly into this register, a short program jump can be executed directly, however, as only this low byte is available for manipulation, the jumps are limited to the present page of memory, that is 256 locations. When such program jumps are executed it should also be noted that a dummy cycle will be inserted.

Note

The lower byte of the Program Counter is fully accessible under program control. The use of the PCL might cause program branching, so an extra cycle is needed to pre-fetch. Further information on the PCL register can be found in the Special Function Register section.



I/O Type MTP MCU with EEPROM

Mode	Program Counter Bits												
Wode	b12	b11	b10	b9	b8	b7	b6	b5	b4	b3	b2	b1	b0
Initial Reset	0	0	0	0	0	0	0	0	0	0	0	0	0
External Interrupt	0	0	0	0	0	0	0	0	0	0	1	0	0
Timer/Event Counter 0 Overflow	0	0	0	0	0	0	0	0	0	1	0	0	0
Timer/Event Counter 1 Overflow	0	0	0	0	0	0	0	0	0	1	1	0	0
Skip					F	rograr	n Cou	nter +	2	•			
Loading PCL	PC12	PC11	PC10	PC9	PC8	@7	@6	@5	@4	@3	@2	@1	@0
Jump, Call Branch	#12	#11	#10	#9	#8	#7	#6	#5	#4	#3	#2	#1	#0
Return from Subroutine	S12	S11	S10	S9	S8	S7	S6	S5	S4	S3	S2	S1	S0

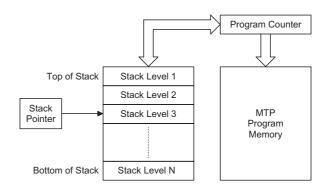
- Note 1. PC12~PC8: Current Program Counter bits.
 - 2. @7~@0: PCL bits.
 - 3. #12~#0: Instruction code address bits.
 - 4. S12~S0: Stack register bits.
 - 5. For the HT48E70, the Program Counter is 13 bits wide, i.e. from b12~b0.
 - 6. For the HT48E50, since their Program Counter is 12 bits wide, the b12 column in the table is not applicable.
 - 7. For the HT48E30, since their Program Counter is 11 bits wide, the b11 and b12 columns in the table are not applicable.
 - 8. For the HT48E10 and the HT48E06, since their Program Counter is 10 bits wide, the b10, b11, and b12 columns in the table are not applicable.
 - 9. The Timer/Event Counter 1 overflow row is available only for the HT48E50 and the HT48E70.

Stack

This is a special part of the memory which is used to save the contents of the Program Counter only. The stack can have 2, 4, 6 or 16 levels depending upon which device is selected and is neither part of the data nor part of the program space, and is neither readable nor writable. The activated level is indexed by the Stack Pointer (SP) and is neither readable nor writable. At a subroutine call or interrupt acknowledge signal, the contents of the Program Counter are pushed onto the stack. At the end of a subroutine or an interrupt routine, signaled by a return instruction (RET or RETI), the Program Counter is restored to its previous value from the stack. After a device reset, the Stack Pointer will point to the top of the stack.

If the stack is full and an enabled interrupt takes place, the interrupt request flag will be recorded but the acknowledge signal will be inhibited. When the Stack Pointer is decremented (by RET or RETI), the interrupt will be serviced. This feature prevents stack overflow allowing the programmer to use the structure more easily. However, when the stack is full, a "CALL subroutine" instruction can still be executed which will result in a stack overflow. Precautions should be taken to avoid such cases which might cause unpredictable program branching.





Note

- 1. For the HT48E06, N=2, i.e. 2 levels of stack available.
- 2. For the HT48E10 and HT48E30, N=4, i.e. 4 levels of stack available.
- 3. For the HT48E50, N=6, i.e. 6 levels of stack available.
- 4. For the HT48E70, N=16, i.e. 16 levels of stack available.

Arithmetic and Logic Unit - ALU

The arithmetic-logic unit or ALU is a critical area of the microcontroller that carries out arithmetic and logic operations of the instruction set. Connected to the main microcontroller data bus, the ALU receives related instruction codes and performs the required arithmetic or logical operations after which the result will be placed in the specified register. As these ALU calculation or operations may result in carry, borrow or other status changes, the status register will be correspondingly updated to reflect these changes. The ALU supports the following functions:

- Arithmetic operations ADD, ADDM, ADC, ADCM, SUB, SUBM, SBC, SBCM, DAA
- Logic operations AND, OR, XOR, ANDM, ORM, XORM, CPL, CPLA
- Rotation RRA, RR, RRCA, RRC, RLA, RL, RLCA, RLC
- Increment and Decrement INCA, INC, DECA, DEC
- Branch decision JMP, SZ, SZA, SNZ, SIZ, SDZ, SIZA, SDZA, CALL, RET, RETI

MTP Program Memory

The Program Memory is the location where the user code or program is stored. For this series of devices the Program Memory is an MTP type, which means it can be programmed and reprogrammed a large number of times, allowing the user the convenience of code modification using the same device. By using the appropriate programming tools, these MTP devices offer users the flexibility to conveniently debug and develop their applications while also offering a means of field programming.

Organization

The Program Memory has a capacity of 1K by 14, 2K by 14, 4K by 15 or 8K by 16 bits depending upon which device is selected. The Program Memory is addressed by the Program Counter and also contains data, table information and interrupt entries. Table data, which can be setup in any location within the Program Memory, is addressed by a separate table pointer register.



The following diagram shows the Program Memory for the I/O Type MTP MCU with EEPROM series.

	HT48E06 HT48E10	HT48E30	HT48E50	HT48E70	
000H	Initialization Vector	Initialization Vector	Initialization Vector	Initialization Vector	
004H	External Interrupt Vector	External Interrupt Vector	External Interrupt Vector	External Interrupt Vector	
H800	Timer/Counter Interrupt Vector	Timer/Counter Interrupt Vector	Timer/Counter 0 Interrupt Vector	Timer/Counter 0 Interrupt Vector	
00CH			Timer/Counter 1 Interrupt Vector	Timer/Counter 1 Interrupt Vector	
010H					
014H					
018H					
3FFH	⊱ ≈	*	ř ř	ř	¥
400H					
7FFH	¥	⊱	¥	ř	¥
800H					
FFFH	\	⋡	k	∤	¥
1000H					
1FFFH	¥ ~	¥		į	Not Implemented
	14 bits/	14 bits ——/	15 bits ——/	16 bits ——/	

Special Vectors

Within the Program Memory, certain locations are reserved for special usage such as reset and interrupts.

Location 000H

This vector is reserved for use by the device reset for program initialization. After a device reset is initiated, the program will jump to this location and begin execution.

Location 004H

This vector is used by the external interrupt. If the external interrupt pin on the device receives a high to low transition, the program will jump to this location and begin execution if the external interrupt is enabled and the stack is not full.

• Location 008H

This internal vector is used by the Timer/Event Counter. If a counter overflow occurs, the program will jump to this location and begin execution if the timer interrupt is enabled and the stack is not full. For the HT48E50 and HT48E70 devices, which have dual timers, this timer is known as Timer/Event Counter 0.

Location 00CH

This internal vector is used by the Timer/Event Counter. If a counter overflow occurs, the program will jump to this location and begin execution if the timer interrupt is enabled and the stack is not full. This vector is available for the HT48E50 and HT48E70 only. The Timer/Event Counter is known as Timer/Event Counter 1. Note that the HT48E06, HT48E10 and HT48E30 devices have only one timer, therefore, this interrupt vector is not used.



Look-up Table

Any location within the Program Memory can be defined as a look-up table where programmers can store fixed data. To use the look-up table, the table pointer must first be setup by placing the lower order address of the look up data to be retrieved in the table pointer register, TBLP. This register defines the lower 8-bit address of the look-up table.

After setting up the table pointer, the table data can be retrieved from the current Program Memory page or last Program Memory page using the "TABRDC[m]" or "TABRDL [m]" instructions, respectively. When these instructions are executed, the lower order table byte from the Program Memory will be transferred to the user defined Data Memory register [m] as specified in the instruction. The higher order table data byte from the Program Memory will be transferred to the TBLH special register. Any unused bits in this transferred higher order byte will have uncertain values.

The following diagram illustrates the addressing/data flow of the look-up table:

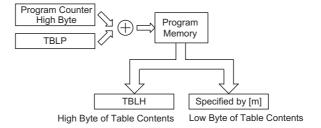


Table Program Example

The following example shows how the table pointer and table data is defined and retrieved from the HT48E10 I/O Type MTP microcontroller with EEPROM. This example uses raw table data located in the last page which is stored there using the ORG statement. The value at this ORG statement is "300H" which refers to the start address of the last page within the 1K Program Memory of the HT48E10 microcontroller. The table pointer is setup here to have an initial value of "06H". This will ensure that the first data read from the data table will be at the Program Memory address "306H" or 6 locations after the start of the last page. Note that the value for the table pointer is referenced to the first address of the present page if the "TABRDC [m]" instruction is being used. The high byte of the table data which in this case is equal to zero will be transferred to the TBLH register automatically when the "TABRDL [m]" instruction is executed.



```
db ?
db ?
                      ; temporary register #1
; temporary register #2
tempreg1
tempreg2
mov
        a,06h
                      ; initialize table pointer - note that this address is
                      : referenced
                      ; to the last page or present page
mov
        tblp,a
tabrdl
        tempreg1
                      ; transfers value in table referenced by table pointer
                      ; to tempregl
                      ; data at prog. memory address "306H" transferred to ; tempreg1 and TBLH \,
dec
        tblp
                      ; reduce value of table pointer by one
tabrdl tempreg2
                      ; transfers value in table referenced by table pointer
                        to tempreg2
                      ; data at prog. memory address "305H" transferred to ; tempreg2 and TBLH
                      ; in this example the data "1AH" is transferred to
                      ; tempreg1 and data "OFH" to register tempreg2
org 300h
                      ; sets initial address of last page (for HT48E10)
    00Ah, 00Bh, 00Ch, 00Dh, 00Eh, 00Fh, 01Ah, 01Bh
```

Because the TBLH register is a read-only register and cannot be restored, care should be taken to ensure its protection if both the main routine and Interrupt Service Routine use the table read instructions. If using the table read instructions, the Interrupt Service Routines may change the value of the TBLH and subsequently cause errors if used again by the main routine. As a rule it is recommended that simultaneous use of the table read instructions should be avoided. However, in situations where simultaneous use cannot be avoided, the interrupts should be disabled prior to the execution of any main routine table-read instructions. Note that all table related instructions require two instruction cycles to complete their operation.

Instruction		Table Location Bits											
Instruction	b12	b11	b10	b9	b8	b7	b6	b5	b4	b3	b2	b1	b0
TABRDC [m]	PC12	PC11	PC10	PC9	PC8	@7	@6	@5	@4	@3	@2	@1	@0
TABRDL [m]	1	1	1	1	1	@7	@6	@5	@4	@3	@2	@1	@0

Note

- 1. PC12~PC8: Current Program Counter bits.
- 2. @7~@0: Table Pointer TBLP bits.
- 3. For the HT48E70, the Table address location is 13 bits, i.e. from b12~b0.
- 4. For the HT48E50, the Table address location is 12 bits, i.e. from b11~b0.
- 5. For the HT48E30, the Table address location is 11 bits, i.e. from b10~b0.
- 6. For the HT48E10 and the HT48E06, the Table address location is 10 bits, i.e. from b9~b0.

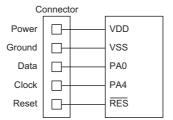


In Circuit Programming

The provision of multi-programmable Program Memory gives the user and designer the convenience of easy upgrades and modifications to their programs on the same device. As an additional convenience, Holtek has provided a means of programming the microcontroller in-circuit. This provides manufacturers with the possibility of manufacturing their circuit boards complete with a programmed or un-programmed MTP Type microcontroller, and then programming or upgrading the program at a later stage. This enables product manufacturers to easily keep their manufactured products supplied with the latest program releases without removal and re-insertion of the device.

Pin Name	Function
PA0	Serial data input/output
PA4	Serial clock
RES	Device reset
VDD	Power supply
VSS	Ground

The MTP device Program Memory and EEPROM memory can both be programmed serially in-circuit using a 5-wire interface. Data is downloaded and uploaded serially on a single pin with an additional line for the clock. Two additional lines are required for the power supply and one line for the reset. The technical details regarding the in-circuit programming of the devices are beyond the scope of this handbook and will be supplied in supplementary literature.



In-circuit Programming Interface

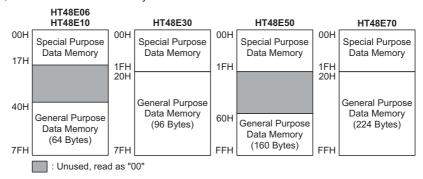


RAM Data Memory

The RAM Data Memory is a volatile area of 8-bit wide RAM internal memory and is the location where temporary information is stored. Divided into two sections, the first of these is an area of RAM where special function registers are located. These registers have fixed locations and are necessary for correct operation of the device. Many of these registers can be read from and written to directly under program control, however, some remain protected from user manipulation. The second area of RAM Data Memory is reserved for general purpose use. All locations within this area are read and write accessible under program control.

Organization

The RAM Data Memory is subdivided into two banks, known as Bank 0 and Bank 1, all of which are implemented in 8-bit wide RAM. Most of the RAM Data Memory is located in Bank 0 which is also subdivided into two sections, the Special Purpose Data Memory and the General Purpose Data Memory. The length of these sections is dictated by the type of microcontroller chosen. The start address of the RAM Data Memory for all devices is the address "00H". The last Data Memory address is "7FH" for the HT48E06, HT48E10 and HT48E30 devices, and "FFH" for the HT48E50 and HT48E70 devices. Registers which are common to all microcontrollers, such as ACC, PCL, etc., have the same Data Memory address.



Bank 0 RAM Data Memory Structure

Bank 1 of the RAM Data Memory contains only one special function register, known as the EECR register which is located at address "40H" for all devices.

40H EECR

Bank 1 RAM Data Memory Structure

Note

Most of the RAM Data Memory bits can be directly manipulated using the "SET [m].i" and "CLR [m].i" with the exception of a few dedicated bits. The RAM Data Memory can also be accessed through the Memory Pointer registers MP0 and MP1.



General Purpose Data Memory

All microcontroller programs require an area of read/write memory where temporary data can be stored and retrieved for use later. It is this area of RAM memory that is known as General Purpose Data Memory. This area of Data Memory is fully accessible by the user program for both read and write operations. By using the "SET [m].i" and "CLR [m].i" instructions individual bits can be set or reset under program control giving the user a large range of flexibility for bit manipulation in the Data Memory.

Special Purpose Data Memory

This area of Data Memory, is located in Bank 0, where registers, necessary for the correct operation of the microcontroller, are stored. Most of the registers are both readable and writable but some are protected and are readable only, the details of which are located under the relevant Special Function Register section. Note that for locations that are unused, any read instruction to these addresses will return the value "00H". Although the Special Purpose Data Memory registers are located in Bank 0, they will still be accessible even if Bank Pointer 1 is selected.

The following diagram shows a detailed Special Purpose Data Memory organization map of the I/O Type MTP microcontrollers with EEPROM:

	HT48E06 HT48E10	HT48E	30	HT48E50		HT48E70	
00H	IAR0	IARO		IAR0]	IAR0	
01H	MP0	MPC		MP0		MP0	
02H	IAR1	IAR1		IAR1		IAR1	
03H	MP1	MP1		MP1		MP1	
04H	BP	BP		BP		BP	
05H	ACC	ACC		ACC		ACC	
06H	PCL	PCL		PCL		PCL	
07H	TBLP	TBLF	•	TBLP		TBLP	
08H	TBLH	TBL	1	TBLH		TBLH	
09H	WDTS	WDT	3	WDTS		WDTS	
0AH	STATUS	STATI	JS	STATUS		STATUS	
0BH	INTC	INTO	;	INTC		INTC	
0CH						TMR0H	
0DH	TMR	TMF		TMR0		TMR0L	
0EH	TMRC	TMR		TMR0C		TMR0C	
0FH				TMR1H		TMR1H	
10H				TMR1L		TMR1L	
11H				TMR1C		TMR1C	
12H	PA	PA		PA		PA	
13H	PAC	PAC		PAC		PAC	
14H	PB	PB		PB		PB	
15H	PBC	PBC		PBC		PBC	
16H	PC	PC		PC		PC	
17H	PCC	PCC		PCC		PCC	
18H				PD		PD	
19H				PDC		PDC	
1AH						PE	
1BH						PEC	
1CH						PF	
1DH						PFC	
1EH		PG		PG		PG	
1FH		PGC		PGC		PGC	Unused, read as "00"



Special Function Registers

To ensure successful operation of the microcontroller, certain internal registers are implemented in the RAM Data Memory area. These registers ensure correct operation of internal functions such as timers, interrupts, watchdog, etc., as well as external functions such as I/O data control. The location of these registers within the RAM Data Memory begins at the address "00H". Any unused Data Memory locations between these special function registers and the point where the General Purpose Memory begins is reserved for future expansion purposes, attempting to read data from these locations will return a value of "00H".

Indirect Addressing Registers – IAR0, IAR1

The Indirect Addressing Registers, IAR0 and IAR1, although having their locations in normal RAM register space, do not actually physically exist as normal registers. The method of indirect addressing for RAM data manipulation uses these Indirect Addressing Registers and Memory Pointers, in contrast to direct memory addressing, where the actual memory address is specified. Actions on the IAR0 and IAR1 registers will result in no actual read or write operation to these registers but rather to the memory location specified by their corresponding Memory Pointer, MP0 or MP1. Acting as a pair, IAR0 and MP0 can together only access data from Bank 0, while the IAR1 and MP1 register pair can access data from both Bank 0 and Bank 1. As the Indirect Addressing Registers are not physically implemented, reading the Indirect Addressing Registers indirectly will return a result of "00H" and writing to the registers indirectly will result in no operation.

Memory Pointers - MP0, MP1

For all devices, two Memory Pointers, known as MP0 and MP1 are provided. These Memory Pointers are physically implemented in the Data Memory and can be manipulated in the same way as normal registers providing a convenient way with which to address and track data. When any operation to the relevant Indirect Addressing Registers is carried out, the actual address that the microcontroller is directed to, is the address specified by the related Memory Pointer. MP0, together with Indirect Addressing Register, IAR0, are used to access data from Bank 0 only, while MP1 and IAR1 are used to access data from both Bank 0 and Bank 1. For the HT48E06, HT48E10 and HT48E30 devices, which have smaller RAM Data Memory capacities, bit 7 of the Memory Pointers is not required to address the full memory space. It must be noted that when the Memory Pointers for these devices are read, a value of "1" will be returned.

The following example shows how to clear a section of four RAM locations already defined as locations adres1 to adres4.

Chapter 1 Hardware Structure

continue:

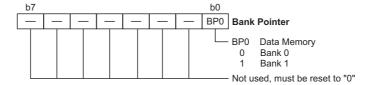
The important point to note here is that in the example shown above, no reference is made to specific RAM addresses.

Bank Pointer - BP

The RAM Data Memory is divided into two Banks, known as Bank 0 and Bank 1. With the exception of the EECR register, all of the Special Purpose Registers and General Purpose Registers are contained in Bank 0. Bank 1 contains only one register, which is the EEPROM Control Register, known as EECR. Selecting the required Data Memory area is achieved using the Bank Pointer. If data in Bank 0 is to be accessed, then the BP register must be loaded with the value "00", while if data in Bank 1 is to be accessed, then the BP register must be loaded with the value "01".

Using Memory Pointer MP0 and Indirect Addressing Register IAR0 will always access data from Bank 0, irrespective of the value of the Bank Pointer. The EECR register is located at memory location 40H in Bank 1 and can only be accessed indirectly using memory pointer MP1 and the indirect addressing register, IAR1, after the BP register has first been loaded with the value "01". Data can only be read from or written to the EEPROM via this register.

The Data Memory is initialised to Bank 0 after a reset, except for the WDT time-out reset in the Power Down Mode, in which case, the Data Memory bank remains unaffected. It should be noted that Special Function Data Memory is not affected by the bank selection, which means that the Special Function Registers can be accessed from within either Bank 0 or Bank 1. Directly addressing the Data Memory will always result in Bank 0 being accessed irrespective of the value of the Bank Pointer.



Accumulator – ACC

The Accumulator is central to the operation of any microcontroller and is closely related with operations carried out by the ALU. The Accumulator is the place where all intermediate results from the ALU are stored. Without the Accumulator it would be necessary to write the result of each calculation or logical operation, such as addition, subtraction, shift, etc., to the Data Memory resulting in higher programming and timing overheads. Data transfer operations usually involve the temporary storage function of the Accumulator; for example, when transferring data between one user defined register and another, it is necessary to do this by passing the data through the Accumulator as no direct transfer between two registers is permitted.



Program Counter Low Register - PCL

To provide additional program control functions, the low byte of the Program Counter is made accessible to programmers by locating it within the Special Purpose area of the Data Memory. By manipulating this register, direct jumps to other program locations are easily implemented. Loading a value directly into this PCL register will cause a jump to the specified Program Memory location, however, as the register is only 8-bit wide, only jumps within the current Program Memory page are permitted. When such operations are used, note that a dummy cycle will be inserted.

Look-up Table Registers - TBLP, TBLH

These two special function registers are used to control operation of the look-up table which is stored in the Program Memory. TBLP is the table low byte pointer and indicates the location where the table data is located. Its value must be setup before any table read commands are executed. Its value can be changed, for example using the "INC" or "DEC" instructions, allowing for easy table data pointing and reading. TBLH is the location where the high order byte of the table data is stored after a table read data instruction has been executed. Note that the lower order table data byte is transferred to a user defined location.

Watchdog Timer Register - WDTS

The Watchdog feature of the microcontroller provides an automatic reset function giving the microcontroller a means of protection against spurious jumps to incorrect Program Memory addresses. To implement this, a timer is provided within the microcontroller which will issue a reset command when its value overflows. To provide variable Watchdog Timer reset times, the Watchdog Timer clock source can be divided by various division ratios, the value of which is set using the WDTS register. By writing directly to this register, the appropriate division ratio for the Watchdog Timer clock source can be setup. Note that only the lower 3 bits are used to set division ratios between 1 and 128.

Status Register - STATUS

This 8-bit register contains the zero flag (Z), carry flag (C), auxiliary carry flag (AC), overflow flag (OV), power down flag (PDF), and watchdog time-out flag (TO). These arithmetic/logical operation and system management flags are used to record the status and operation of the microcontroller.

With the exception of the TO and PDF flags, bits in the status register can be altered by instructions like most other registers. Any data written into the status register will not change the TO or PDF flag. In addition, operations related to the status register may give different results due to the different instruction operations. The TO flag can be affected only by a system power-up, a WDT time-out or by executing the "CLR WDT" or "HALT" instruction. The PDF flag is affected only by executing the "HALT" or "CLR WDT" instruction or during a system power-up.

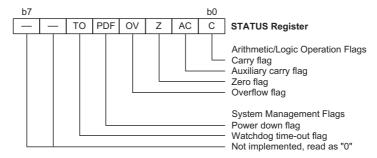
The Z, OV, AC and C flags generally reflect the status of the latest operations.

- C is set if an operation results in a carry during an addition operation or if a borrow does not take place during a subtraction operation; otherwise C is cleared. C is also affected by a rotate through carry instruction.
- AC is set if an operation results in a carry out of the low nibbles in addition, or no borrow from the high nibble into the low nibble in subtraction; otherwise AC is cleared.



- Z is set if the result of an arithmetic or logical operation is zero; otherwise Z is cleared.
- OV is set if an operation results in a carry into the highest-order bit but not a carry out of the highest-order bit, or vice versa; otherwise OV is cleared.
- PDF is cleared by a system power-up or executing the "CLR WDT" instruction. PDF is set by executing the "HALT" instruction.
- TO is cleared by a system power-up or executing the "CLR WDT" or "HALT" instruction. TO is set by a WDT time-out.

In addition, on entering an interrupt sequence or executing a subroutine call, the status register will not be pushed onto the stack automatically. If the contents of the status registers are important and if the subroutine can corrupt the status register, precautions must be taken to correctly save it.



Interrupt Control Register – INTC

This 8-bit register, known as the INTC register, controls the operation of both external and internal timer interrupts. By setting various bits within this register using standard bit manipulation instructions, the enable/disable function of the external interrupt and each of the internal timer interrupts can be independently controlled. A master interrupt bit within this register, the EMI bit, acts like a global enable/disable and is used to set all of the interrupt enable bits on or off. This bit is cleared when an interrupt routine is entered to disable further interrupt and is set by executing the "RETI" instruction.

Note

In situations where other interrupts may require servicing within present interrupt service routines, the EMI bit can be manually set by the program after the present interrupt service routine has been entered.

Timer/Event Counter Registers

Depending upon which device is selected, all devices contain one or two integrated Timer/Event Counters of either 8-bit or 16-bit size. For the HT48E06, HT48E10 and HT48E30 devices, which have a single 8-bit Timer/Event Counter, an associated register known as TMR is the location where the timer's 8-bit value is located. An associated control register, known as TMRC, contains the setup information for this timer. The HT48E50 devices contain a single 8-bit Timer/Event Counter with an associated register, known as TMR0, and a single 16-bit Timer/Event Counter with an associated register pairs, known as TMR1L/TMR1H, where the timer's values are located. Two associated control registers, known as TMR0C and TMR1C contain the setup information for these two timers. The HT48E70 devices contain two 16-bit Timer/Event Counters with two associated



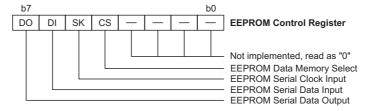
register pairs, known as TMR0L/TMR0H and TMR1L/TMR1H, where the timer's 16-bit values are located. Two associated control registers, known as TMR0C and TMR1C contain the setup information for these two timers.

Input/Output Ports and Control Registers

Within the area of Special Function Registers, the I/O registers and their associated control registers play a prominent role. All I/O ports have a designated register correspondingly labeled as PA, PB, PC, etc. These labeled I/O registers are mapped to specific addresses within the Data Memory as shown in the Data Memory table, which are used to transfer the appropriate output or input data on that port. with each I/O port there is an associated control register labeled PAC, PBC, PCC, etc., also mapped to specific addresses with the Data Memory. The control register specifies which pins of that port are set as inputs and which are set as outputs. To setup a pin as an input, the corresponding bit of the control register must be set high, for an output it must be set low. During program initialization, it is important to first setup the control registers to specify which pins are outputs and which are inputs before reading data from or writing data to the I/O ports. One flexible feature of these registers is the ability to directly program single bits using the "SET [m].i" and "CLR [m].i" instructions. The ability to change I/O pins from output to input and vice versa by manipulating specific bits of the I/O control registers during normal program operation is a useful feature of these devices.

EEPROM Control Register – EECR

This register is used to control all operations to and from the EEPROM Data Memory. As the EEPROM Data Memory is not mapped like the other memory types, all data to and from the EEPROM must be made through this register. The EECR register is located in Bank 1 of the Data Memory, so before use the Bank Pointer must be setup to a value of "1". The EECR register can only be read and written to indirectly using the MP1 address pointer.



EEPROM Data Memory

One of the special features within all the devices in the MTP series of microcontrollers is their internal EEPROM Data Memory. EEPROM, which stands for Electrically Erasable Programmable Read Only Memory, is by its nature a non-volatile form of memory, with data retention even when its power supply is removed. By incorporating this kind of data memory in all of its MTP range, a whole new host of application possibilities are made available to the designer. The availability of EEPROM storage allows information such as product identification numbers, calibration values, specific user data, system setup data or other product information to be stored directly within the product microcontroller.



EEPROM Data Memory Structure

Dependent upon which device is chosen, the EEPROM Data Memory capacity is either 128×8 bits or 256×8 bits. Unlike the Program Memory and RAM Data Memory, the EEPROM Data Memory is not directly mapped and is therefore not directly accessible in same way as the other types of memory. Instead it has to be accessed indirectly through the EEPROM Control Register.

Device	EEPROM Memory Capacity
HT48E06	128×8
HT48E10	128×8
HT48E30	128×8
HT48E50	256×8
HT48E70	256×8

EEPROM Data Memory Capacity

Accessing the EEPROM Data Memory

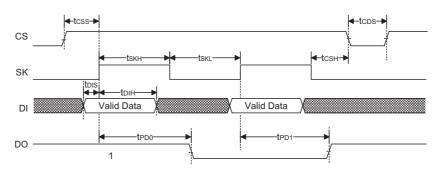
The EEPROM Data Memory is accessed using a set of seven instructions. These instructions control all functions of the EEPROM such as read, write, erase, enable etc. The internal EEPROM structure is similar to that of a standard 3-wire EEPROM, for which four pins are used for transfer of instruction, address and data information. These are the Chip Select pin, CS, Serial Clock pin, SK, Data In pin, DI and the Data Out pin, DO. All actions related to the EEPROM must be conducted through the EECR register which is located in Bank 1 of the RAM Data Memory, in which each of these four EEPROM pins is represented by a bit in the EECR register. By manipulating these four bits in the EECR register, in accordance with the accompanying timing diagrams, the microcontroller can communicate with the EEPROM and carry out the required functions, such as reading and writing data.

Bit No.	Label	EEPROM Function
0~3	_	Not implemented bit, read as "0"
4	CS	EEPROM Data Memory select
5	SK	Serial Clock: Used to clock data into and out of the EEPROM
6	DI	Data Input: Instructions, address and data information are written to the EEPROM on this pin
7	DO	Data Output: Data from the EEPROM is readout with this bit. Will be in a high-impedance condition if no data is being read.

EECR Register EEPROM Control Bit Functions

When reading data from the EEPROM, the data will clocked out on the rising edge of SK and appear on DO. The DO pin will normally be in a high-impedance condition unless a READ statement is being executed. When writing to the EEPROM the data must be presented first on DI and then clocked in on the rising edge of SK. After all the instruction, address and data information has been transmitted, CS should be cleared to "0" to terminate the instruction transmission. Note that after power on the EEPROM must be initialised as described.

As indirect addressing is the only way to access the EECR register, all read and write operations to this register must take place using the Indirect Addressing Register, IAR1, and the Memory Pointer, MP1. Because the EECR control register is located in Bank 1 of the RAM Data Memory at location 40H, the MP1 Memory Pointer must first be set to the value 40H and the Bank Pointer set to "1".



Clocking Data in and Out of the EEPROM

EEPROM Data Memory Instruction Set

Control over the internal EEPROM, to execute functions such as read, write, disable, enable etc, is implemented through instructions of which there are a total of seven. The related instruction is transmitted to the EEPROM via the DI bit, after CS has first been set to "1" to enable the EEPROM and a start bit "1" has been transmitted. For the READ, WRITE and ERASE instructions, each of the three instructions has its own two bit related instruction code. The address should then be transmitted, which in the case of devices with a 128×8 capacity EEPROM is 7-bits. For devices with a 256×8 capacity EEPROM, a 9-bit address is transmitted, however the first bit is a dummy bit and can have any value. The address is transmitted in MSB first format.

For the other four instructions, "EWEN", "EWDS", "ERAL" and "WRAL", after the start bit has been transmitted a "00" instruction code should then follow. The address information should then follow which is 7-bits long for devices with a 128×8 capacity EEPROM, and 9-bits long for devices with a 256×8 capacity EEPROM. The first two bits of this address is instruction dependant as shown in the table while the remaining bits have don't care values and can be either high or low.

After any write or erase instruction is issued, the internal write function of the EEPROM will be used to write the data into the device. As this internal write operation uses the EEPROM's own internal clock, no further instructions will be accepted by the EEPROM until the internal write function has ended. After power on and before any instruction is issued the EEPROM must be properly initialised to ensure proper operation.

Instruction	Function	Start Bit	Instruction Code	Address	Data
READ	Read Out Data Byte(s)	1	10	A6~A0	D7~D0
ERASE	Erase Single Data Byte	1	11	A6~A0	_
WRITE	Write Single Data Byte	1	01	A6~A0	D7~D0
EWEN	Erase/Write Enable	1	00	11 XXXXX	_
EWDS	Erase/Write Disable	1	00	00 XXXXX	_
ERAL	Erase All	1	00	10 XXXXX	_
WRAL	Write All	1	00	01 XXXXX	_

Instruction Set Summary - HT48E06, HT48E10 and HT48E30

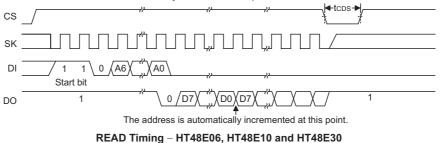


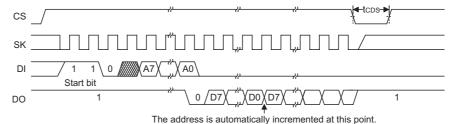
Instruction	Function	Start Bit	Instruction Code	Address	Data
READ	Read Out Data Byte(s)	1	10	X, A7~A0	D7~D0
ERASE	Erase Single Data Byte	1	11	X, A7~A0	_
WRITE	Write Single Data Byte	1	01	X, A7~A0	D7~D0
EWEN	Erase/Write Enable	1	00	11 XXXXXXX	_
EWDS	Erase/Write Disable	1	00	00 XXXXXXX	_
ERAL	Erase All	1	00	10 XXXXXXX	_
WRAL	Write All	1	00	01 XXXXXXX	_

Instruction Set Summary - HT48E50 and HT48E70

READ

The "READ" instruction is used to read out one or more bytes of data from the EEPROM Data Memory. To instigate a "READ" instruction, the CS bit should be set high, followed by a high start bit and then the instruction code "10", all transmitted via the DI bit. The address information should then follow with the MSB being transmitted first. For the HT48E50 and HT48E70 devices, a dummy bit must be inserted between the last bit of the instruction code and the MSB of the address. After the last address bit, A0, has been transmitted, the data can be clocked out, bit D7 first, on the rising edge of the SK clock signal and can be read via the D0 bit. However, a dummy "0" bit will first precede the reading of the first data bit, D7. After the full byte has been read out, the internal address will be automatically incremented allowing the next consecutive data byte to be read out without entering further address data. As long as the CS bit remains high, data bit D7 of the next address will automatically follow data bit D0 of the previous address with no dummy "0" being inserted between them. The address will keep incrementing in this way until CS returns to a low value. D0 will normally be in a high impedance condition until the "READ" instruction is executed. Note that as the "READ" instruction is not affected by the condition of the "EWEN" or "EWDS" instruction, the READ command is always valid and independent of these two instructions.



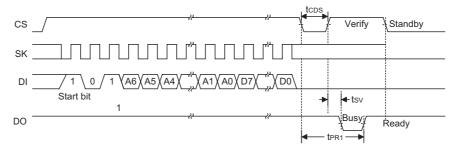


READ Timing - HT48E50 and HT48E70

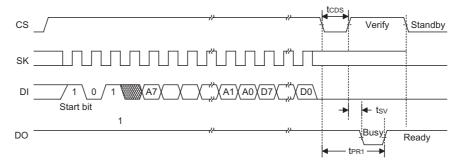


WRITE

The "WRITE" instruction is used to write a single byte of data into the EEPROM. To instigate a WRITE instruction, the CS bit should be set high, followed by a high start bit and then the instruction code "01". all transmitted via the DI bit. The address information should then follow with the MSB bit being transmitted first. After the last address bit, A0, has been transmitted, the data can be immediately transmitted MSB first. For the HT48E50 and HT48E70 devices, a dummy bit must be inserted between the last bit of the instruction code and the MSB of the address. After all the WRITE instruction code, address and data have been transmitted, the data will be written into the EEPROM when the CS bit is cleared to zero. The EEPROM does this by executing an internal write-cycle, which will first erase and then write the previously transmitted data byte into the EEPROM. This process takes place internally using the EEPROM's own internal clock and does not require any action from the SK clock. No further instructions can be accepted by the EEPROM until this internal write-cycle has finished. To determine when the write cycle has ended, CS should be again brought high and the DO bit polled. If DO is low this indicates that the internal write-cycle is still in progress, however, the DO bit will change to a high value when the internal write-cycle has ended. Before a "WRITE" instruction is transmitted an "EWEN" instruction must have been transmitted at some point earlier to ensure that the erase/write function of the EEPROM is enabled.



WRITE Timing - HT48E06, HT48E10 and HT48E30

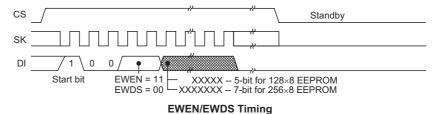


WRITE Timing - HT48E50 and HT48E70



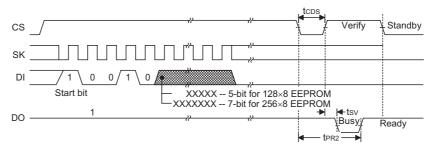
EWEN/EWDS

The "EWEN" instruction is the Erase/Write Enable instruction and the "EWDS" instruction is the Erase/Write Disable instruction. To instigate an "EWEN" or "EWDS" instruction, the CS bit should first be set high, followed by a high start bit and then the instruction code "00". For the "EWEN" instruction, a "11" should then be transmitted and for the "EWDS" instruction a "00" should be transmitted. Following on from this, and depending on whether the internal EEPROM has a 128×8 or 256×8 capacity, either 5-bits or 7-bits respectively, of "don't-care" data should then be transmitted to complete the instruction. If the device is already in the Erase Write Disable mode then no write or erase operations can be executed thus protecting the internal EEPROM data. Before any write or erase instruction is executed an "EWEN" instruction must be issued. After the "EWEN" instruction is executed, the device will remain in the Erase Write Enable mode until a subsequent "EWDS" instruction is issued or until the device is powered down.



ERAL

The "ERAL" instruction is used to erase the whole contents of the EEPROM memory. After it has been executed all the data in the EEPROM will be set to "1". To instigate this instruction, the CS bit should be set high, followed by a high start bit and then the instruction code "00". Following on from this, a "10" should then be transmitted, and depending on whether the internal EEPROM has a 128×8 or 256×8 capacity, this should be followed by either 5-bits or 7-bits respectively, of "don't-care" data to complete the instruction. After the "ERAL" instruction code has been transmitted, the EEPROM data will be erased when the CS bit is cleared to zero. The EEPROM does this by executing an internal write-cycle. This process takes place internally using the EEPROM's own internal clock and does not require any action from the SK clock. No further instructions can be accepted by the EEPROM until this internal write-cycle has finished. To determine when the write cycle has ended, CS should be again brought high and the DO bit polled. If D0 is low this indicates that the internal write-cycle is still in progress, however the D0 bit will change to a high value when



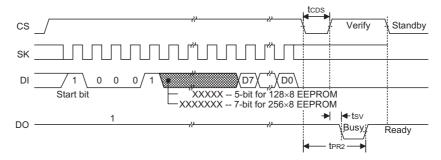
ERAL Timing



the internal write-cycle has ended. Before an "ERAL" instruction is transmitted an "EWEN" instruction must have been transmitted at some point earlier to ensure that the erase/write function of the EEPROM is enabled.

WRAL

The WRAL instruction is used to write the same data into the entire EEPROM. To instigate this instruction, the CS bit should be set high, followed by a high start bit and then the instruction code "00". Following on from this, a "01" should then be transmitted, and depending on whether the internal EEPROM has a 128×8 or 256×8 capacity, this should be followed by either 5-bits or 7-bits respectively, of "don't-care" data. The data information should then follow with the MSB bit being transmitted first. After the instruction code and data have been transmitted, the data will be written into the EEPROM when the CS bit is cleared to zero. The EEPROM does this by executing an internal write-cycle. This process takes place internally using the EEPROM's own internal clock and does not require any action from the SK clock. No further instructions can be accepted by the EEPROM until this internal write-cycle has finished. To determine when the write cycle has ended, CS should be again brought high and the DO bit polled. If D0 is low this indicates that the internal write-cycle is still in progress, however the D0 bit will change to a high value when the internal write-cycle has ended. Before a "WRAL" instruction is transmitted an "EWEN" instruction must have been transmitted at some point earlier to ensure that the erase/write function of the EEPROM is enabled. The WRAL instruction will automatically erase any previously written data making it unnecessary to first issue an erase instruction.



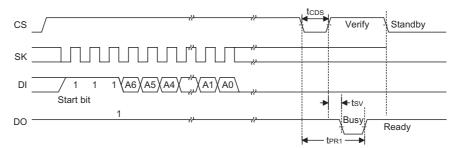
WRAL Timing

ERASE

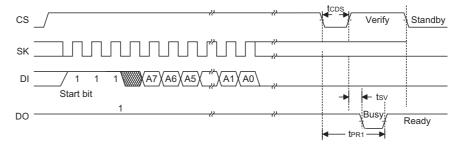
The "ERASE" instruction is used to erase data at a specified addresses. The data at the address specified will be set to "1". To instigate an "ERASE" instruction, the CS bit should be set high, followed by a high start bit and then the instruction code "11", all transmitted via the DI bit. The address information should then follow with the MSB bit being transmitted first. For the HT48E50 and HT48E70 devices, a dummy bit must be inserted between the last bit of the instruction code and the MSB of the address. After all the "ERASE" instruction code and address have been transmitted, the data at the specified address will be erased when the CS bit is cleared to zero. The EEPROM does this by executing an internal write cycle which will set all data at the specified address to "1". This process takes place internally using the EEPROM's own internal clock and does



not require any action from the SK clock. No further instructions can be accepted by the EEPROM until the write cycle has finished. To determine when the write cycle has ended, the CS should be again brought high and the DO bit polled. If the DO bit is low this indicates that the write-cycle is still in progress, however, the DO bit will change to a high value when the write-cycle has ended. Before an "ERASE" instruction is transmitted, an "EWEN" instruction must have been transmitted at some point earlier to ensure that the erase/write function of the EEPROM is enabled.



ERASE Timing - HT48E06, HT48E10 and HT48E30



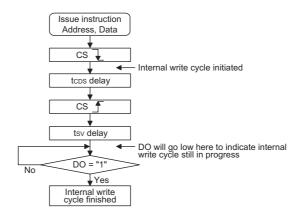
ERASE Timing - HT48E50 and HT48E70

Internal Write Cycle

The write or erase instructions, "WRITE", "ERASE", "ERAL" or "WRAL" will all use the EEPROM's internal write cycle function. As this function is completely internally timed, the SK clock is not required. As the MCU has no control over the timing of this write cycle, it must still have some way of knowing when the internal write cycle has completed. This is because, when the internal write cycle is executing, the EEPROM will not accept any further instructions from the MCU. The MCU must therefore wait until the write cycle has finished before sending any further instructions.

One way for the MCU to know when the write cycle has terminated is to poll the DO bit after the CS bit has issued a low pulse. The low going edge of this CS bit pulse will initiate the internal write cycle, when the bit is returned high the DO bit will go low to indicated that the write cycle is in progress. When the DO bit returns high this indicates that the internal write cycle has ended and that the EEPROM is ready to receive further instructions.





Internal Write Cycle Busy Polling

Initialising the EEPROM

After the MCU is powered on and if the EEPROM is to be used, it must be initialised in a specific way before any user instructions are transmitted. This is achieved by first transmitting an EWEN instruction, then by issuing a WRITE instruction to write random data to any single address in the EEPROM. The initialisation procedure can then be terminated by issuing an EWDS instruction, however at this point, if actual user data is to be imminently written to the EEPROM, this last step is optional.

The following is an example program of how this can be implemented:

```
A,01h
mov
                    ; set to bank 1
mov
        BP,A
        A,40h
mov
        MP1,A
                   ; set MP1 to EECR address
mov
call
        EWEN
                    ; subroutine to run EWEN instructions
mov
        A, 7Fh
        EEADDR, A
mov.
mov
        A, 55h
mov
        EEDATA, A
       WRITE
                    ; subroutine to run WRITE instruction
call
                    ; write 55h data to address 7Fh
call
        EWDS
                    ; optional subroutine to run EWDS instruction
```

EEPROM Program Examples

The following short programs gives examples of how to send instructions, read and write to the EEPROM. These programs can form a basis of understanding as to how the internal EEPROM memory is to be used to store and retrieve data. The programs are for use with the HT48E50 and HT48E70 devices, which have the same capacity internal EEPROM memory of 256×8 bits. For the other devices, which have a smaller 128×8 bit EEPROM memory capacity, the dummy bit which is inserted between the instruction code transmission and the address MSB, is not transmitted.



Example 1 - Definitions and Sending Instructions to the EEPROM

```
; EEPROM lines setup to have a corresponding
_CS EQU IAR1.4
                                ; Bit in the Indirect Addressing Register IAR1 ; EEPROM can only be indirectly addressed using
 SK EOU IAR1.5
DI EQU IAR1.6
                                 ; MP1
_DO EQU IAR1.7
__EECR EQU 40H ; Setup address of the EEPROM control register C_Addr_Length EQU 8 ; Address length - 8-bits for this device C_Data_Length EQU 8 ; Data length - always 8-bits
DATA .SECTION at 70h 'DATA'
EE_command DB ? ; Stores the read or write instruction ; information
                           ; Store write data or read data address
; Store read or write data
; Temporary counter
ADDR
          DB ?
WR_Data DB ?
COUNT DB ?
                                ; Write instruction code subroutine
WriteCommand:
    MOV A, 3
                                  ; Read, write and erase instructions are 3 bits
                                 ; long
    MOV COUNT, A
WriteCommand 0:
    CLR _DI ; Prepare the transmitted bit SZ EE_command.7 ; Check value of highest instruction code bit
    CLR DI
    SET _DI
SET _SK
     CLR _SK
     CLR C
    CLR C
RLC EE_command
                                 ; Get next bit of instruction code
     SDZ COUNT
                                 ; Check if last bit has been transmitted
     JMP WriteCommand 0
     CLR _DI
     RET
```

Example 2 - Transmitting an Address to the EEPROM

```
; Write address subroutine
WriteAddr:
                         ; Setup address length - 8 bits for HT48E50 and
   MOV A, C_Addr_Length
                           ; HT48E70 devices
   MOV COUNT, A
   SET _SK
                           ; Dummy bit transmission for HT48E50 and
                           ; HT48E70 devices only
   CLR SK
                           ; Not required for other devices
WriteAddr 0:
   CLR DI
   SZ ADDR.7
                          ; Check value of address MSB
   SET _DI
   CLR C
   RLC ADDR
                          : Get next address bit
   SET _SK
CLR _SK
SDZ COUNT
                           ; Check if address LSB has been written
   JMP WriteAddr 0
   CLR _DI
   RET
```



Example 3 - Writing Data to the EEPROM

```
WriteData:
   MOV A, C_Data_Length ; Setup data length
   MOV COUNT, A
WriteData 0:
   CLR _DI
   SZ WR_Data.7
                     ; Check value of data MSB
   SET DI
   CLR C
   RLC WR Data
                          ; Get next address bit
   SET _SK
CLR _SK
   SDZ COUNT
                          ; Check if data LSB has been written
   JMP _0
   CLR _CS
                          ; CS low edge initiates internal write cycle
                          ; CS high edge allows DO to be used to indicate ; end of write cycle
   SET _CS
   SNZ DO
                          ; Poll for DO high to indicate end of write
                           ; cycle
   JMP $-1
   RET
```

Example 4 - Reading Data from the EEPROM

```
ReadData:

MOV A,C_Data_Length ; Setup data length
MOV COUNT,A
CLR WR_Data

ReadData_0:
CLR C
RLC WR_Data
SET _SK
SZ _DO ; check value of data MSB
SET WR_Data.0
CLR _SK
SDZ COUNT ; check if LSB has been received
JMP _0
MOV A,WR_Data
RET
```



Input/Output Ports

Holtek microcontrollers offer considerable flexibility on their I/O ports. with the input or output designation of every pin fully under user program control, pull-high options for all ports and wake-up options on certain pins, the user is provided with an I/O structure to meet the needs of a wide range of application possibilities.

Depending upon which device or package is chosen, the microcontroller range provides from 13 to 56 bidirectional input/output lines labeled with port names PA, PB, PC, etc. These I/O ports are mapped to the RAM Data Memory with specific addresses as shown in the Special Purpose Data Memory table. All of these I/O ports can be used for input and output operations. For input operation, these ports are non-latching, which means the inputs must be ready at the T2 rising edge of instruction "MOV A,[m]", where m denotes the port address. For output operation, all the data is latched and remains unchanged until the output latch is rewritten.

Pull-high Resistors

Many product applications require pull-high resistors for their switch inputs usually requiring the use of an external resistor. To eliminate the need for these external resistors, all I/O pins, when configured as an input have the capability of being connected to an internal pull-high resistor. These pull-high resistors are selectable via configuration options and are implemented using a weak PMOS transistor. Note that if the pull-high option is selected, then all I/O pins on that port will be connected to pull-high resistors, individual pins cannot be selected for pull-high resistor options.

Port A Wake-up

Each device has a HALT instruction enabling the microcontroller to enter a Power Down Mode and preserve power, a feature that is important for battery and other low-power applications. Various methods exist to wake-up the microcontroller, one of which is to change the logic condition on one of the Port A pins from high to low. After a "HALT" instruction forces the microcontroller into entering the Power Down Mode, the processor will remain in a low-power state until the logic condition of the selected wake-up pin on Port A changes from high to low. This function is especially suitable for applications that can be woken up via external switches. Note that each pin on Port A can be selected individually to have this wake-up feature.

I/O Port Control Registers

Each I/O port has its own control register PAC, PBC, PCC, etc., to control the input/output configuration. with this control register, each CMOS output or input with or without pull-high resistor structures can be reconfigured dynamically under software control. Each pin of the I/O ports is directly mapped to a bit in its associated port control register. For the I/O pin to function as an input, the corresponding bit of the control register must be written as a "1". This will then allow the logic state of the input pin to be directly read by instructions. When the corresponding bit of the control register is written as a "0", the I/O pin will be setup as a CMOS output. If the pin is currently setup as an output, instructions can still be used to read the output register. However, it should be noted that the program will in fact only read the status of the output data latch and not the actual logic status of the output pin. Note that with the exception of the HT48E06 device, there is an additional configuration option for Port A that can select whether the inputs on this port are Schmitt Trigger types or non-Schmitt Trigger types. Inputs for the other ports are all Schmitt Trigger type.



Pin-shared Functions

The flexibility of the microcontroller range is greatly enhanced by the use of pins that have more than one function. Limited numbers of pins can force serious design constraints on designers but by supplying pins with multi-functions, many of these difficulties can be overcome. For some pins, the chosen function of the multi-function I/O pins is set by configuration options while for others the function is set by application program control.

Buzzer

The buzzer pins BZ and \overline{BZ} are pin-shared with I/O pins PB0 and PB1. The buzzer function is selected via a configuration option and remains fixed after the device is programmed. Note that the corresponding bits of the port control register, PBC, must setup the pins as outputs to enable the buzzer outputs. If the PBC port control register has setup the pins as inputs, then the pins will function as normal logic inputs with the usual pull-high options, even if the buzzer configuration option has been selected.

External Interrupt Input

The external interrupt pin $\overline{\text{INT}}$ is pin-shared with the I/O pin PC0 or PG0 depending upon which device is used. However, for the HT48E70 devices, the external interrupt pin $\overline{\text{INT}}$ is an independent non-shared pin. For the shared function pins to operate as an external interrupt pin and not as a normal I/O pin, the corresponding external interrupt enable bits in the INTC interrupt control register must be correctly set. For applications not requiring an external interrupt input, the pin-shared external interrupt pin can be used as a normal I/O pin, however to do this, the external interrupt enable bits in the INTC register must be disabled.

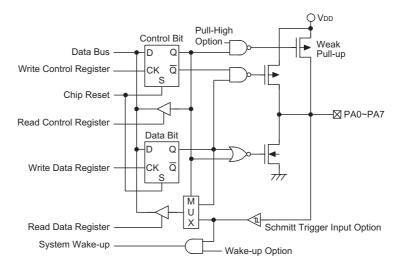
External Timer/Event Counter Input

Each device contains either one or two Timer/Event Counters depending upon which one is chosen. Each Timer/Event Counter has an external input pin, known as TMR, TMR0 or TMR1. For all devices with a single Timer/Event Counter, the external input pin TMR is pin-shared with I/O pin PC0 or PC1. For devices with two Timer/Event Counters, the external input pins TMR0 and TMR1 are pin-shared with pins PC0 and PC5 respectively or exist as independent non-shared pins depending upon which device and which package is selected. If a shared pin is to be used as a Timer/Event Counter input, then the corresponding Timer/Event Counter must be configured to be in the Event Counter or Pulse Width Measurement Mode. This is achieved by setting the appropriate bits in the relevant Timer/Event Counter Control Register. The pin must also be setup as an input by setting the appropriate bit in the Port Control Register. Pull-high resistor options can also be selected via the appropriate port pull-high configuration option. If the shared pin is to be used as a normal I/O pin, then the external timer input function must be disabled, by ensuring that the corresponding Timer/Event Counter is configured to be in the Off Mode or Timer Mode.

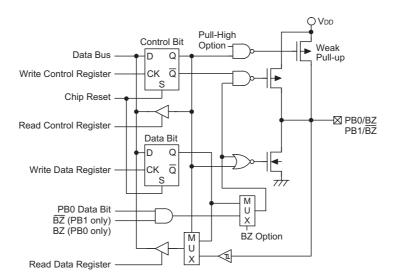
I/O Pin Structures

The following diagrams illustrate the I/O pin internal structures. As the exact logical construction of the I/O pin may differ from these drawings, they are supplied as a guide only to assist with the functional understanding of the I/O pins. Note also that the specified pins refer to the largest device package, therefore not all pins specified will exist on all devices.



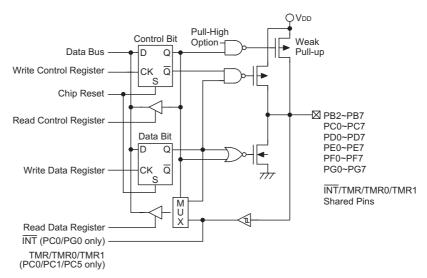


PA Input/Output Port



PB0~PB1 Input/Output Ports

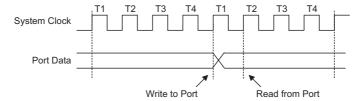




PB, PC, PD, PE, PF and PG Input/Output Ports

Programming Considerations

Within the user program, one of the first things to consider is port initialization. After a reset, all of the I/O data and port control registers will be set high. This means that all I/O pins will default to an input state, the level of which depends on the other connected circuitry and whether pull-high options have been selected. If the port control registers, PAC, PBC, PCC, etc., are then programmed to setup some pins as outputs, these output pins will have an initial high output value unless the associated port data registers, PA, PB, PC, etc., are first programmed. Selecting which pins are inputs and which are outputs can be achieved byte-wide by loading the correct values into the appropriate port control register or by programming individual bits in the port control register using the "SET [m].i" and "CLR [m].i" instructions. Note that when using these bit control instructions, a read-modify-write operation takes place. The microcontroller must first read in the data on the entire port, modify it to the required new bit values and then rewrite this data back to the output ports.



Port A has the additional capability of providing wake-up functions. When the device is in the Power Down Mode, various methods are available to wake the device up. One of these is a high to low transition of any of the Port A pins. Single or multiple pins on Port A can be setup to have this function.



Timer/Event Counters

The provision of timers form an important part of any microcontroller, giving the designer a means of carrying out time related functions. The devices in the I/O Type MTP MCU with EEPROM series contain either one or two count-up timers of either 8 or 16-bit capacity depending upon which device is selected. As each timer has three different operating modes, they can be configured to operate as a general timer, an external event counter or as a pulse width measurement device. The provision of an internal prescaler to the clock circuitry of some of the timer/event counters gives added range to the timer.

There are two types of registers related to the Timer/Event Counters. The first is the register that contains the actual value of the timer and into which an initial value can be preloaded. Reading from this register retrieves the contents of the Timer/Event Counter. The second type of associated register is the Timer Control Register which defines the timer options and determines how the timer is to be used. All devices can have the timer clock configured to come from the internal clock source. In addition, the timer clock source can also be configured to come from an external timer pin. The accompanying table lists the associated timer register names.

	HT48E06	HT48E10	HT48E30	HT48E50	HT48E70
No. of 8-bit Timers	1	1	1	1	0
Timer Register Name	TMR	TMR	TMR	TMR0	_
Timer Control Register	TMRC	TMRC	TMRC	TMR0C	_
No. of 16-bit Timers	0	0	0	1	2
Timer Register Name	_	_	_	TMR1L/TMR1H	TMR0L/TMR0H TMR1L/TMR1H
Timer Control Register	_	_	_	TMR1C	TMR0C TMR1C

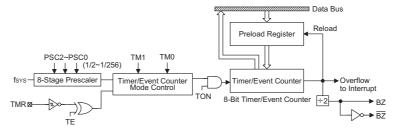
An external clock source is used when the timer is in the event counting mode, the clock source being provided on the external timer pin, known as TMR, TMR0 or TMR1 depending on which device is selected. These external pins may be pin-shared with other I/O pins depending upon which device and package is chosen. Depending upon the condition of the TE, T0E or T1E bit in the corresponding Timer Control Register, each high to low, or low to high transition on the external timer input pin will increment the counter by one.

Configuring the Timer/Event Counter Input Clock Source

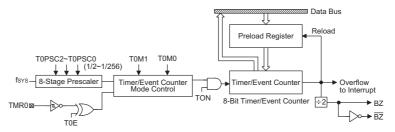
The internal timer's clock can originate from various sources, depending upon which device and which timer is chosen. The system clock input timer source is used when the timer is in the timer mode or in the pulse width measurement mode. Depending upon which timer and which device is chosen this system clock timer source may be first divided by a prescaler, the division ratio of which is conditioned by the Timer Control Register bits PSC2~PSC0 or T0PSC2~T0PSC0.



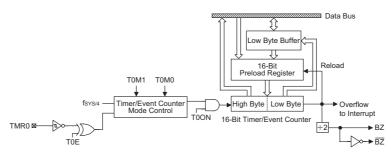
An external clock source is used when the timer is in the event counting mode, the clock source being provided on an external timer pin, TMR, TMR0 or TMR1 depending upon which device and which timer is used. Depending upon the condition of the TE, T0E or T1E bit, each high to low, or low to high transition on the external timer pin will increment the counter by one.



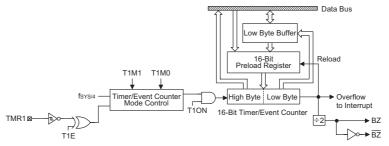
8-Bit Timer/Event Counter Structure - HT48E06, HT48E10 and HT48E30



8-Bit Timer/Event Counter 0 Structure - HT48E50



16-Bit Timer/Event Counter 0 Structure - HT48E70



16-Bit Timer/Event Counter 1 Structure - HT48E50 and HT48E70



Timer Registers - TMR, TMR0, TMR0L/TMR0H, TMR1L/TMR1H

The timer registers are special function registers located in the Special Purpose Data Memory and is the place where the actual timer value is stored. For the 8-bit timer, this register is known as TMR or TMR0, depending upon which device is used. In the case of the 16-bit timer, a pair of 8-bit registers is required to store the16-bit timer value. These register pairs are known as TMR0L/TMR0H or TMR1L/TMR1H depending upon which device and timer is used. The value in the timer registers increases by one each time an internal clock pulse is received or an external transition occurs on the external timer pin. The timer will count from the initial value loaded by the preload register to the full count of FFH for the 8-bit timer or FFFFH for the 16-bit timers at which point the timer overflows and an internal interrupt signal is generated. The timer value will then be reset with the initial preload register value and continue counting.

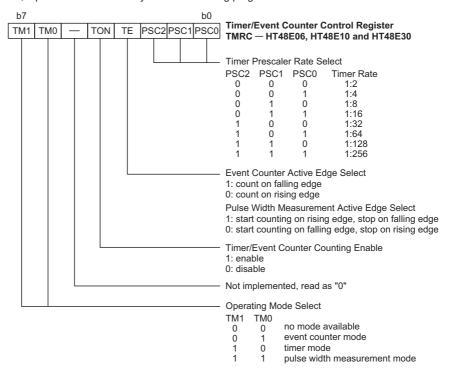
Note that to achieve a maximum full range count of FFH for the 8-bit timer or FFFFH for the 16-bit timers, the preload registers must first be cleared to all zeros. It should be noted that after power-on, the preload registers will be in an unknown condition. Note that if the Timer/Event Counters are in an OFF condition and data is written to their preload registers, this data will be immediately written into the actual counter. However, if the counter is enabled and counting, any new data written into the preload data registers during this period will remain in the preload registers and will only be written into the actual counter the next time an overflow occurs.

For devices which have an internal 16-bit Timer/Event Counter, and which therefore have both low byte and high byte timer registers, accessing these registers is carried out in a specific way. It must be noted that when using instructions to preload data into the low byte register, namely TMR0L or TMR1L, the data will only be placed in a low byte buffer and not directly into the low byte register. The actual transfer of the data into the low byte register is only carried out when a write to its associated high byte register, namely TMR0H or TMR1H, is executed. On the other hand, using instructions to preload data into the high byte timer register will result in the data being directly written to the high byte register. At the same time the data in the low byte buffer will be transferred into its associated low byte register. For this reason, when preloading data into the 16-bit timer registers, the low byte should be written first. It must also be noted that to read the contents of the low byte register, a read to the high byte register must first be executed to latch the contents of the low byte buffer from its associated low byte register. After this has been done, the low byte register can be read in the normal way. Note that reading the low byte timer register directly will only result in reading the previously latched contents of the low byte buffer and not the actual contents of the low byte timer register.



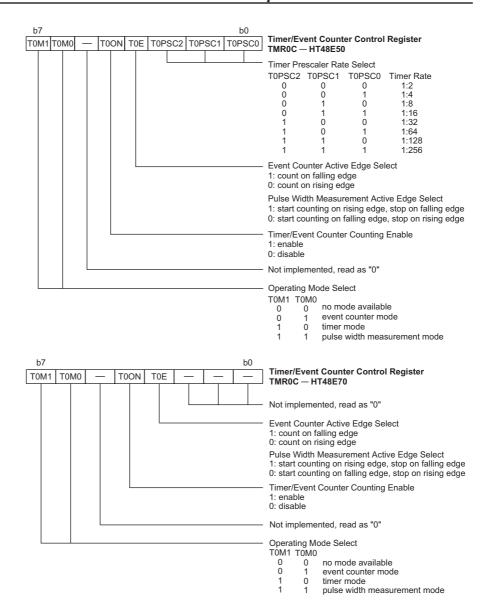
Timer Control Registers - TMRC, TMR0C, TMR1C

The flexible features of the Holtek microcontroller Timer/Event Counters enable them to operate in three different modes, the options of which are determined by the contents of their respective control register. For devices with only one timer, the single Timer Control Register is known as TMRC while for devices with more than one timer, there are two Timer Control Registers, known as TMROC and TMR1C. It is the Timer Control Register together with its corresponding timer registers that control the full operation of the Timer/Event Counters. Before the timers can be used, it is essential that the appropriate Timer Control Register is fully programmed with the right data to ensure its correct operation, a process that is normally carried out during program initialization.



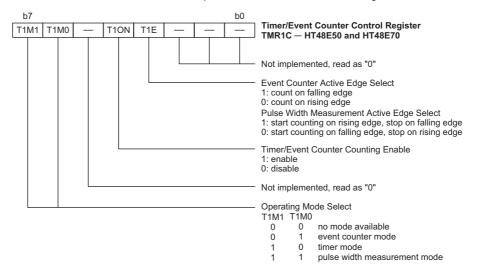
To choose which of the three modes the timer is to operate in, either in the timer mode, the event counting mode or the pulse width measurement mode, bits 7 and 6 of the Timer Control Register, which are known as the bit pair TM1/TM0, T0M1/T0M0 or T1M1/T1M0 respectively, depending upon which timer is used, must be set to the required logic levels. The timer-on bit, which is bit 4 of the Timer Control Register and known as TON, T0ON or T1ON, depending upon which timer is used, provides the basic on/off control of the respective timer. Setting the bit high allows the counter to run, clearing the bit stops the counter. For timers that have prescalers, bits 0~2 of the Timer Control Register determine the division ratio of the input clock prescaler. The prescaler bit settings have no effect if an external clock source is used. If the timer is in the event count or pulse width measurement mode, the active transition edge level type is selected by the logic level of bit 3 of the Timer Control Register which is known as TE, T0E or T1E, depending upon which timer is used.

Chapter 1 Hardware Structure



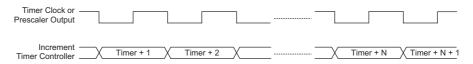


The HT48E50 and HT48E70 devices have two internal timers, Timer/Event Counter 0 and Timer/Event Counter 1, and therefore require an additional Timer Control Register TMR1C.



Configuring the Timer Mode

In this mode, the timer can be utilized to measure fixed time intervals, providing an internal interrupt signal each time the counter overflows. To operate in this mode, the bit pair, TM1/TM0, T0M1/T0M0 or T1M1/T1M0, depending upon which timer is used, must be set to 1 and 0, respectively. In this mode the internal clock is used as the timer clock. Note that for the 8-bit timers, which are the single Timer/Event Counters in the HT48E06, HT48E10 and HT48E30 devices and Timer/ Event Counter 0 in the HT48E50 device, the timer input clock source is f_{SYS}. However, this timer clock source is further divided by a prescaler, the value of which is determined by the bits PSC2~PSC0 or T0PSC2~T0PSC0 in the relevant Timer Control Register. For the remaining Timer/Event Counters, which are the 16-bit Timer/Event Counters, the input clock frequency is f_{SYS}/4. There is no prescaler function for the 16-bit timers. The timer-on bit, TON, TOON or T1ON, depending upon which timer is used, must be set high to enable the timer to run. Each time an internal clock high to low transition occurs, the timer increments by one; when the timer is full and overflows, an interrupt signal is generated and the timer will preload the value already loaded into the preload register and continue counting. The timer interrupts can be disabled by ensuring that the ETI, ET0I or ET1I bits in the INTC register are reset to zero. It should be noted that a timer overflow and corresponding timer interrupt is one of the wake-up sources.



Timer Mode Timing Chart



Configuring the Event Counter Mode

In this mode, a number of externally changing logic events, occurring on the external timer pin, can be recorded by the internal timer. For the timer to operate in the event counting mode, the bit pair, TM1/TM0, T0M1/T0M0 or T1M1/T1M0, depending upon which timer is used, must be set to 0 and 1, respectively. The timer-on bit, TON, T0ON or T1ON, depending upon which timer is used, must be set high to enable the timer to count. Depending upon which counter is used, if the TE, T0E or T1E bit is low, the counter will increment each time the external timer pin receives a low to high transition. If the TE, T0E or T1E bit is high, the counter will increment each time the external timer pin receives a high to low transition. As in the case of the other two modes, when the counter is full, the timer will overflow and generate an internal interrupt signal. The counter will then preload the value already loaded into the preload register. If the external timer pins are pin-shared with other I/O pins, to ensure that the pin is configured to operate as an event counter input pin, two things have to happen. The first is to ensure that the TM1/TM0, T0M1/T0M0 or T1M1/T1M0 bits place the Timer/Event Counter in the event counting mode, the second is to ensure that the port control register configures the pin as an input. It should be noted that in this event counting mode, the Timer/Event Counter will continue to record externally changing logic events on the timer input pin, even if the microcontroller is in the Power Down Mode. As a result when the timer overflows it will generate a timer interrupt and corresponding wake-up source. Note that the timer interrupts can be disabled by ensuring that the ETI, ET0I or ET1I bits in the INTC register are reset to zero.



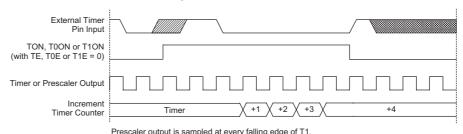
Event Counter Mode Timing Chart

Configuring the Pulse Width Measurement Mode

In this mode, the width of external pulses applied to the external timer pin can be measured. In the Pulse Width Measurement Mode the timer clock source is supplied by the internal clock. For the timer to operate in this mode, the bit pair, TM1/TM0, T0M1/T0M0 or T1M1/T1M0, depending upon which timer is used, must both be set high. Depending upon which counter is used, if the TE, T0E or T1E bit is low, once a high to low transition has been received on the external timer pin, the timer will start counting until the external timer pin returns to its original high level. At this point the TON, T0ON or T1ON bit, depending upon which counter is used, will be automatically reset to zero and the timer will stop counting. If the TE, T0E or T1E bit is high, the timer will begin counting once a low to high transition has been received on the external timer pin and stop counting when the external timer pin returns to its original low level. As before, the TON, T0ON or T1ON bit will be automatically reset to zero and the timer will stop counting. It is important to note that in the Pulse Width Measurement Mode, the TON, TOON or T1ON bit is automatically reset to zero when the external control signal on the external timer pin returns to its original level, whereas in the other two modes the TON, T0ON or T1ON bit can only be reset to zero under program control. The residual value in the timer, which can now be read by the program, therefore represents the length of the pulse received on the external timer pin. As the TON, T0ON or T1ON bit has now been reset, any further transitions on the external timer pin, will be ignored. Not until the TON, T0ON or T1ON bit is again set high by the program can the timer begin further pulse width measurements. In this way, single shot pulse measurements can be easily made. It should be noted that in this mode the counter is controlled by logical transitions on the external timer pin and not by the logic level.

I/O Type MTP MCU with EEPROM

As in the case of the other two modes, when the counter is full, the timer will overflow and generate an internal interrupt signal. The counter will also be reset to the value already loaded into the preload register. If the external timer pin is pin-shared with other I/O pins, to ensure that the pin is configured to operate as a pulse width measuring input pin, two things have to happen. The first is to ensure that the TM1/TM0, T0M1/T0M0 or T1M1/T1M0 bits place the Timer/Event Counter in the pulse width measuring mode, the second is to ensure that the port control register configures the pin as an input. It should be noted that a timer overflow and corresponding timer interrupt is one of the wake-up sources. Note that the timer interrupts can be disabled by ensuring that the ETI, ET0I or ET1I bits in the INTC register are reset to zero.



Pulse Width Measurement Mode Timing Chart

Programmable Frequency Divider (PFD) and Buzzer Application

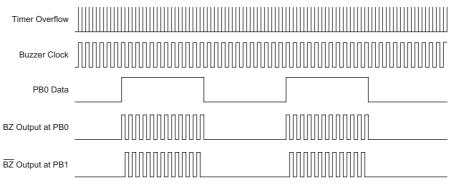
Operating similar to a programmable frequency divider, the buzzer function within the microcontroller provides a means of producing a variable frequency output suitable for applications, such as piezo-buzzer driving or other interfaces requiring a precise frequency generator.

The BZ and \overline{BZ} are a complimentary pair and pin-shared with I/O pins, PB0 and PB1. The function is selected via configuration option, however, if not selected, the pins can operate as normal I/O pins. Note that the \overline{BZ} pin is the inverse of the BZ pin generating a kind of differential output and supplying more power to connected interfaces such as buzzers.

The timer overflow signal is the clock source for the buzzer circuit. The output frequency is controlled by loading the required values into the timer prescaler and timer registers to give the required division ratio. The counter will begin to count-up from this preload register value until full, at which point an overflow signal is generated, causing both the BZ and $\overline{\text{BZ}}$ outputs to change state. The counter will then be automatically reloaded with the preload register value and continue counting-up. Refer to the relevant Timer/Event Counters section for details of its settings and operations. For the HT48E50 and HT48E70 devices, either Timer/Event Counter 0 or Timer/Event Counter 1 can form the clock source for the buzzer function, selectable via configuration option.

If the configuration option has selected the buzzer function, then for both buzzer outputs to operate, it is essential that the Port B control register PBC bit 0 and PBC bit 1 are setup as outputs. If only one pin is setup as an output, the other pin can still be used as a normal data input pin. However, if both pins are setup as inputs then the buzzer will not function. The buzzer outputs will only be activated if bit PB0 is set to "1". This output data bit is used as the on/off control bit for the buzzer outputs. Note that the BZ and $\overline{\text{BZ}}$ outputs will both be low if the PB0 output data bit is cleared to "0". The condition of data bit PB1 has no effect on the overall control of the BZ and $\overline{\text{BZ}}$ pins.





PFD Output Control

Using this method of frequency generation, and if a crystal oscillator is used for the system clock, very precise values of frequency can be generated.

Prescaler

The single timer in the HT48E06, HT48E10 and HT48E30, and Timer/Event Counter 0 in the HT48E50 all possess a prescaler. Bits 0~2 of their associated Timer Control Register, namely bits PSC0~ PSC2 or T0PSC0~T0PSC2, define the prescaling stages of the internal clock source of the Timer/Event Counter.

I/O Interfacing

The Timer/Event Counter, when configured to run in the event counter or pulse width measurement mode, require the use of external pins for correct operation. As these external timer pins may be pin-shared with other I/O pins, depending upon which device is selected, they must be configured correctly to ensure they are setup for use as Timer/Event Counter inputs and not as normal I/O pins. This is implemented by ensuring that the mode select bits in the Timer/Event Counter control register, select either the event counter or pulse width measurement mode. Additionally the Port Control Register bits for these pins must be set high to ensure that the pin is setup as an input. Any pull high configuration for these pins will remain valid even if the pin is used as a Timer/Event Counter input.

Programming Considerations

When configured to run in the timer mode, the internal system clock is used as the timer clock source and is therefore synchronized with the overall operation of the microcontroller. In this mode, when the appropriate timer register is full, the microcontroller will generate an internal interrupt signal directing the program flow to the respective internal interrupt vector. For the pulse width measurement mode, the internal system clock is also used as the timer clock source but the timer will only run when the correct logic condition appears on the external timer input pin. As this is an external event and not synchronised with the internal timer clock, the microcontroller will only see this external event when the next timer clock pulse arrives. As a result there may be small differences in measured values requiring programmers to take this into account during programming. The same applies if the timer is configured to be in the event counting mode which again is an external event and not synchronised with the internal system or timer clock.



When the 8-bit Timer/Event Counter or the high byte of the 16-bit Timer/Event Counter is read or if data is written to the preload registers, the clock is inhibited to avoid errors, however as this may result in a counting error, this should be taken into account by the programmer. Care must be taken to ensure that the timers are properly initialised before using them for the first time. The associated timer enable bits in the interrupt control register must be properly set otherwise the internal interrupt associated with the timer will remain inactive. The edge select, timer mode and clock source control bits in timer control register must also be correctly set to ensure the timer is properly configured for the required application. It is also important to ensure that an initial value is first loaded into the timer registers before the timer is switched on; this is because after power-on the initial values of the timer registers are unknown. After the timer has been initialised the timer can be turned on and off by controlling the enable bit in the timer control register.

Timer Program Example

The following example program section is based on the HT48E50 device, which contains one internal 8-bit Timer/Event Counter and one internal 16-bit Timer/Event Counter. Programming the Timer/Event Counters for other devices is conducted in a very similar way. The program shows how the Timer/Event Counter registers are setup along with how the interrupts are enabled and managed. Points to note in the example are how, for the 16-bit Timer/Event Counters, the low byte must be written first, this is because the 16-bit data will only be written into the actual timer register when the high byte is loaded. Also note how the Timer/Event Counter is turned on, by setting bit 4 of the respective Timer Control Register. The Timer/Event Counter can be turned off in a similar way by clearing the same bit. This example program sets the Timer/Event Counters to be in the timer mode, which uses the internal system clock as their clock source.

```
include ht48e50.inc
   jmp begin
   org 04h
                          ; external interrupt vector
   reti
  org 08h
jmp tmr0int
                           ; Timer Counter 0 interrupt vector
                            ; jump here when Timer O overflows
   org Och
                            ; Timer Counter 1 interrupt vector
   jmp tmr1int
                            ; jump here when Timer 1 overflows
   org 20h
                            ; main program
;internal Timer 0 interrupt routine
                            ; Timer 0 main program placed here
reti
; internal Timer 1 interrupt routine
tmr1int:
                            ; Timer 1 main program placed here
   reti
```



```
begin:
;setup Timer O registers
   mov a,09bh
                              ; setup Timer O preload value
  mov tmr0,a;
mov a,081h
                              ; setup Timer O control register
                              ; timer mode and prescaler set to /4
  mov tmr0c,a
;setup Timer 1 registers
   clr tmr11
                              ; clear both low and high bytes to give maximum
   clr tmr1h
                              ; setup Timer 1 control register ; Timer 1 has no prescaler
   mov a,080h
   mov tmr1c,a
; setup interrupt register
                              ; enable master interrupt and both timer ; interrupts
  mov a.00dh
   mov intc, a
set tmr0c.4; start Timer 0
set tmrlc.4; start Timer 1
```

Interrupts

The I/O Type MTP MCU with EEPROM series each contains a range of both external and internal interrupt functions. The external interrupt is controlled by the action of an external interrupt pin, which is present on all devices. One internal interrupt control register contains the control bits, which manage the enable/disable function of the individual interrupts and their corresponding interrupt request flags.

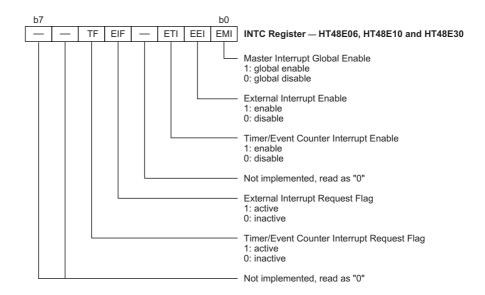
Interrupt Registers

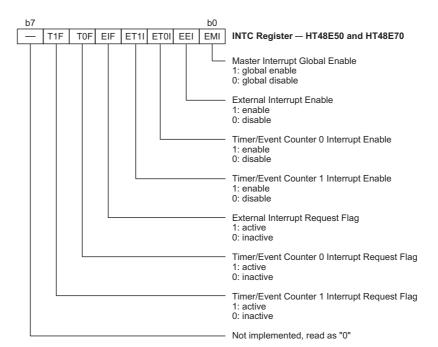
A single interrupt control register, known as INTC is provided to control all the interrupt control features.

Once an interrupt subroutine is serviced, all the other interrupts will be blocked, as the EMI bit will be cleared automatically. This will prevent any further interrupt nesting from occurring. However, if other interrupt requests occur during this interval, although the interrupt will not be immediately serviced, the request flag will still be recorded. If an interrupt requires immediate servicing while the program is already in another interrupt service routine, the EMI bit should be set after entering the routine, to allow interrupt nesting. If the stack is full, the interrupt request will not be acknowledged, even if the related interrupt is enabled, until the Stack Pointer is decremented. If immediate service is desired, the stack must be prevented from becoming full.

All interrupts have the capability of waking up the processor when in the Power Down Mode. As an interrupt is serviced, a control transfer occurs by pushing the Program Counter onto the stack, followed by a branch to a subroutine at a specified location in the Program Memory. Only the Program Counter is pushed onto the stack. If the contents of the accumulator or status register or other registers are altered by the interrupt service program, which may corrupt the desired control sequence, then the contents should be saved in advance.

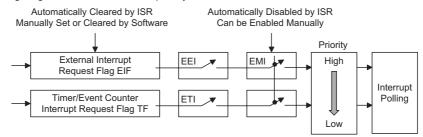
I/O Type MTP MCU with EEPROM



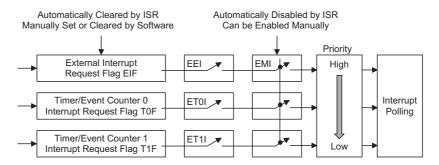




The various interrupt enable bits, together with their associated request flags, are shown in the following diagrams with their order of priority.



Interrupt Scheme - HT48E06, HT48E10 and HT48E30



Interrupt Scheme - HT48E50 and HT48E70

Interrupt Priority

Interrupts, occurring in the interval between the rising edges of two consecutive T2 pulses, will be serviced on the latter of the two T2 pulses, if the corresponding interrupts are enabled. In case of simultaneous requests, the following table shows the priority that is applied.

Interrupt Source	HT48E06 Priority	HT48E10 Priority	HT48E30 Priority	HT48E50 Priority	HT48E70 Priority
External Interrupt	1	1	1	1	1
Timer/Event Counter or Timer/Event Counter 0 Overflow	2	2	2	2	2
Timer/Event Counter 1 Overflow	N/A	N/A	N/A	3	3

Note

For the HT48E06, HT48E10 and HT48E30 devices, there is only one timer. The HT48E50 and HT48E70 devices have two internal timers.

In cases where several interrupts are enabled, and where more than one interrupt occur simultaneously, the interrupt that is serviced first will follow the order shown in the table. Suitable masking of the individual interrupts using the INTC register can prevent simultaneous occurrences.



External Interrupt

For an external interrupt to occur, the corresponding external interrupt enable bit must be first set. This enable bit is bit 1 of the INTC register and is known as EEI. An external interrupt is triggered by a high to low transition on the external interrupt pin, after which the related interrupt request flag will be set. This is bit 4 of the INTC register and is known as EIF. When the master interrupt and external interrupt bits are enabled, the stack is not full and a high to low transition occurs on the external interrupt pin, a subroutine call to the corresponding external interrupt vector, which is located at 04H, will occur. After entering the interrupt execution routine, the corresponding interrupt request flag, EIF, will be reset and the EMI bit will be cleared to disable other interrupts. Depending upon which device is selected, the $\overline{\text{INT}}$ pin may be pin-shared with PC0 or PG0 or may exist as an independent pin. If pin-shared, the pin must first be setup as an input to enable correct operation.

Timer/Event Counter Interrupt

For a timer generated internal interrupt to occur, the corresponding timer interrupt enable bit must be first set. For devices with a single timer, this is bit 2 of the INTC register and is known as ETI. For devices with two timers, the Timer/Event Counter 0 interrupt enable is bit 2 of the INTC register and known as ET0I while the Timer 1 interrupt enable is bit 3 of the INTC register and known as ET1I. An actual Timer/Event Counter interrupt will be initialised when the Timer/Event Counter interrupt request flag is set, caused by a timer overflow. For devices which have a single timer, this is bit 5 of the INTC register and is known as TF. For devices which have two timers, the Timer/Event Counter 0 request flag is bit 5 of the INTC register and known as T0F, while the Timer/Event Counter 1 request flag is bit 6 of the INTC register and known as T1F. When the master interrupt global enable bit is set, the stack is not full and the corresponding timer interrupt enable bit is set, an internal interrupt will be generated when the corresponding timer overflows. This will create a subroutine call to location 08H for devices with a single timer. For devices with two timers, a subroutine call to location 08H will occur for Timer/Event Counter 0 and a subroutine call to location 0CH for Timer/Event Counter 1. After entering the timer interrupt execution routine, the corresponding timer interrupt request flag, either, TF, T0F or T1F will be reset and the EMI bit will be cleared to disable other interrupts.

Programming Considerations

The interrupt request flags, TF, T0F, T1F and EIF, together with the interrupt enable bits ETI, ET0I, ET1I, EEI and EMI, form the interrupt control register INTC, which is located in the Data Memory. By disabling the interrupt enable bits, a requested interrupt can be prevented from being serviced, however, once an interrupt request flag is set, it will remain in this condition in the INTC register until the corresponding interrupt is serviced or until the request flag is cleared by a software instruction.

It is recommended that programs do not use the "CALL subroutine" instruction within the interrupt subroutine. Interrupts often occur in an unpredictable manner or need to be serviced immediately in some applications. If only one stack is left and the interrupt is not well controlled, the original control sequence will be damaged once a "CALL subroutine" is executed in the interrupt subroutine.



Reset and Initialization

A reset function is a fundamental part of any microcontroller ensuring that the device can be set to some predetermined condition irrespective of outside parameters. The most important reset condition is after power is first applied to the microcontroller. In this case, internal circuitry will ensure that the microcontroller, after a short delay, will be in a well defined state and ready to execute the first program instruction. After this power-on reset, certain important internal registers will be set to defined states before the program commences. One of these registers is the Program Counter, which will be reset to zero forcing the microcontroller to begin program execution from the lowest Program Memory address.

In addition to the power-on reset, situations may arise where it is necessary to forcefully apply a reset condition when the microcontroller is running. One example of this is where after power has been applied and the microcontroller is already running, the \overline{RES} line is forcefully pulled low. In such a case, known as a normal operation reset, some of the microcontroller registers remain unchanged allowing the microcontroller to proceed with normal operation after the reset line is allowed to return high. Another type of reset is when the Watchdog Timer overflows and resets the microcontroller. All types of reset operations result in different register conditions being setup.

Another reset exists in the form of a Low Voltage Reset, LVR, where a full reset, similar to the $\overline{\text{RES}}$ reset is implemented in situations where the power supply voltage falls below a certain threshold.

Reset Functions

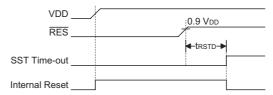
There are five ways in which a microcontroller reset can occur, through events occurring both internally and externally:

Power-on Reset

The most fundamental and unavoidable reset is the one that occurs after power is first applied to the microcontroller. As well as ensuring that the Program Memory begins execution from the first memory address, a power-on reset also ensures that certain other registers are preset to known conditions. All the I/O port and port control registers will power-up in a high condition ensuring that all pins will be first set to inputs.

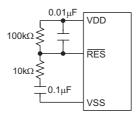
Although the microcontroller has an internal RC reset function, if the VDD power supply rise time is not fast enough or does not stabilise quickly at power-on, the internal reset function may be incapable of providing proper reset operation. For this reason it is recommended that an external RC network is connected to the \overline{RES} pin, whose additional time delay will ensure that the \overline{RES} pin remains low for an extended period to allow the power supply to stabilise. During this time delay, normal operation of the microcontroller will be inhibited. After the \overline{RES} line reaches a certain voltage value, the reset delay time t_{RSTD} is invoked to provide an extra delay time after which the microcontroller will begin normal operation. The abbreviation SST in the figures stands for System Start-up Timer.





Power-On Reset Timing Chart

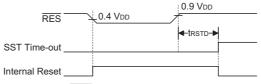
For most circuits a resistor connected between VDD and the $\overline{\text{RES}}$ pin and a capacitor connected between VSS and the $\overline{\text{RES}}$ pin will suffice, however for more reliable operation the following circuit is recommended.



Reset Circuit

RES Pin Reset

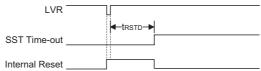
This type of reset occurs when the microcontroller is already running and the $\overline{\text{RES}}$ pin is forcefully pulled low by external hardware such as an external switch. In this case, as in the case of other resets, the Program Counter will reset to zero and program execution initiated from this point.



RES Reset Timing Chart

Low Voltage Reset - LVR

The microcontroller contains a low voltage reset circuit in order to monitor the supply voltage of the device, which is selected via a configuration option. If the supply voltage of the device drops to within a range of $0.9V \sim V_{LVR}$ such as might occur when changing the battery, the LVR will automatically reset the device internally. The LVR includes the following specifications: For a valid LVR signal, a low voltage, i.e., a voltage in the range between $0.9V \sim V_{LVR}$ must exist for greater than 1ms. If the low voltage state does not exceed 1ms, the LVR will ignore it and will not perform a reset function.

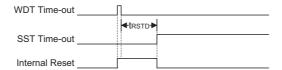


Low Voltage Reset Timing Chart



Watchdog Time-out Reset during Normal Operation

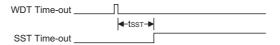
The Watchdog time-out Reset during normal operation is the same as a hardware $\overline{\text{RES}}$ pin reset except that the Watchdog time-out flag TO will be set to "1".



WDT Time-out Reset during Normal Operation Timing Chart

Watchdog Time-out Reset during Power Down

The Watchdog time-out Reset during Power Down is a little different from other kinds of reset. Most of the conditions remain unchanged except that the Program Counter and the Stack Pointer will be cleared to "0" and the TO flag will be set to "1". Refer to the A.C. Characteristics for t_{SST} details.



WDT Time-out Reset during Power Down Timing Chart

The different types of reset described affect the reset flags in different ways. These flags, known as PDF and TO are located in the status register and are controlled by various microcontroller operations, such as the Power Down function or Watchdog Timer. The reset flags are shown in the table:

то	PDF	RESET Conditions	
0	0	RES reset during power-on	
u	u	RES or LVR reset during normal operation	
1	u	WDT time-out reset during normal operation	
1	1	WDT time-out reset during Power Down	

[&]quot;u" stands for unchanged

The following table indicates the way in which the various components of the microcontroller are affected after a power-on reset occurs.

Item	Condition After RESET
Program Counter	Reset to zero
Interrupts	All interrupts will be disabled
WDT	Clear after reset, WDT begins counting
Timer/Event Counter	All Timer Counters will be turned off
Prescaler	The Timer Counter Prescaler will be cleared
Input/Output Ports	All I/O ports will be setup as inputs
Stack Pointer	Stack Pointer will point to the top of the stack



The different kinds of resets all affect the internal registers of the microcontroller in different ways. To ensure reliable continuation of normal program execution after a reset occurs, it is important to know what condition the microcontroller is in after a particular reset occurs. The following table describes how each type of reset affects each of the microcontroller internal registers. Note that where more than one package type exists the table will reflect the situation for the larger package type.

HT48E06 and HT48E10

Register	Reset (Power-on)	RES or LVR Reset	WDT Time-out (Normal Operation)	WDT Time-out (HALT)
MP0	1xxx xxxx	1uuu uuuu	1 uuu uuuu	1 u u u u u u
MP1	1xxx xxxx	1 u u u u u u	1 u u u u u u	1 u u u u u u
BP	0000 0000	0000 0000	0000 0000	uuuu uuuu
ACC	xxxx xxxx	uuuu uuuu	uuuu uuuu	uuuu uuuu
PCL	0000 0000	0000 0000	0000 0000	0000 0000
TBLP	xxxx xxxx	uuuu uuuu	uuuu uuuu	uuuu uuuu
TBLH	xxxx xxxx	xxuu uuuu	xxuu uuuu	xxuu uuuu
WDTS	0000 0111	0000 0111	0000 0111	uuuu uuuu
STATUS	00 xxxx	uu uuuu	1 u uuuu	11 uuuu
INTC	00 -000	00 -000	00 -000	uu-uuu
TMR	xxxx xxxx	xxxx xxxx	xxxx xxxx	uuuu uuuu
TMRC	00-0 1000	00-0 1000	00-0 1000	uu-u uuuu
PA	1111 1111	1111 1111	1111 1111	uuuu uuuu
PAC	1111 1111	1111 1111	1111 1111	uuuu uuuu
РВ	1111 1111	1111 1111	1111 1111	uuuu uuuu
PBC	1111 1111	1111 1111	1111 1111	uuuu uuuu
PC	111	111	111	u u u
PCC	111	111	111	u u u
EECR	1000	1000	1000	uuuu

"u" stands for unchanged

"x" stands for unknown

"-" stands for unimplemented



HT48E30

Register	Reset (Power-on)	RES or LVR Reset	WDT Time-out (Normal Operation)	WDT Time-out (HALT)
MP0	1xxx xxxx	1uuu uuuu	1 u u u u u u	1 u u u u u u
MP1	1xxx xxxx	1 u u u u u u	1 u u u u u u	1uuu uuuu
BP	0000 0000	0000 0000	0000 0000	uuuu uuuu
ACC	xxxx xxxx	uuuu uuuu	uuuu uuuu	uuuu uuuu
PCL	0000 0000	0000 0000	0000 0000	0000 0000
TBLP	xxxx xxxx	uuuu uuuu	uuuu uuuu	uuuu uuuu
TBLH	xxxx xxxx	xxuu uuuu	xxuu uuuu	xxuu uuuu
WDTS	0000 0111	0000 0111	0000 0111	uuuu uuuu
STATUS	00 xxxx	uu uuuu	1 u u u u u	11 uuuu
INTC	00 -000	00 -000	00 -000	uu -uuu
TMR	xxxx xxxx	xxxx xxxx	xxxx xxxx	uuuu uuuu
TMRC	00-0 1000	00-0 1000	00-0 1000	uu-u uuuu
PA	1111 1111	1111 1111	1111 1111	uuuu uuuu
PAC	1111 1111	1111 1111	1111 1111	uuuu uuuu
РВ	1111 1111	1111 1111	1111 1111	uuuu uuuu
PBC	1111 1111	1111 1111	1111 1111	uuuu uuuu
PC	11 1111	11 1111	11 1111	u u u u u u
PCC	11 1111	11 1111	11 1111	uu uuuu
PG	1	1	1	u
PGC	1	1	1	u
EECR	1000	1000	1000	u u u u

[&]quot;u" stands for unchanged

[&]quot;x" stands for unknown

[&]quot;-" stands for unimplemented



HT48E50

Register	Reset (Power-on)	RES or LVR Reset	WDT Time-out (Normal Operation)	WDT Time-out (HALT)
MP0	xxxx xxxx	uuuu uuuu	uuuu uuuu	uuuu uuuu
MP1	xxxx xxxx	uuuu uuuu	uuuu uuuu	uuuu uuuu
BP	0000 0000	0000 0000	0000 0000	uuuu uuuu
ACC	xxxx xxxx	uuuu uuuu	uuuu uuuu	uuuu uuuu
PCL	0000 0000	0000 0000	0000 0000	0000 0000
TBLP	xxxx xxxx	uuuu uuuu	uuuu uuuu	uuuu uuuu
TBLH	xxxx xxxx	xxuu uuuu	xxuu uuuu	xxuu uuuu
WDTS	0000 0111	0000 0111	0000 0111	uuuu uuuu
STATUS	00 xxxx	uu uuuu	1u uuuu	11 uuuu
INTC	-000 0000	-000 0000	-000 0000	-uuu uuuu
TMR0	xxxx xxxx	xxxx xxxx	xxxx xxxx	uuuu uuuu
TMR0C	00-0 1000	00-0 1000	00-0 1000	uu-u uuuu
TMR1H	xxxx xxxx	xxxx xxxx	xxxx xxxx	uuuu uuuu
TMR1L	xxxx xxxx	xxxx xxxx	xxxx xxxx	uuuu uuuu
TMR1C	00-01	00-01	0 0 - 0 1	u u – u u – – –
PA	1111 1111	1111 1111	1111 1111	uuuu uuuu
PAC	1111 1111	1111 1111	1111 1111	uuuu uuuu
РВ	1111 1111	1111 1111	1111 1111	uuuu uuuu
PBC	1111 1111	1111 1111	1111 1111	uuuu uuuu
PC	1111 1111	1111 1111	1111 1111	uuuu uuuu
PCC	1111 1111	1111 1111	1111 1111	uuuu uuuu
PD	1111 1111	1111 1111	1111 1111	uuuu uuuu
PDC	1111 1111	1111 1111	1111 1111	uuuu uuuu
PG	1	1	1	u
PGC	1	1	1	u
EECR	1000	1000	1000	u u u u

"u" stands for unchanged

"x" stands for unknown

"-" stands for unimplemented



HT48E70

Register	Reset (Power-on)	RES or LVR Reset	WDT Time-out (Normal Operation)	WDT Time-out (HALT)
MP0	xxxx xxxx	uuuu uuuu	uuuu uuuu	uuuu uuuu
MP1	xxxx xxxx	uuuu uuuu	uuuu uuuu	uuuu uuuu
BP	0000 0000	0000 0000	0000 0000	uuuu uuuu
ACC	xxxx xxxx	uuuu uuuu	uuuu uuuu	uuuu uuuu
PCL	0000 0000	0000 0000	0000 0000	0000 0000
TBLP	xxxx xxxx	uuuu uuuu	uuuu uuuu	uuuu uuuu
TBLH	xxxx xxxx	uuuu uuuu	uuuu uuuu	uuuu uuuu
WDTS	0000 0111	0000 0111	0000 0111	uuuu uuuu
STATUS	00 xxxx	uu uuuu	1u uuuu	11 uuuu
INTC	-000 0000	-000 0000	-000 0000	- u u u u u u
TMR0H	xxxx xxxx	xxxx xxxx	xxxx xxxx	uuuu uuuu
TMR0L	xxxx xxxx	xxxx xxxx	xxxx xxxx	uuuu uuuu
TMR0C	00-01	00-01	00-01	u u – u u – – –
TMR1H	xxxx xxxx	xxxx xxxx	xxxx xxxx	uuuu uuuu
TMR1L	xxxx xxxx	xxxx xxxx	xxxx xxxx	uuuu uuuu
TMR1C	00-0 1	00-01	00-01	u u – u u – – –
PA	1111 1111	1111 1111	1111 1111	uuuu uuuu
PAC	1111 1111	1111 1111	1111 1111	uuuu uuuu
РВ	1111 1111	1111 1111	1111 1111	uuuu uuuu
PBC	1111 1111	1111 1111	1111 1111	uuuu uuuu
PC	1111 1111	1111 1111	1111 1111	uuuu uuuu
PCC	1111 1111	1111 1111	1111 1111	uuuu uuuu
PD	1111 1111	1111 1111	1111 1111	uuuu uuuu
PDC	1111 1111	1111 1111	1111 1111	uuuu uuuu
PE	1111 1111	1111 1111	1111 1111	uuuu uuuu
PEC	1111 1111	1111 1111	1111 1111	uuuu uuuu
PF	1111 1111	1111 1111	1111 1111	uuuu uuuu
PFC	1111 1111	1111 1111	1111 1111	uuuu uuuu
PG	1111 1111	1111 1111	1111 1111	uuuu uuuu
PGC	1111 1111	1111 1111	1111 1111	uuuu uuuu
EECR	1000	1000	1000	u u u u

[&]quot;u" stands for unchanged

[&]quot;x" stands for unknown

[&]quot;-" stands for unimplemented



Oscillator

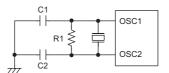
Various oscillator options offer the user a wide range of functions according to their various application requirements. Two types of system clocks can be selected while various clock source options for the Watchdog Timer, are provided for maximum flexibility. All oscillator options are selected through the configuration options.

System Clock Configurations

There are two methods of generating the system clock, using an external crystal/ceramic oscillator or an external RC network. The chosen method is selected through the configuration options.

System Crystal/Ceramic Oscillator

For most crystal oscillator configurations, the simple connection of a crystal across OSC1 and OSC2 will create the necessary phase shift and feedback for oscillation. However, to ensure oscillation for certain lower crystal frequencies and for all ceramic resonator applications, it is recommended that two small value capacitors and a resistor, the values of which are shown in the table, should be connected as shown in the diagram.



Crystal/Ceramic Oscillator

The table below shows the C1, C2 and R1 values for various crystal/ceramic oscillating frequencies.

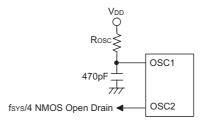
Crystal or Resonator	C1, C2	R1
4MHz Crystal	0pF	10kΩ
4MHz Resonator	10pF	12kΩ
3.58MHz Crystal	0pF	10kΩ
3.58MHz Resonator	25pF	10kΩ
2MHz Crystal and Resonator	25pF	10kΩ
1MHz Crystal	35pF	27kΩ
480kHz Resonator	300pF	9.1kΩ
455kHz Resonator	300pF	10kΩ
429kHz Resonator	300pF	10kΩ

The function of the resistor R1 is to ensure that the oscillator will switch off should low voltage conditions occur. Such a low voltage, as mentioned here, is one which is less than the lowest value of the MCU operating voltage. Note however that if the LVR is enabled then R1 can be removed.



System RC Oscillator

Using the external RC network as an oscillator requires that a resistor, with a value between $24k\Omega$ and $1M\Omega$, is connected between OSC1 and VDD, and a 470pF capacitor is connected to ground. The generated system clock divided by 4 will be provided on OSC2 as an output which can be used for external synchronization purposes. Note that as the OSC2 output is an NMOS open-drain type, a pull high resistor should be connected if it to be used to monitor the internal frequency. Although this is a cost effective oscillator configuration, the oscillation frequency can vary with VDD, temperature and process variations on the device itself and is therefore not suitable for applications where timing is critical or where accurate oscillator frequencies are required. For the value of the external resistor $R_{\rm OSC}$ please refer to the Appendix section for typical RC Oscillator vs. Temperature and $V_{\rm DD}$ characteristics graphics.



RC Oscillator

Note

An internal capacitor together with the external resistor, ROSC, are the components which determine the frequency of the oscillator. The external capacitor shown on the diagram does not influence the frequency of oscillation. This external capacitor should be added to improve oscillator stability if the open-drain OSC2 output is utilised in the application circuit.

Watchdog Timer Oscillator

The WDT oscillator is a fully integrated free running RC oscillator with a typical period of $65\mu s$ at 5V, requiring no external components. It is selected via configuration option. If selected, when the device enters the Power Down Mode, the system clock will stop running, however the WDT oscillator will continue to run and keep the watchdog function active. However, as the WDT will consume a certain amount of power when in the Power Down Mode, for low power applications, it may be desirable to disable the WDT oscillator by configuration option.



Power Down Mode and Wake-up

Power Down Mode

All of the Holtek microcontrollers have the ability to enter a Power Down Mode, also known as the HALT Mode or Sleep Mode. When the device enters this mode, the normal operating current, will be reduced to an extremely low standby current level. This occurs because when the device enters the Power Down Mode, the system oscillator is stopped which reduces the power consumption to extremely low levels, however, as the device maintains its present internal condition, it can be woken up at a later stage and continue running, without requiring a full reset. This feature is extremely important in application areas where the MCU must have its power supply constantly maintained to keep the device in a known condition but where the power supply capacity is limited such as in battery applications.

Entering the Power Down Mode

There is only one way for the device to enter the Power Down Mode and that is to execute the "HALT" instruction in the application program. When this instruction is executed, the following will occur:

- The system oscillator will stop running and the application program will stop at the "HALT" instruction.
- The Data Memory contents and registers will maintain their present condition.
- The WDT will be cleared and resume counting if the WDT clock source is selected to come from the WDT oscillator. The WDT will stop if its clock source originates from the system clock.
- The I/O ports will maintain their present condition.
- In the status register, the Power Down flag, PDF, will be set and the Watchdog time-out flag, TO, will be cleared.

Standby Current Considerations

As the main reason for entering the Power Down Mode is to keep the current consumption of the MCU to as low a value as possible, perhaps only in the order of several micro-amps, there are other considerations which must also be taken into account by the circuit designer if the power consumption is to be minimized. Special attention must be made to the I/O pins on the device. All high-impedance input pins must be connected to either a fixed high or low level as any floating input pins could create internal oscillations and result in increased current consumption. Care must also be taken with the loads, which are connected to I/Os, which are setup as outputs. These should be placed in a condition in which minimum current is drawn or connected only to external circuits that do not draw current, such as other CMOS inputs. Also note that additional standby current will also be required if the configuration options have enabled the Watchdog Timer internal oscillator.



Wake-up

After the system enters the Power Down Mode, it can be woken up from one of various sources listed as follows:

- · An external reset
- An external falling edge on Port A
- · A system interrupt
- · A WDT overflow

If the system is woken up by an external reset, the device will experience a full system reset, however, if the device is woken up by a WDT overflow, a Watchdog Timer reset will be initiated. Although both of these wake-up methods will initiate a reset operation, the actual source of the wake-up can be determined by examining the TO and PDF flags. The PDF flag is cleared by a system power-up or executing the clear Watchdog Timer instructions and is set when executing the "HALT" instruction. The TO flag is set if a WDT time-out occurs, and causes a wake-up that only resets the Program Counter and Stack Pointer, the other flags remain in their original status.

Each pin on Port A can be setup via an individual configuration option to permit a negative transition on the pin to wake-up the system. When a Port A pin wake-up occurs, the program will resume execution at the instruction following the "HALT" instruction.

If the system is woken up by an interrupt, then two possible situations may occur. The first is where the related interrupt is disabled or the interrupt is enabled but the stack is full, in which case the program will resume execution at the instruction following the "HALT" instruction. In this situation, the interrupt which woke-up the device will not be immediately serviced, but will rather be serviced later when the related interrupt is finally enabled or when a stack level becomes free. The other situation is where the related interrupt is enabled and the stack is not full, in which case the regular interrupt response takes place. If an interrupt request flag is set to "1" before entering the Power Down Mode, the wake-up function of the related interrupt will be disabled.

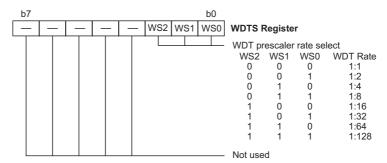
No matter what the source of the wake-up event is, once a wake-up situation occurs, a time period equal to 1024 system clock periods will be required before normal system operation resumes. However, if the wake-up has originated due to an interrupt, the actual interrupt subroutine execution will be delayed by an additional one or more cycles. If the wake-up results in the execution of the next instruction following the "HALT" instruction, this will be executed immediately after the 1024 system clock period delay has ended.

Watchdog Timer

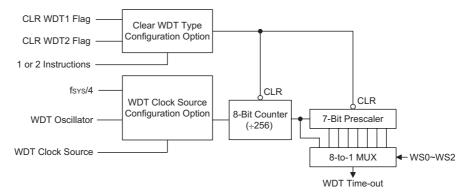
The Watchdog Timer is provided to prevent program malfunctions or sequences from jumping to unknown locations, due to certain uncontrollable external events such as electrical noise. It operates by providing a device reset when the WDT counter overflows. The WDT clock is supplied by one of two sources selected by configuration option: its own self-contained dedicated internal WDT oscillator, or the instruction clock which is the system clock divided by 4. Note that if the WDT configuration option has been disabled, then any instruction relating to its operation will result in no operation.



The internal WDT oscillator has an approximate period of $65\mu s$ at a supply voltage of 5V. If selected, it is first divided by 256 via an 8-stage counter to give a nominal period of 17ms. Note that this period can vary with VDD, temperature and process variations. For longer WDT time-out periods the WDT prescaler can be utilized. By writing the required value to bits 0, 1 and 2 of the WDTS register, known as WS0, WS1 and WS2, longer time-out periods can be achieved. with WS0, WS1 and WS2 all equal to 1, the division ratio is 1:128 which gives a maximum time-out period of about 2.1s.



A configuration option can select the instruction clock, which is the system clock divided by 4, as the WDT clock source instead of the internal WDT oscillator. If the instruction clock is used as the clock source, it must be noted that when the system enters the Power Down Mode, as the system clock is stopped, then the WDT clock source will also be stopped. Therefore the WDT will lose its protecting purposes. In such cases the system cannot be restarted by the WDT and can only be restarted using external signals. For systems that operate in noisy environments, using the internal WDT oscillator is therefore the recommended choice.



Watchdog Timer

Under normal program operation, a WDT time-out will initialise a device reset and set the status bit TO. However, if the system is in the Power Down Mode, when a WDT time-out occurs, only the Program Counter and Stack Pointer will be reset. Three methods can be adopted to clear the contents of the WDT and the WDT prescaler. The first is an external hardware reset, which means a low level on the $\overline{\text{RES}}$ pin, the second is using the watchdog software instructions and the third is via a "HALT" instruction.



There are two methods of using software instructions to clear the Watchdog Timer, one of which must be chosen by configuration option. The first option is to use the single "CLR WDT" instruction while the second is to use the two commands "CLR WDT1" and "CLR WDT2". For the first option, a simple execution of "CLR WDT" will clear the WDT while for the second option, both "CLR WDT1" and "CLR WDT2" must both be executed to successfully clear the WDT. Note that for this second option, if "CLR WDT1" is used to clear the WDT, successive executions of this instruction will have no effect, only the execution of a "CLR WDT2" instruction will clear the WDT. Similarly, after the "CLR WDT2" instruction has been executed, only a successive "CLR WDT1" instruction can clear the Watchdog Timer.

Configuration Options

Configuration options refer to certain options within the MCU that are programmed into the MTP Program Memory device during the programming process. During the development process, these options are selected using the HT-IDE software development tools. As these options are programmed into the device using the hardware programming tools, once they are selected they cannot be changed later by the application software.

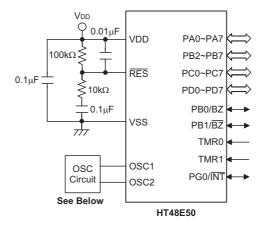
All options must be defined for proper system function, the details of which are shown in the table.

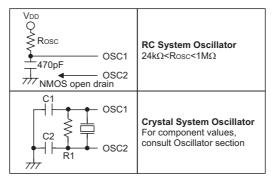
No.	Options
1	Watchdog Timer: enable or disable
2	Watchdog Timer clock source: WDT oscillator or f _{SYS} /4
3	CLRWDT instructions: 1 or 2 instructions
4	PA0~PA7: wake-up enable or disable (bit option)
5	PA, PB, PC, PD, PE, PF and PG: pull-high enable or disable (port numbers are device dependent)
6	PA input type: CMOS or Schmitt Trigger (HT48E06 excepted)
7	Buzzer function: enable or normal I/O
8	Buzzer clock source: Timer/Event Counter 0 or Timer/Event Counter 1 (HT48E50 and HT48E70 only)
9	System oscillator: Crystal or RC
10	LVR function: enable or disable



Application Circuits

The following application circuits although based around the HT48E50 device equally apply to all devices in the I/O Type MTP MCU with EEPROM series.





OSC Circuit



Part II

Programming Language





Chapter 2

Instruction Set Introduction

2

Instruction Set

Central to the successful operation of any microcontroller is its instruction set, which is a set of program instruction codes that directs the microcontroller to perform certain operations. In the case of Holtek microcontrollers, a comprehensive and flexible set of over 60 instructions is provided to enable programmers to implement their application with the minimum of programming overheads.

For easier understanding of the various instruction codes, they have been subdivided into several functional groupings.

Instruction Timing

Most instructions are implemented within one instruction cycle. The exceptions to this are branch, call, or table read instructions where two instruction cycles are required. One instruction cycle is equal to 4 system clock cycles, therefore in the case of an 8MHz system oscillator, most instructions would be implemented within $0.5\mu s$ and branch or call instructions would be implemented within $1\mu s$. Although instructions which require one more cycle to implement are generally limited to the JMP, CALL, RET, RETI and table read instructions, it is important to realize that any other instructions which involve manipulation of the Program Counter Low register or PCL will also take one more cycle to implement. As instructions which change the contents of the PCL will imply a direct jump to that new address, one more cycle will be required. Examples of such instructions would be "CLR PCL" or "MOV PCL, A". For the case of skip instructions, it must be noted that if the result of the comparison involves a skip operation then this will also take one more cycle, if no skip is involved then only one cycle is required.



Moving and Transferring Data

The transfer of data within the microcontroller program is one of the most frequently used operations. Making use of three kinds of MOV instructions, data can be transferred from registers to the Accumulator and vice-versa as well as being able to move specific immediate data directly into the Accumulator. One of the most important data transfer applications is to receive data from the input ports and transfer data to the output ports.

Arithmetic Operations

The ability to perform certain arithmetic operations and data manipulation is a necessary feature of most microcontroller applications. Within the Holtek microcontroller instruction set are a range of add and subtract instruction mnemonics to enable the necessary arithmetic to be carried out. Care must be taken to ensure correct handling of Carry and borrow data when results exceed 255 for addition and less than 0 for subtraction. The increment and decrement instructions INC, INCA, DEC and DECA provide a simple means of increasing or decreasing by a value of one of the values in the destination specified.

Logical and Rotate Operations

The standard logical operations such as AND, OR, XOR and CPL all have their own instruction within the Holtek microcontroller instruction set. As with the case of most instructions involving data manipulation, data must pass through the Accumulator which may involve additional programming steps. In all logical data operations, the zero flag may be set if the result of the operation is zero. Another form of logical data manipulation comes from the rotate instructions such as RR, RL, RRC and RLC which provide a simple means of rotating one bit right or left. Different rotate instructions exist depending on program requirements. Rotate instructions are useful for serial port programming applications where data can be rotated from an internal register into the Carry bit from where it can be examined and the necessary serial bit set high or low. Another application where rotate data operations are used is to implement multiplication and division calculations.

Branches and Control Transfer

Program branching takes the form of either jumps to specified locations using the JMP instruction or to a subroutine using the CALL instruction. They differ in the sense that in the case of a subroutine call, the program must return to the instruction immediately when the subroutine has been carried out. This is done by placing a return instruction RET in the subroutine which will cause the program to jump back to the address right after the CALL instruction. In the case of a JMP instruction, the program simply jumps to the desired location. There is no requirement to jump back to the original jumping off point as in the case of the CALL. One special and extremely useful set of branch instructions are the conditional branches. Here a decision is first made regarding the condition of a certain Data Memory or individual bits. Depending upon the conditions, the program will continue with the next instruction or skip over it and jump to the following instruction. These instructions are the key to decision making and branching within the program perhaps determined by the condition of certain input switches or by the condition of internal data bits.



Bit Operations

The ability to provide single bit operations on Data Memory is an extremely flexible feature of all Holtek microcontrollers. This feature is especially useful for output port bit programming where individual bits or port pins can be directly set high or low using either the "SET [m].i" or "CLR [m].i" instructions respectively. The feature removes the need for programmers to first read the 8-bit output port, manipulate the input data to ensure that other bits are not changed and then output the port with the correct new data. This read-modify-write process is taken care of automatically when these bit operation instructions are used.

Table Read Operations

Data storage is normally implemented by using registers. However, when working with large amounts of fixed data, the volume involved often makes it inconvenient to store the fixed data in individual memory. To overcome this problem, Holtek microcontrollers allow an area of Program Memory to be setup as a table where data can be directly stored. A set of easy to use instructions provides the means by which this fixed data can be referenced and retrieved from the Program Memory.

Other Operations

In addition to the above functional instructions, a range of other instructions also exist such as "HALT" instruction for power-down operation and instructions to control the operation of the Watchdog Timer for reliable program operations under extreme electric or electromagnetic environment. For their relevant operations, refer to the functional related sections.

Instruction Set Summary

Convention

x: Bits immediate data

m: Data Memory address

A: Accumulator

i: 0~7 number of bits

addr: Program Memory address

Mnemonic	Description	Cycles	Flag Affected
Arithmetic			
ADD A,[m]	Add Data Memory to ACC	1	Z, C, AC, OV
ADDM A,[m]	Add ACC to Data Memory	1 ^{Note}	Z, C, AC, OV
ADD A,x	Add immediate data to ACC	1	Z, C, AC, OV
ADC A,[m]	Add Data Memory to ACC with Carry	1	Z, C, AC, OV
ADCM A,[m]	Add ACC to Data Memory with Carry	1 ^{Note}	Z, C, AC, OV
SUB A,x	Subtract immediate data from the ACC	1	Z, C, AC, OV
SUB A,[m]	Subtract Data Memory from ACC	1	Z, C, AC, OV
SUBM A,[m]	Subtract Data Memory from ACC with result in Data Memory	1 ^{Note}	Z, C, AC, OV
SBC A,[m]	Subtract Data Memory from ACC with Carry	1	Z, C, AC, OV
SBCM A,[m]	Subtract Data Memory from ACC with Carry, result in Data Memory	1 ^{Note}	Z, C, AC, OV
DAA [m]	Decimal adjust ACC for Addition with result in Data Memory	1 ^{Note}	С



Mnemonic	Description	Cycles	Flag Affected
Logic Opera	tion	·	
AND A,[m]	Logical AND Data Memory to ACC	1	Z
OR A,[m]	Logical OR Data Memory to ACC	1	Z
XOR A,[m]	Logical XOR Data Memory to ACC	1	Z
ANDM A,[m]	Logical AND ACC to Data Memory	1 ^{Note}	Z
ORM A,[m]	Logical OR ACC to Data Memory	1 ^{Note}	Z
XORM A,[m]	Logical XOR ACC to Data Memory	1 ^{Note}	Z
AND A,x	Logical AND immediate Data to ACC	1	Z
OR A,x	Logical OR immediate Data to ACC	1	Z
XOR A,x	Logical XOR immediate Data to ACC	1	Z
CPL [m]	Complement Data Memory	1 ^{Note}	Z
CPLA [m]	Complement Data Memory with result in ACC	1	Z
Increment &	Decrement		
INCA [m]	Increment Data Memory with result in ACC	1	Z
INC [m]	Increment Data Memory	1 ^{Note}	Z
DECA [m]	Decrement Data Memory with result in ACC	1	Z
DEC [m]	Decrement Data Memory	1 ^{Note}	Z
Rotate			
RRA [m]	Rotate Data Memory right with result in ACC	1	None
RR [m]	Rotate Data Memory right	1 ^{Note}	None
RRCA [m]	Rotate Data Memory right through Carry with result in ACC	1	С
RRC [m]	Rotate Data Memory right through Carry	1 ^{Note}	С
RLA [m]	Rotate Data Memory left with result in ACC	1	None
RL [m]	Rotate Data Memory left	1 ^{Note}	None
RLCA [m]	Rotate Data Memory left through Carry with result in ACC	1	С
RLC [m]	Rotate Data Memory left through Carry	1 ^{Note}	С
Data Move			
MOV A,[m]	Move Data Memory to ACC	1	None
MOV [m],A	Move ACC to Data Memory	1 ^{Note}	None
MOV A,x	Move immediate data to ACC	1	None
Bit Operation	1		
CLR [m].i	Clear bit of Data Memory	1 ^{Note}	None
SET [m].i	Set bit of Data Memory	1 ^{Note}	None



Chapter 2 Instruction Set Introduction

Mnemonic	Description	Cycles	Flag Affected
Branch			
JMP addr	Jump unconditionally	2	None
SZ [m]	Skip if Data Memory is zero	1 ^{Note}	None
SZA [m]	Skip if Data Memory is zero with data movement to ACC	1 ^{Note}	None
SZ [m].i	Skip if bit i of Data Memory is zero	1 ^{Note}	None
SNZ [m].i	Skip if bit i of Data Memory is not zero	1 ^{Note}	None
SIZ [m]	Skip if increment Data Memory is zero	1 ^{Note}	None
SDZ [m]	Skip if decrement Data Memory is zero	1 ^{Note}	None
SIZA [m]	Skip if increment Data Memory is zero with result in ACC	1 ^{Note}	None
SDZA [m]	Skip if decrement Data Memory is zero with result in ACC	1 ^{Note}	None
CALL addr	Subroutine call	2	None
RET	Return from subroutine	2	None
RET A,x	Return from subroutine and load immediate data to ACC	2	None
RETI	Return from interrupt	2	None
Table Read			
TABRDC [m]	Read table (current page) to TBLH and Data Memory	2 ^{Note}	None
TABRDL [m]	Read table (last page) to TBLH and Data Memory	2 ^{Note}	None
Miscellaneou	ıs		
NOP	No operation	1	None
CLR [m]	Clear Data Memory	1 ^{Note}	None
SET [m]	Set Data Memory	1 ^{Note}	None
CLR WDT	Clear Watchdog Timer	1	TO, PDF
CLR WDT1	Pre-clear Watchdog Timer	1	TO, PDF
CLR WDT2	Pre-clear Watchdog Timer	1	TO, PDF
SWAP [m]	Swap nibbles of Data Memory	1 ^{Note}	None
SWAPA [m]	Swap nibbles of Data Memory with result in ACC	1	None
HALT	Enter Power Down Mode	1	TO, PDF

Note

- 1. For skip instructions, if the result of the comparison involves a skip then two cycles are required if no skip takes place only one cycle is required.
- $2. \, Any \, instruction \, which \, changes \, the \, contents \, of \, the \, PCL \, will \, also \, require \, 2 \, cycles \, for \, execution.$
- 3. For the "CLR WDT1" and "CLR WDT2" instructions, the TO and PDF flags may be affected by the execution status. The TO and PDF flags are cleared after both "CLR WDT1" and "CLR WDT2" instructions are consecutively executed. Otherwise the TO and PDF flags remain unchanged.





Chapter 3

Instruction Definition

3

ADC A,[m] Add Data Memory to ACC with Carry

Description The contents of the specified Data Memory, Accumulator and the carry flag are added. The

result is stored in the Accumulator.

Operation $ACC \leftarrow ACC + [m] + C$

Affected flag(s) OV, Z, AC, C

ADCM A,[m] Add ACC to Data Memory with Carry

Description The contents of the specified Data Memory, Accumulator and the carry flag are added. The

result is stored in the specified Data Memory.

Operation $[m] \leftarrow ACC + [m] + C$

Affected flag(s) OV, Z, AC, C

ADD A,[m] Add Data Memory to ACC

Description The contents of the specified Data Memory and the Accumulator are added. The result is

stored in the Accumulator.

 $\label{eq:acc} \begin{array}{ll} \text{Operation} & \text{ACC} \leftarrow \text{ACC} + [m] \\ \\ \text{Affected flag(s)} & \text{OV, Z, AC, C} \end{array}$

ADD A,x Add immediate data to ACC

Description The contents of the Accumulator and the specified immediate data are added. The result is

stored in the Accumulator.

Operation $ACC \leftarrow ACC + x$ Affected flag(s) OV, Z, AC, C

ADDM A,[m] Add ACC to Data Memory

Description The contents of the specified Data Memory and the Accumulator are added. The result is

stored in the specified Data Memory.

 $\label{eq:continuous} \begin{array}{ll} \text{Operation} & & [m] \leftarrow \text{ACC + } [m] \\ \\ \text{Affected flag(s)} & & \text{OV, Z, AC, C} \\ \end{array}$



AND A,[m] Logical AND Data Memory to ACC

Description Data in the Accumulator and the specified Data Memory perform a bitwise logical AND op-

eration. The result is stored in the Accumulator.

Operation $ACC \leftarrow ACC \text{ "AND" [m]}$

Affected flag(s) Z

AND A,x Logical AND immediate data to ACC

Description Data in the Accumulator and the specified immediate data perform a bitwise logical AND

operation. The result is stored in the Accumulator.

Operation $ACC \leftarrow ACC "AND" x$

Affected flag(s) Z

ANDM A,[m] Logical AND ACC to Data Memory

Description Data in the specified Data Memory and the Accumulator perform a bitwise logical AND op-

eration. The result is stored in the Data Memory.

Operation $[m] \leftarrow ACC "AND" [m]$

Affected flag(s) Z

CALL addr Subroutine call

Description Unconditionally calls a subroutine at the specified address. The Program Counter then in-

crements by 1 to obtain the address of the next instruction which is then pushed onto the stack. The specified address is then loaded and the program continues execution from this new address. As this instruction requires an additional operation, it is a two cycle instruc-

tion.

Operation Stack ← Program Counter + 1

Program Counter ← addr

Affected flag(s) None

CLR [m] Clear Data Memory

Description Each bit of the specified Data Memory is cleared to 0.

Operation $[m] \leftarrow 00H$ Affected flag(s) None

CLR [m].i Clear bit of Data Memory

Description Bit i of the specified Data Memory is cleared to 0.

 $\label{eq:continuous} \begin{array}{ll} \text{Operation} & [m].i \leftarrow 0 \\ \\ \text{Affected flag(s)} & \text{None} \end{array}$

Chapter 3 Instruction Definition

CLR WDT Clear Watchdog Timer

Description The TO, PDF flags and the WDT are all cleared.

Operation WDT cleared

 $TO \leftarrow 0$ PDF $\leftarrow 0$

Affected flag(s) TO, PDF

CLR WDT1 Pre-clear Watchdog Timer

Description The TO, PDF flags and the WDT are all cleared. Note that this instruction works in conjunc-

tion with CLR WDT2 and must be executed alternately with CLR WDT2 to have effect. Repetitively executing this instruction without alternately executing CLR WDT2 will have no

effect.

Operation WDT cleared

 $TO \leftarrow 0$ PDF $\leftarrow 0$

Affected flag(s) TO, PDF

CLR WDT2 Pre-clear Watchdog Timer

Description The TO, PDF flags and the WDT are all cleared. Note that this instruction works in conjunc-

tion with CLR WDT1 and must be executed alternately with CLR WDT1 to have effect. Repetitively executing this instruction without alternately executing CLR WDT1 will have no

effect.

Operation WDT cleared

 $TO \leftarrow 0$ $PDF \leftarrow 0$

Affected flag(s) TO, PDF

CPL [m] Complement Data Memory

Description Each bit of the specified Data Memory is logically complemented (1's complement). Bits

which previously contained a 1 are changed to 0 and vice versa.

Operation $[m] \leftarrow \overline{[m]}$

Affected flag(s) Z

CPLA [m] Complement Data Memory with result in ACC

Description Each bit of the specified Data Memory is logically complemented (1's complement). Bits

which previously contained a 1 are changed to 0 and vice versa. The complemented result is stored in the Accumulator and the contents of the Data Memory remain unchanged.

Operation $ACC \leftarrow \overline{[m]}$

DAA [m] Decimal-Adjust ACC for addition with result in Data Memory

Description Convert the contents of the Accumulator value to a BCD (Binary Coded Decimal) value re-

sulting from the previous addition of two BCD variables. If the low nibble is greater than 9 or if AC flag is set, then a value of 6 will be added to the low nibble. Otherwise the low nibble remains unchanged. If the high nibble is greater than 9 or if the C flag is set, then a value of 6 will be added to the high nibble. Essentially, the decimal conversion is performed by adding 00H, 06H, 60H or 66H depending on the Accumulator and flag conditions. Only the C flag may be affected by this instruction which indicates that if the original BCD sum is

greater than 100, it allows multiple precision decimal addition.

Operation $[m] \leftarrow ACC + 00H \text{ or}$

[m] \leftarrow ACC + 06H or [m] \leftarrow ACC + 60H or [m] \leftarrow ACC + 66H

Affected flag(s) C

DEC [m] Decrement Data Memory

Description Data in the specified Data Memory is decremented by 1.

Operation $[m] \leftarrow [m] - 1$

Affected flag(s) Z

DECA [m] Decrement Data Memory with result in ACC

Description Data in the specified Data Memory is decremented by 1. The result is stored in the Accu-

mulator. The contents of the Data Memory remain unchanged.

Operation $ACC \leftarrow [m] - 1$

Affected flag(s) Z

HALT Enter Power Down Mode

Description This instruction stops the program execution and turns off the system clock. The contents

of the Data Memory and registers are retained. The WDT and prescaler are cleared. The

power down flag PDF is set and the WDT time-out flag TO is cleared.

Operation $TO \leftarrow 0$

PDF ← 1

Affected flag(s) TO, PDF

INC [m] Increment Data Memory

Description Data in the specified Data Memory is incremented by 1.

Operation $[m] \leftarrow [m] + 1$

Chapter 3 Instruction Definition

INCA [m] Increment Data Memory with result in ACC

Description Data in the specified Data Memory is incremented by 1. The result is stored in the Accumu-

lator. The contents of the Data Memory remain unchanged.

Operation $ACC \leftarrow [m] + 1$

Affected flag(s) Z

JMP addr Jump unconditionally

Description The contents of the Program Counter are replaced with the specified address. Program

execution then continues from this new address. As this requires the insertion of a dummy

instruction while the new address is loaded, it is a two cycle instruction.

Operation Program Counter ← addr

Affected flag(s) None

MOV A,[m] Move Data Memory to ACC

Description The contents of the specified Data Memory are copied to the Accumulator.

 $\label{eq:continuous} \begin{array}{ll} \text{Operation} & \text{ACC} \leftarrow [m] \\ \\ \text{Affected flag(s)} & \text{None} \end{array}$

MOV A,x Move immediate data to ACC

Description The immediate data specified is loaded into the Accumulator.

 $\label{eq:acc} \mbox{Operation} \qquad \qquad \mbox{ACC} \leftarrow \mbox{x}$ $\mbox{Affected flag(s)} \qquad \qquad \mbox{None}$

MOV [m],A Move ACC to Data Memory

Description The contents of the Accumulator are copied to the specified Data Memory.

 $\begin{tabular}{ll} Operation & [m] \leftarrow ACC \\ Affected flag(s) & None \\ \end{tabular}$

NOP No operation

Description No operation is performed. Execution continues with the next instruction.

Operation No operation
Affected flag(s) None

OR A,[m] Logical OR Data Memory to ACC

Description Data in the Accumulator and the specified Data Memory perform a bitwise logical OR oper-

ation. The result is stored in the Accumulator.

Operation $ACC \leftarrow ACC "OR" [m]$



OR A,x Logical OR immediate data to ACC

Description Data in the Accumulator and the specified immediate data perform a bitwise logical OR op-

eration. The result is stored in the Accumulator.

Operation $ACC \leftarrow ACC "OR" x$

Affected flag(s) Z

ORM A,[m] Logical OR ACC to Data Memory

Description Data in the specified Data Memory and the Accumulator perform a bitwise logical OR oper-

ation. The result is stored in the Data Memory.

Operation $[m] \leftarrow ACC "OR" [m]$

Affected flag(s) Z

RET Return from subroutine

Description The Program Counter is restored from the stack. Program execution continues at the

restored address.

Operation Program Counter ← Stack

Affected flag(s) None

RET A,x Return from subroutine and load immediate data to ACC

Description The Program Counter is restored from the stack and the Accumulator loaded with the

specified immediate data. Program execution continues at the restored address.

Operation Program Counter ← Stack

 $ACC \leftarrow x$

Affected flag(s) None

RETI Return from interrupt

Description The Program Counter is restored from the stack and the interrupts are re-enabled by set-

ting the EMI bit. EMI is the enable master (global) interrupt bit (bit 0; register INTC). If an interrupt was pending when the RETI instruction is executed, the pending interrupt routine

will be processed before returning to the main program.

EMI ← 1

Affected flag(s) None

RL [m] Rotate Data Memory left

Description The contents of the specified Data Memory are rotated left by 1 bit with bit 7 rotated into bit

0.

Operation [m].(i+1) \leftarrow [m].i; (i = 0~6)

 $[m].0 \leftarrow [m].7$

Chapter 3 Instruction Definition

RLA [m] Rotate Data Memory left with result in ACC

Description The contents of the specified Data Memory are rotated left by 1 bit with bit 7 rotated into bit

0. The rotated result is stored in the Accumulator and the contents of the Data Memory re-

main unchanged.

Operation ACC.(i+1) \leftarrow [m].i; (i = 0~6)

 $ACC.0 \leftarrow [m].7$

Affected flag(s) None

RLC [m] Rotate Data Memory left through Carry

Description The contents of the specified Data Memory and the carry flag are rotated left by 1 bit. Bit 7

replaces the Carry bit and the original carry flag is rotated into bit 0.

Operation $[m].(i+1) \leftarrow [m].i; (i = 0~6)$

 $[m].0 \leftarrow C$

 $C \leftarrow [m].7$

Affected flag(s) C

RLCA [m] Rotate Data Memory left through Carry with result in ACC

Description Data in the specified Data Memory and the carry flag are rotated left by 1 bit. Bit 7 replaces

the Carry bit and the original carry flag is rotated into the bit 0. The rotated result is stored in

the Accumulator and the contents of the Data Memory remain unchanged.

Operation ACC.(i+1) \leftarrow [m].i; (i = 0~6)

 $\begin{array}{c} \mathsf{ACC.0} \leftarrow \mathsf{C} \\ \mathsf{C} \leftarrow [\mathsf{m}].7 \end{array}$

Affected flag(s) C

RR [m] Rotate Data Memory right

Description The contents of the specified Data Memory are rotated right by 1 bit with bit 0 rotated into

bit 7.

Operation [m].i \leftarrow [m].(i+1); (i = 0 \sim 6)

 $[m].7 \leftarrow [m].0$

Affected flag(s) None

RRA [m] Rotate Data Memory right with result in ACC

Description Data in the specified Data Memory and the carry flag are rotated right by 1 bit with bit 0 ro-

tated into bit 7. The rotated result is stored in the Accumulator and the contents of the Data

Memory remain unchanged.

Operation ACC.i \leftarrow [m].(i+1); (i = 0~6)

 $ACC.7 \leftarrow [m].0$



RRC [m] Rotate Data Memory right through Carry

Description The contents of the specified Data Memory and the carry flag are rotated right by 1 bit. Bit 0

replaces the Carry bit and the original carry flag is rotated into bit 7.

Operation [m].i \leftarrow [m].(i+1); (i = 0 \sim 6)

 $[m].7 \leftarrow C$ $C \leftarrow [m].0$

Affected flag(s) C

RRCA [m] Rotate Data Memory right through Carry with result in ACC

Description Data in the specified Data Memory and the carry flag are rotated right by 1 bit. Bit 0 re-

places the Carry bit and the original carry flag is rotated into bit 7. The rotated result is

stored in the Accumulator and the contents of the Data Memory remain unchanged.

Operation $ACC.i \leftarrow [m].(i+1); (i = 0~6)$

 $\begin{array}{c} ACC.7 \leftarrow C \\ C \leftarrow [m].0 \end{array}$

Affected flag(s) C

SBC A,[m] Subtract Data Memory from ACC with Carry

Description The contents of the specified Data Memory and the complement of the carry flag are

subtracted from the Accumulator. The result is stored in the Accumulator. Note that if the result of subtraction is negative, the C flag will be cleared to 0, otherwise if the result is pos-

itive or zero, the C flag will be set to 1.

Operation $ACC \leftarrow ACC - [m] - \overline{C}$

Affected flag(s) OV, Z, AC, C

SBCM A,[m] Subtract Data Memory from ACC with Carry and result in Data Memory

Description The contents of the specified Data Memory and the complement of the carry flag are sub-

tracted from the Accumulator. The result is stored in the Data Memory. Note that if the result of subtraction is negative, the C flag will be cleared to 0, otherwise if the result is

positive or zero, the C flag will be set to 1.

Operation $[m] \leftarrow ACC - [m] - \overline{C}$

Affected flag(s) OV, Z, AC, C

SDZ [m] Skip if decrement Data Memory is 0

Description The contents of the specified Data Memory are first decremented by 1. If the result is 0 the

following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not 0 the program

proceeds with the following instruction.

Operation $[m] \leftarrow [m] - 1$

Skip if [m] = 0

Chapter 3 Instruction Definition

SDZA [m] Skip if decrement Data Memory is zero with result in ACC

Description The contents of the specified Data Memory are first decremented by 1. If the result is 0, the

following instruction is skipped. The result is stored in the Accumulator but the specified Data Memory contents remain unchanged. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not

0, the program proceeds with the following instruction.

Operation $ACC \leftarrow [m] - 1$

Skip if ACC = 0

Affected flag(s) None

SET [m] Set Data Memory

Description Each bit of the specified Data Memory is set to 1.

Operation $[m] \leftarrow FFH$ Affected flag(s) None

SET [m].i Set bit of Data Memory

Description Bit i of the specified Data Memory is set to 1.

 $\label{eq:continuous} \begin{array}{ll} \text{Operation} & [m].i \leftarrow 1 \\ \\ \text{Affected flag(s)} & \text{None} \end{array}$

SIZ [m] Skip if increment Data Memory is 0

Description The contents of the specified Data Memory are first incremented by 1. If the result is 0, the

following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not 0 the program

proceeds with the following instruction.

Operation $[m] \leftarrow [m] + 1$

Skip if [m] = 0

Affected flag(s) None

SIZA [m] Skip if increment Data Memory is zero with result in ACC

Description The contents of the specified Data Memory are first incremented by 1. If the result is 0, the

following instruction is skipped. The result is stored in the Accumulator but the specified Data Memory contents remain unchanged. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not

0 the program proceeds with the following instruction.

Operation $ACC \leftarrow [m] + 1$

Skip if ACC = 0



SNZ [m].i Skip if bit i of Data Memory is not 0

Description If bit i of the specified Data Memory is not 0, the following instruction is skipped. As this re-

quires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is 0 the program proceeds with the following instruction.

Operation Skip if [m].i \neq 0

Affected flag(s) None

SUB A,[m] Subtract Data Memory from ACC

Description The specified Data Memory is subtracted from the contents of the Accumulator. The result

is stored in the Accumulator. Note that if the result of subtraction is negative, the C flag will be cleared to 0, otherwise if the result is positive or zero, the C flag will be set to 1.

 $\label{eq:acc} \begin{array}{ll} \text{Operation} & \text{ACC} \leftarrow \text{ACC} - [m] \\ \\ \text{Affected flag(s)} & \text{OV, Z, AC, C} \end{array}$

SUBM A,[m] Subtract Data Memory from ACC with result in Data Memory

Description The specified Data Memory is subtracted from the contents of the Accumulator. The result

is stored in the Data Memory. Note that if the result of subtraction is negative, the C flag will be cleared to 0, otherwise if the result is positive or zero, the C flag will be set to 1.

Operation $[m] \leftarrow ACC - [m]$ Affected flag(s) OV, Z, AC, C

SUB A,x Subtract immediate data from ACC

Description The immediate data specified by the code is subtracted from the contents of the Accumu-

lator. The result is stored in the Accumulator. Note that if the result of subtraction is negative, the C flag will be cleared to 0, otherwise if the result is positive or zero, the C flag will

be set to 1.

Operation $ACC \leftarrow ACC - x$ Affected flag(s) OV, Z, AC, C

SWAP [m] Swap nibbles of Data Memory

Description The low-order and high-order nibbles of the specified Data Memory are interchanged.

Operation [m].3~[m].0 \leftrightarrow [m].7 ~ [m].4

Affected flag(s) None

SWAPA [m] Swap nibbles of Data Memory with result in ACC

Description The low-order and high-order nibbles of the specified Data Memory are interchanged. The

result is stored in the Accumulator. The contents of the Data Memory remain unchanged.

Operation $ACC.3 \sim ACC.0 \leftarrow [m].7 \sim [m].4$

ACC.7 ~ ACC.4 \leftarrow [m].3 ~ [m].0



Chapter 3 Instruction Definition

SZ [m] Skip if Data Memory is 0

Description If the contents of the specified Data Memory is 0, the following instruction is skipped. As

this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not 0 the program proceeds with the following instruc-

tion.

Operation Skip if [m] = 0

Affected flag(s) None

SZA [m] Skip if Data Memory is 0 with data movement to ACC

Description The contents of the specified Data Memory are copied to the Accumulator. If the value is

zero, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not 0 the

program proceeds with the following instruction.

Operation $ACC \leftarrow [m]$

Skip if [m] = 0

Affected flag(s) None

SZ [m].i Skip if bit i of Data Memory is 0

quires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not 0, the program proceeds with the following instruction.

Operation Skip if [m].i = 0

Affected flag(s) None

TABRDC [m] Read table (current page) to TBLH and Data Memory

Description The low byte of the program code (current page) addressed by the table pointer (TBLP) is

moved to the specified Data Memory and the high byte moved to TBLH.

Operation $[m] \leftarrow program \ code \ (low \ byte)$

TBLH ← program code (high byte)

Affected flag(s) None

TABRDL [m] Read table (last page) to TBLH and Data Memory

Description The low byte of the program code (last page) addressed by the table pointer (TBLP) is

moved to the specified Data Memory and the high byte moved to TBLH.

 $\text{Operation} \qquad \qquad [m] \leftarrow \text{program code (low byte)}$

TBLH ← program code (high byte)



XOR A,[m] Logical XOR Data Memory to ACC

Description Data in the Accumulator and the specified Data Memory perform a bitwise logical XOR op-

eration. The result is stored in the Accumulator.

Operation $ACC \leftarrow ACC "XOR" [m]$

Affected flag(s) Z

XORM A,[m] Logical XOR ACC to Data Memory

Description Data in the specified Data Memory and the Accumulator perform a bitwise logical XOR op-

eration. The result is stored in the Data Memory.

Operation $[m] \leftarrow ACC "XOR" [m]$

Affected flag(s) Z

XOR A,x Logical XOR immediate data to ACC

Description Data in the Accumulator and the specified immediate data perform a bitwise logical XOR

operation. The result is stored in the Accumulator.

Operation $ACC \leftarrow ACC "XOR" x$



Chapter 4

Assembly Language and Cross Assembler

4

Assembly-Language programs are written as source files. They can be assembled into object files by the Holtek Cross Assembler. Object files are combined by the Cross Linker to generate a task file.

A source program is made up of statements and look up tables, giving directions to the Cross Assembler at assembly time or to the processor at run time. Statements are constituted by mnemonics (operations), operands and comments.

Notational Conventions

The following list describes the notations used by this document.

Example of Convention	Description of Convention	
	Syntax elements that are enclosed by a pair of brackets are optional. For example, the syntax of the command line is as follows:	
[optional items]	HASM [options] filename [;]	
[opacinal norms]	In the above command line, <i>options</i> and semicolon; are both optional, but <i>filename</i> is required, except for the following case:	
	Brackets in the instruction operands. In this case, the brackets refer to memory address.	
{choice1 choice2}	Braces and vertical bars stand for a choice between two or more items. Braces enclose the choices whereas vertical bars separate the choices. Only one item can be chosen.	



Example of Convention	Description of Convention	
	Three dots following an item signify that more items with the same form may be entered. For example, the directive PUB-LIC has the following form:	
Repeating elements	PUBLIC name1 [,name2 [,]]	
	In the above form, the three dots following <i>name2</i> indicate that many names can be entered as long as each is preceded by a comma.	

Statement Syntax

The construction of each statement is as follows:

[name] [operation] [operands] [;comment]

- All fields are optional.
- Each field (except the comment field) must be separated from other fields by at least one space or one tab character.
- Fields are not case-sensitive, i.e., lower-case characters are changed to upper-case characters before processing.

Name

Statements can be assigned labels to enable easy access by other statements. A name consists of the following characters:

with the following restrictions:

- 0~9 cannot be the first character of a name
- ? cannot stand alone as a name
- Only the first 31 characters are recognized

Operation

The operation defines the statement action of which two types exist, directives and instructions. Directives give directions to the Cross Assembler, specifying the manner in which the Cross Assembler is to generate the object code at assembly time. Instructions, on the other hand, give directions to the processor. They are translated to object code at assembly time, the object code in turn controls the behavior of the processor at run time.

Operand

Operands define the data used by directives and instructions. They can be made up of symbols, constants, expressions and registers.

Chapter 4 Assembly Language and Cross Assembler

Comment

Comments are the descriptions of codes. They are used for documentation only and are ignored by the Cross Assembler. Any text following a semicolon is considered a comment.

Assembly Directives

Directives give direction to the Cross Assembler, specifying the manner in which the Cross Assembler generates object code at assembly time. Directives can be further classified according to their behavior as described below.

Conditional Assembly Directives

The conditional block has the following form:

```
IF
statements
[ELSE
statements]
ENDIF
```

Syntax

```
IF expression
IFE expression
```

Description

The directives IF and IFE test the <code>expression</code> following them.

The ${\tt IF}$ directive grants assembly if the value of the ${\tt expression}$ is true, i.e. non-zero.

The IFE directive grants assembly if the value of the *expression* is false, i.e. zero.

Example

```
IF debugcase

ACC1 equ 5

extern username: byte
ENDIF
```

In this example, the value of the variable ACC1 is set to 5 and the username is declared as an external variable if the symbol debugcase is evaluated as true, i.e. nonzero.

Syntax

```
IFDEF name
IFNDEF name
```

Description

The directives **IFDEF** and **IFNDEF** test whether or not the given name has been defined. The **IFDEF** directive grants assembly only if the name is a label, a variable or a symbol. The **IFNDEF** directive grants assembly only if the name has not yet been defined. The conditional assembly directives support a nesting structure, with a maximum nesting level of 7.

Example

In this example, the buffer is allocated only if the buf flag has been previously defined.



File Control Directives

Syntax

INCLUDE file-name
or
INCLUDE "file-name"

Description

This directive inserts source codes from the source file given by file-name into the current source file during assembly. Cross Assembler supports at most 7 nesting levels.

• Example

```
INCLUDE macro.def
```

In this example, the Cross Assembler inserts the source codes from the file ${\tt macro.def}$ into the current source file.

Syntax

PAGE size

Description

This directive specifies the number of the lines in a page of the program listing file. The page size must be within the range from 10 to 255, the default page size is 60.

Example

PAGE 57

This example sets the maximum page size of the listing file to 57 lines.

Syntax

- LIST
- .NOLIST
- Description

The directives .LIST and .NOLIST decide whether or not the source program lines are to be copied to the program listing file. .NOLIST suppresses copying of subsequent source lines to the program listing file. .LIST restores the copying of subsequent source lines to the program listing file. The default is .LIST.

Example

```
.NOLIST
mov a, 1
mov b1, a
.LIST
```

In this example, the two instructions in the block enclosed by $.\mathtt{NOLIST}$ and $.\mathtt{LIST}$ are suppressed from copying to the source listing file.

Syntax

- .LISTMACRO
- .NOLISTMACRO
- Description

The directive .LISTMACRO causes the Cross Assembler to list all the source statements, including comments, in a macro. The directive .NOLISTMACRO suppresses the listing of all macro expansions. The default is .NOLISTMACRO.



Chapter 4 Assembly Language and Cross Assembler

Syntax

- LISTINCLUDE
- . NOLISTINCLUDE
- Description

The directive .LISTINCLUDE inserts the contents of all included files into the program listing. The directive .NOLISTINCLUDE suppresses the addition of included files. The default is .NOLISTINCLUDE.

Syntax

MESSAGE 'text-string'

Description

The directive MESSAGE directs the Cross Assembler to display the text-string on the screen. The characters in the text-string must be enclosed by a pair of single quotation marks.

Syntax

ERRMESSAGE 'error-string'

• Description

The directive **ERRMESSAGE** directs the Cross Assembler to issue an error. The characters in the <code>error-string</code> must be enclosed by a pair of single quotation marks.

Program Directives

Syntax (comment)

; text

Description

A comment consists of characters preceded by a semicolon (;) and terminated by an embedded carriage-return/line-feed.

Syntax

```
name .SECTION [align] [combine] 'class'
```

Description

The .SECTION directive marks the beginning of a program section. A program section is a collection of instructions and/or data whose addresses are relative to the section beginning with the name which defines that section. The name of a section can be unique or be the same as the name given to other sections in the program. Sections with the same complete names are treated as the same section.

The optional align type defines the alignment of the given section. It can be one of the following:

BYTE uses any byte address (the default align type)

WORD uses any word address
PARA uses a paragraph address
PAGE uses a page address

For the CODE section, the byte address is in a single instruction unit. **BYTE** aligns the section at any instruction address, **WORD** aligns the section at any even instruction address, **PARA** aligns the section at any instruction address which is a multiple of 16, and **PAGE** aligns the section at any instruction address with a multiple of 256.

For DATA sections, the byte address is in one byte units (8 bits/byte). **BYTE** aligns the section at any byte address, **WORD** aligns the section at any even address, **PARA** aligns the section at any address which is a multiple of 16, and **PAGE** aligns the section at any address which is a multiple of 256.

The optional combine type defines the way of combining sections having the same complete name (section and class name). It can be any one of the following:

COMMON

Creates overlapping sections by placing the start of all sections with the same complete name at the same address. The length of the resulting area is the length of the longest section.

- AT address

Causes all label and variable addresses defined in a section to be relative to the given address. The *address* can be any valid expression except a forward reference. It is an absolute address in a specified ROM/RAM bank and must be within the ROM/RAM range.

If no <code>combine</code> type is given, the section is combinative, i.e., this section can be concatenated with all sections having the same complete name to form a single, contiguous section.

The class type defines the sections that are to be loaded in the contiguous memory. Sections with the same class name are loaded into the memory one after another. The class name **CODE** is used for sections stored in ROM, and the class name **DATA** is used for sections stored in RAM. The complete name of a section consists of a section name and a class name. The named section includes all codes and data below (after) it until the next section is defined.

Syntax

ROMBANK banknum section-name [, section-name, ...]

Description

This directive declares which sections are allocated to the specified ROM bank. The <code>banknum</code> specifies the ROM bank, ranging from 0 to the maximum bank number of the destination MCU. The <code>section-name</code> is the name of the section defined previously in the program. More than one section can be declared in a bank as long as the total size of the sections does not exceed the bank size of 8K words. If this directive is not declared, bank 0 is assumed and all CODE sections defined in this program will be in bank 0. If a CODE section is not declared in any ROM bank, then bank 0 is assumed.

Syntax

RAMBANK banknum section-name [,section-name,...]

Description

This directive is similar to **ROMBANK** except that it specifies the RAM bank, the size of RAM bank is 256 bytes.

Syntax

END

Description

This directive marks the end of a program. Adding this directive to any included file should be avoided.



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Syntax

ORG expression

Description

This directive sets the location counter to expression. The subsequent code and data offsets begin at the new offset specified by expression. The code or data offset is relative to the beginning of the section where the directive **ORG** is defined. The attribute of a section determines the actual value of offset, absolute or relative.

Example

```
ORG 8 mov A, 1
```

In this example, the statement mov A, 1 begins at location 8 in the current section.

Syntax

```
PUBLIC name1 [, name2 [, ...]]
EXTERN name1:type [, name2:type [, ...]]
```

• Description

The PUBLIC directive marks the variable or label specified by a name that is available to other modules in the program. The EXTERN directive, on the other hand, declares an external variable, label or symbol of the specified name and type. The type can be one of the four types: BYTE, WORD and BIT (these three types are for data variables), and NEAR (a label type and used by call or jmp).

Example

```
PUBLIC start, setflag
EXTERN tmpbuf:byte

CODE .SECTION 'CODE'
start:

mov a, 55h
call setflag
....
setflag proc
mov tmpbuf, a
ret
setflag endp
end
```

In this example, both the label start and the procedure setflag are declared as public variables. Programs in other sources may refer to these variables. The variable tmpbuf is also declared as external. There should be a source file defining a byte that is named tmpbuf and is declared as a public variable.



Syntax

name PROC
name ENDP

Description

The PROC and ENDP directives mark a block of code which can be called or jumped to from other modules. The PROC creates a label <code>name</code> which stands for the address of the first instruction of a procedure. The Cross Assembler will set the value of the label to the current value of the location counter.

• Example

```
toggle PROC
mov tmpbuf, a
mov a, 1
xorm a, flag
mov a, tmpbuf
ret
toggle ENDP
```

Syntax

[label:] DC expression1 [, expression2 [,...]]

Description

The DC directive stores the value of <code>expression1</code>, <code>expression2</code> etc. in consecutive memory locations. This directive is used for the CODE section only. The bit size of the result value is dependent on the ROM size of the MCU. The Cross Assembler will clear any redundant bits; <code>expression1</code> has to be a value or a label. This directive may also be employed to setup the table in the code section.

Example

```
table1: DC 0128h, 025CH
```

In this example, the Cross Assembler reserves two units of ROM space and also stores 0128H and 025CH into these two ROM units.

Data Definition Directives

An assembly language program consists of one or more statements and comments. A statement or comment is a composition of characters, numbers, and names. The assembly language supports integer numbers. An integer number is a collection of binary, octal, decimal, or hexadecimal digits along with an optional radix. If no radix is given, the Cross Assembler uses the default radix (decimal). The table lists the digits that can be used with each radix.

Radix	Туре	Digits
В	Binary	01
Ο	Octal	01234567
D	Decimal	0123456789
Н	Hexadecimal	0123456789ABCDEF



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Syntax

```
[name] DB value1 [,value2 [, ...]]
[name] DW value1 [,value2 [, ...]]
[name] DBIT
[name] DB repeated-count DUP(?)
[name] DW repeated-count DUP(?)
```

• Description

These directives reserve the number of bytes/words specified by the repeated-count or reserve bytes/words only. value1 and value2 should be? due to the microcontroller RAM. The Cross Assembler will not initialize the RAM data. DBIT reserves a bit. The content? denotes uninitialized data, i.e., reserves the space of the data. The Cross Assembler will gather every 8 DBIT together and reserve a byte for these 8 DBIT variables.

Example

```
DATA .SECTION 'DATA'
tbuf DB ?
chksum DW ?
flag1 DBIT
sbuf DB ?
cflag DBIT
```

In this example, the Cross Assembler reserves byte location 0 for tbuf, location 1 and 2 for chksum, bit 0 of location 3 for flag1, location 4 for sbuf and bit 1 of location 3 for cflag.

Syntax

name LABEL {BIT | BYTE | WORD}

• Description

The name with the data type has the same address as the following data variable

Example

lab1	LABEL	WORD
d1	DB ?	
d2	DB ?	

In this example, d1 is the low byte of lab1 and d2 is the high byte of lab1.

Syntax

name \mathbf{EQU} expression

• Description

The EQU directive creates absolute symbols, aliases, or text symbols by assigning an <code>expression</code> to <code>name</code>. An absolute symbol is a name standing for a 16-bit value; an alias is a name representing another symbol; a text symbol is a name for another combination of characters. The <code>name</code> must be unique, i.e. not having been defined previously. The <code>expression</code> can be an integer, a string constant, an instruction mnemonic, a constant expression, or an address expression.

Example

```
accreg EQU 5 bmove EQU mov
```

In this example, the variable accreg is equal to 5, and bmove is equal to the instruction mov.



Macro Directives

Macro directives enable a block of source statements to be named, and then that name to be re-used in the source file to represent the statements. During assembly, the Cross Assembler automatically replaces each occurrence of the macro name with the statements in the macro definition.

A macro can be defined at any place in the source file as long as the definition precedes the first source line that calls this macro. In the macro definition, the macro to be defined may refer to other macros which have been previously defined. The Cross Assembler supports a maximum of 7 nesting levels.

Syntax

```
name     MACRO [dummy-parameter [, ...]]
     statements
     ENDM
```

The Cross Assembler supports a directive LOCAL for the macro definition.

Syntax

```
name LOCAL dummy-name [, ...]
```

Description

The **LOCAL** directive defines symbols available only in the defined macro. It must be the first line following the **MACRO** directive, if it is present. The <code>dummy-name</code> is a temporary name that is replaced by a unique name when the macro is expanded. The Cross Assembler creates a new actual name for <code>dummy-name</code> each time the macro is expanded. The actual name has the form <code>??digit</code>, where digit is a hexadecimal number within the range from 0000 to FFFF. A label should be added to the **LOCAL** directive when labels are used within the **MACRO/ENDM** block. Otherwise, the Cross Assembler will issue an error if this **MACRO** is referred to more than once in the source file.

In the following example, tmp1 and tmp2 are both dummy parameters, and are replaced by actual parameters when calling this macro. label1 and label2 are both declared LOCAL, and are replaced by ??0000 and ??0001 respectively at the first reference, if no other MACRO is referred. If no LOCAL declaration takes place, label1 and label2 will be referred to labels, similar to the declaration in the source program. At the second reference of this macro, a multiple define error message is displayed.

```
Delay MACRO tmp1, tmp2
   LOCAL
              label1, label2
          a, 70h
   mov
   mov
          tmp1, a
label1:
           tmp2, a
   mov
label2:
   clr
           wdt1
   clr
           wdt2
   sdz
           tmp2
           label2
   qmr
   sdz
           tmp1
           label1
   jmp
   ENDM
```



Chapter 4 Assembly Language and Cross Assembler

The following source program refers to the macro Delay:

```
; T.ASM
; Sample program for MACRO. .ListMacro
Delay MACRO tmp1, tmp2
LOCAL label1, label2
       mov
               a, 70h
       mov
               tmp1, a
label1:
               tmp2, a
       mov
       clr
               wdt1
       clr
               wdt2
               tmp2
label2
       sdz
       dmi
       sdz
               label1
data .section 'data'
BCnt db ?
SCnt db ?
code .section at 0 'code'
Delay BCnt, SCnt
end
```

The Cross Assembler will expand the macro Delay as shown in the following listing file. Note that the offset of each line in the macro body, from line 4 to line 17, is 0000. Line 24 is expanded to 11 lines and forms the macro body. In addition the formal parameters, tmp1 and tmp2, are replaced with the actual parameters, BCnt and SCnt, respectively.

```
File: T.asm
                      Holtek Cross-Assembler Version 2.80
      0000
                           ; T.ASM
                              Sample program for MACRO.
      0000
                          ListMacro
Delay MACRO tmp1, tmp2
LOCAL label1, label2
      0000
      0000
      0000
      0000
                                 mov
                                         a. 70h
      0000
                                         tmp1, a
                          label1:
      0000
      0000
  10
                          label2:
      0000
      0000
      0000
                                 clr
                                          wdt2
      0000
                                  sdz
                                          tmp2
                                          label2
  14
      0000
                                  jmp
                                  sdz
                                          tmp1
                                         label1
      0000
      0000
  18
      0000
                          data .section 'data'
  20
21
      0000
                          BCnt db ?
SCnt db ?
  22
      0002
                           code .section at 0 'code'
                          Delay BCnt, SCnt
mov a, 70h
  24
      0000
      0000 0F70
             0800
                       R1
                                  mov
                                         BCnt, a
                           ??0000:
            0080
                                         SCnt, a
      0002
                       R1
                                 mov
                           ??0001:
      0003
             0001
                                         wdt1
      0003
                                 clr
      0004
             0005
                                          wdt2
             1780
                       R1
                                  sdz
                                         SCnt
??0001
      0006
             2803
                                  jmp
      0007
0008
             1780
                       R1
                                  sdz
                                         BCnt
??0000
             2802
                                 jmp
      0009
                          end
```

0 Errors



Assembly Instructions

The syntax of an instruction has the following form:

```
[name:] mnemonic [operand1[,operand2]] [;comment]
where
```

 $name: \rightarrow label name$

mnemonic → instruction name (keywords)

operand1 → registers

memory address

operand2 → registers

memory address immediate value

Name

A name is made up of letters, digits, and special characters, and is used as a label.

Mnemonic

Mnemonic is an instruction name dependent upon the type of the MCU used in the source program.

Operand, Operator and Expression

Operands (source or destination) are the argument defining values that are to be acted on by instructions. They can be constants, variables, registers, expressions or keywords. When using the instruction statements, care must be taken to select the correct operand type, i.e. source operand or destination operand. The dollar sign \$ is a special operand, namely the current location operand.

An expression consists of many operands that are combined to describe a value or a memory location. The combined operators are evaluated at assembly time. They can contain constants, symbols, or any combination of constants and symbols that are separated by arithmetic operators.

Operators specify the operations to be performed while combining the operands of an expression. The Cross Assembler provides many operators to combine and evaluate operands. Some operators work with integer constants, some with memory values, and some with both. Operators handle the calculation of constant values that are known at the assembly time. The following are some operators provided by the Cross Assembler.

- Arithmetic operators + * / % (MOD)
- SHL and SHR operators
- Syntax

```
expression SHR count expression SHL count
```



Chapter 4 Assembly Language and Cross Assembler

The values of these shift bit operators are all constant values. The expression is shifted right SHR or left SHL by the number of bits specified by count. If bits are shifted out of position, the corresponding bits that are shifted in are zero-filled. The following are such examples:

```
mov A, 01110111b SHR 3 ; result ACC=00001110b mov A, 01110111b SHL 4 ; result ACC=01110000b
```

• Bitwise operators NOT, AND, OR, XOR

Syntax

```
NOT expression
expression1 AND expression2
expression1 OR expression2
expression1 XOR expression2
NOT is a bitwise complement.
AND is a bitwise AND.
OR is a bitwise inclusive OR.
XOR is a bitwise exclusive OR.
```

• OFFSET operator

- Syntax

OFFSET expression

The **OFFSET** operator returns the offset address of an *expression*. The *expression* can be a label, a variable, or other direct memory operand. The value returned by the OFFSET operator is an immediate operand.

• LOW, MID and HIGH operator

- Syntax
LOW expression
MID expression
HIGH expression

The LOW/MID/HIGH operator returns the value of an <code>expression</code> if the result of the <code>expression</code> is an immediate value. The LOW/MID/HIGH operators will then take the low/middle/high byte of this value. But if the <code>expression</code> is a label, the <code>LOW/MID/HIGH</code> operator will take the values of the low/middle/high byte of the program count of this label.

BANK operator

SyntaxBANK name

The BANK operator returns the bank number allocated to the section of the name declared. If the name is a label then it returns the rom bank number. If the name is a data variable then it returns the ram bank number. The format of the bank number is the same as the BP defined. For more information of the format please refer to the data sheets of the corresponding MCUs. (Note: The format of the BP might be different between MCUs.)

Example 1:

```
mov A, BANK start
mov BP,A
jmp start
```



Example 2:

```
mov A, BANK var
mov BP, A
mov A, OFFSET var
mov MP1, A
mov A, IAR1
```

• Operator precedence

Precedence	Operators
1 (Highest)	(),[]
2	+, - (unary), LOW, MID, HIGH, OFFSET, BANK
3	*, /, %, SHL, SHR
4	+, - (binary)
5	> (greater than), >= (greater than or equal to),
	< (less than), <= (less than or equal to)
6	== (equal to), != (not equal to)
7	! (bitwise NOT)
8	& (bitwise AND)
9 (Lowest)	(bitwise OR), ^(bitwise XOR)

Miscellaneous

Forward References

The Cross Assembler allows reference to labels, variable names, and other symbols before they are declared in the source code (forward named references). But symbols to the right of **EQU** are not allowed to be forward referenced.

Local Labels

A local label is a label with a fixed form such as number. The number can be 0~29. The function of a local label is the same as a label except that the local label can be used repeatedly. The local label should be used between any two consecutive labels and the same local label name may used between other two consecutive labels. The Cross Assembler will transfer every local label into a unique label before assembling the source file. At most 30 local labels can be defined between two consecutive labels.

Example.

Litampie.			
Label1:			; label
	\$1:		;; local label
		mov a, 1	
		jmp \$3	
	\$2:		;; local label
		mov a, 2	
		jmp \$1	
	\$3:		;; local label
		jmp \$2	
Label2:			; label
		jmp \$1	
	\$0:		;; local label
		jmp Label1	
	\$1:	jmp \$0	
Label3:			



Chapter 4 Assembly Language and Cross Assembler

Reserved Assembly Language Words

The following tables list all reserved words used by the assembly language.

•	Reserved Names	(directives, operators)	
	\$	DUP	INCLUDE

\$	DUP	INCLUDE	NOT
*	DW	LABEL	OFFSET
+	ELSE	.LIST	OR
_	END	.LISTINCLUDE	ORG
	ENDIF	.LISTMACRO	PAGE
1	ENDM	LOCAL	PARA
=	ENDP	LOW	PROC
?	EQU	MACRO	PUBLIC
[]	ERRMESSAGE	MESSAGE	RAMBANK
AND	EXTERN	MID	ROMBANK
BANK	HIGH	MOD	.SECTION
BYTE	IF	NEAR	SHL
DB	IFDEF	.NOLIST	SHR
DBIT	IFE	.NOLISTINCLUDE	WORD
DC	IFNDEF	.NOLISTMACRO	XOR

• Reserved Names (instruction mnemonics)

ADC	HALT	RLCA	SUB
ADCM	INC	RR	SUBM
ADD	INCA	RRA	SWAP
ADDM	JMP	RRC	SWAPA
AND	MOV	RRCA	SZ
ANDM	NOP	SBC	SZA
CALL	OR	SBCM	TABRDC
CLR	ORM	SDZ	TABRDL
CPL	RET	SDZA	XOR
CPLA	RETI	SET	XORM
DAA	RL	SIZ	
DEC	RLA	SIZA	
DECA	RLC	SNZ	

• Reserved Names (registers names)

A WDT WDT1 WDT2



Cross Assembler Options

The Cross Assembler options can be set via the Options menu Project command in HT-IDE3000. The Cross Assembler Options is located on the center part of the Project Option dialog box.

The symbols could be defined in the Define Symbol edit box.

Syntax

```
symbol1[=value1] [, symbol2[=value2] [, ...]]
• Example,
    debugflag=1, newver=3
```

The check box of the *Generate listing file* is used to decide whether the listing file should be generated or not. If the check box is checked, the listing file will be generated. Otherwise, it won't be generated

Assembly Listing File Format

The Assembly Listing File contains the source program listing and summary information. The first line of each page is a title line which include company name, the Cross Assembler version number, source file name, date/time of assembly and page number.

Source Program Listing

Each line in the source program has the following syntax:

```
line-number offset [code] statement
```

- Line-number is the number of the line starting from the first statement in the assembly source file (4 decimal digits).
- The 2nd field offset is the offset from the beginning of the current section to the code (4 hexadecimal digits)
- The 3rd field code is present only if the statement generates code or data (two hexadecimal 4-digit data)

The code shows the numeric value in hexadecimal if the value is known at assembly time. Otherwise, a proper flag will indicate the action required to compute the value. The following two flags may appear behind the code field.

```
R → relocatable address (Cross Linker must resolve)

E → external symbol (Cross Linker must resolve)

The following flag may appear before the code field
```

= \rightarrow **EQU** or equal-sign directive

The following 2 flags may appear in the code field

```
→ section address (Cross Linker must resolve)
```

 $nn[xx] \rightarrow DUP$ expression: nn DUP(?)

- The 4th field statement is the source statement shown exactly as it appears in the source file, or as expanded by a macro. The following flags may appear before a statement.
 - n → Macro-expansion nesting level
 - $\mathbf{C} \longrightarrow \text{line from INCLUDE file}$



Chapter 4 Assembly Language and Cross Assembler

• Summary

0 1 2 3 4 5 6 12345678901234567890123456789012345678901234567890... IIII oooo hhhh hhhh **EC** source-program-statement **Rn**

IIII → line number (4 digits, right alignment)

 $0000 \rightarrow \text{offset of code (4 digits)}$

 $hhhh \rightarrow two 4$ -digits for opcode

E → external reference

 ${f C}
ightarrow {f statement}$ from included file

 $\mathbf{R} \rightarrow \text{relocatable name}$

 $\textbf{n} \rightarrow \text{Macro-expansion nesting level}$

Summary of Assembly

The total warning number and total error number is the information provided at the end of the Cross Assembler listing file.

Miscellaneous

If any errors occur during assembly, each error message and error number will appear directly below the statement where the error occurred.



Example of assembly listing file

```
Holtek Cross-Assembler Version 2.86
File: SAMPLE.ASM
                                                                   Page 1
      0000
                         page 60
                                      'Sample Program 1'
      0000
                          message
      0000
      0000
                         .listinclude
      0000
                         .listmacro
      0000
      0000
                         #include "sample.inc"
      0000
                       C pa
                                equ
      0000
                        C pac
                                        [13h]
                                equ
      0000
                        C pb
                                equ
                       C pbc
C pc
C pcc
C
      0000
                                equ
                                        [15h]
      0000
                                equ
                                        [16h]
   6
      0000
                                equ
                                        [17h]
      0000
      0000
                         extern extlab : near
  10
      0000
                        extern extbl : byte
  11
      0000
  12
      0000
                         clrpb macro
  13
                         clr pb
                         endm
      0000
  14
      0000
  15
      0000
                         clrpa macro
                         mov a, 00h
      0000
                          mov pa, a
  19
      0000
                          clrpb
  20
      0000
                          endm
 21
22
      0000
                         data .section 'data'
      0000
                         b1 db?
b2 db?
  23
            00
  24
      0001
             00
      0002
             00
                         bit1 dbit
      0003
                          code .section 'code'
                    mov a, 055h
R mov b1, a
E mov extb1, a
mov a, 0aah
mov pac, a
  28
      0000
             0F55
  29
      0001
             0800
      0002
0003
 30
             0080
  31
             0FAA
      0004
  32
             0093
  33
      0005
                          clrpa
  33
      0005
             0F00
                       1 mov a, 00h
  33
                       1 mov [12h], a
  33
      0007
                       1 clrpb
  33
      0007
             1F14
                       2 clr [14h]
  34
      0008
             0700
                     R mov
                               a, b1
                      E mov a, bank extlab
E mov a, offset extb1
E jmp extlab
             0F00
      0009
  35
             0F00
      000A
  36
  37
      000B
             2800
  38
      000C
                         dw 1234h, 5678h, 0abcdh, 0ef12h
  39
      000C
             1234 5678
             ABCD EF12
  40 0010
                          end
        0 Errors
```



Part III

Development Tools





Chapter 5

MCU Programming Tools

5

To ease the process of application development, the importance and availability of supporting tools for microcontrollers cannot be underestimated. To support its range of MCUs, Holtek is fully committed to the development and release of easy to use and fully functional tools for its full range of devices. The overall development environment is known as the HT-IDE, while the operating software is known as the HT-IDE3000. The software provides an extremely user friendly Windows based approach for program editing and debugging while the HT-ICE emulator hardware provides full real time emulation with multi functional trace, stepping and breakpoint functions. With a complete set of interface cards for its full device range and regular software Service Pack updates, the HT-IDE development environment ensures that designers have the best tools to maximise efficiency in the design and release of their microcontroller applications.

HT-IDE Development Environment

The Holtek Integrated Development Environment, otherwise known as the HT-IDE, is a high performance integrated development environment designed around Holtek's series of 8-bit MCU devices. Incorporated within the system is the hardware and software tools necessary for rapid and easy development of applications based on the Holtek range of 8-bit MCUs. The key component within the HT-IDE system is the HT-ICE In-Circuit Emulator, capable of emulating the Holtek 8-bit MCUs in real time, in addition to providing powerful debugging and trace features. The HT-ICE In-Circuit Emulator also incorporates a device programmer which provides the user with all the tools required to design, debug and program their MTP devices.

As for the software, the HT-IDE3000 provides a friendly workbench to ease the process of application program development, by integrating all of the software tools, such as editor, Cross Assembler, Cross Linker, library and symbolic debugger into a user friendly Windows based environment.

As the HT-IDE3000 development system software includes the latest level Service Pack, it is only necessary to install the latest version of the HT-IDE3000 development system, which will automatically install the latest version Service Pack information. It is not necessary to install the Service Pack in a separate operation. The latest HT-IDE3000 development system software can be downloaded from the Holtek website. More detailed information on the development system is contained within the HT-IDE3000 User's Guide.



Some of the special features provided by the HT-IDE3000 include:

Emulation

• Real-time program instruction emulation

Hardware

- · Easy installation and usage
- Either internal or external oscillator
- Breakpoint mechanism
- Trace functions and trigger qualification supported by trace emulation chip
- Printer port for connecting the HT-ICE to a host computer
- I/O interface card for connecting the user's application board to the HT-ICE
- Programmer hardware integrated within the HT-ICE

Software

- · Windows based software utilities
- Source program level debugger (symbolic debugger)
- Multiple source program files workbench allows several program source files in a single application
- All tools are included for the development, debug, evaluation and generation of the final application program code
- Library for the setting up of common procedures which can be linked at a later date to other proiects.
- Virtual Peripheral Manager, VPM, simulates the behavior of peripheral devices.

Holtek In-Circuit Emulator - HT-ICE

Developed alongside the Holtek 8-bit microcontroller device range, the Holtek ICE is a fully functional in-circuit emulator for Holtek's 8-bit microcontroller devices. Incorporated within the system are a comprehensive set of hardware and software tools for rapid and easy development of user applications. Central to the system is the in-circuit hardware emulator, capable of emulating all of Holtek's 8-bit devices in real-time, while also providing a range of powerful debugging and trace facilities. Regarding software functions, the system incorporates a user-friendly Windows based workbench which integrates together functions, such as program editor, Cross Assembler, Cross Linker and library manager.

HT-ICE Interface Card

The interface card supplied with the HT-ICE can be used for most applications, however, it is possible for the user to omit the supplied interface card and design their own interface card. By including the necessary interface circuitry on their own interface card, the user has a means of directly connecting their target boards to the CN1 and CN2 connectors of the HT-ICE.



Programmer

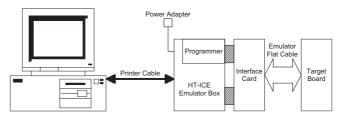
The HT-ICE In-Circuit Emulator has an integrated programmer as part of the hardware package, facilitating complete and convenient design, debug and device programming all within the HT-ICE environment. Holtek also supplies a stand alone programming tool which provides a quick and efficient means for low volume MTP programming. Full details on the different kinds of programmers can be found on the Holtek website.

Adapter Card

The HT-ICE on-board programmer is provided with a programming Adapter Card, which contains a standard Textool chip socket, in which DIP packages can be inserted for convenient programming. However if other package types are to be used, this standard Adapter Card can be removed and replaced by one of the many other Holtek supplied Adapter Cards, which are available for these other package types. Full details on the different kinds of Adapter Cards for the various package types can be found on the Holtek website.

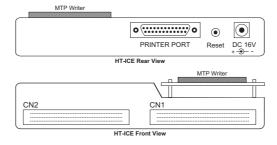
System Configuration

The HT-IDE system configuration is shown below, in which the host computer is a Pentium compatible machine with Windows 95/98/NT/2000/XP or later. Note that if Windows NT/2000/XP or later systems are used, then the HT-IDE3000 software must be installed in the Supervisor Privilege mode.



The HT-IDE system contains the following hardware components:

- HT-ICE emulator box with 1 printer port connector for connecting to the host machine, I/O signal connector and one power-on LED
- I/O interface card for connecting the target board to the HT-ICE box
- Power Adapter
- 25-pin D-type printer cable
- Integrated programmer

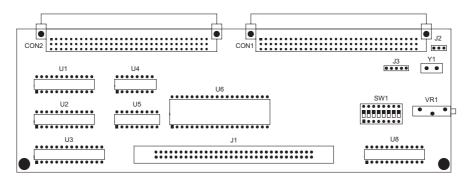




HT-ICE Interface Card Settings

The HT-ICE interface card (CPCB48E000004A) as shown below, is a PCB used to connect the HT-ICE emulator to the user's target board. It has the following functions:

- · External clock source
- MCU socket pin assignment



The external clock source has two modes, RC and Crystal. If a crystal clock is to be used, positions 2 and 3 should be shorted on J2 and a suitable crystal inserted into location Y1. Otherwise, if an RC clock is to be used, positions 1 and 2 should be shorted and the system frequency adjusted using VR1. Refer to the Tools/Mask Option Menu of the HT-IDE3000 User's Guide for the clock source and system frequency selection.

The J1 connector provides the I/O port connections as well as other pins. The DIP switch, SW1, should be set according to which device is selected and in accordance with the following table:

Part No.	Deekene	Socket	SW1							
Part No.	Package	Socket	1	2	3	4	5	6	7	8
HT48E06	18DIP/SOP, 20SSOP	U5, U8	OFF	OFF	ON	OFF	ON	OFF	OFF	_
HT48E10	24SKDIP/SOP	U1	OFF	OFF	ON	OFF	ON	OFF	OFF	
HT48E30	24SKDIP/SOP, 28SKDIP/SOP	U2, U3	ON	OFF	OFF	ON	OFF	OFF	OFF	
HT48E50	28SKDIP/SOP	U3	ON	OFF	OFF	ON	OFF	OFF	ON	_
HT48E50	48SSOP	J1	ON	OFF	OFF	OFF	OFF	OFF	OFF	_
HT48E70	48SSOP, 64QFP	J1	OFF	_						

The pin assignments in the DIP socket locations are defined so as to match the device pin assignments. The interface card VME connectors directly interface to the CON1 and CON2 connectors on the HT-ICE.



Installation

System Requirement

The hardware and software requirements for installing HT-IDE3000 system are as follows:

- PC/AT compatible machine with Pentium or higher CPU
- SVGA color monitor
- At least 32M RAM for best performance
- CD ROM drive (for CD installation)
- At least 20M free disk space
- Parallel port to connect PC and HT-ICE
- Windows 95/98/NT/2000/XP

Windows 95/98/NT/2000/XP are trademarks of Microsoft Corporation.

Hardware Installation

• Step 1

Plug the power adapter into the power connector of the HT-ICE

• Step 2

Connect the target board to the HT-ICE by using the I/O interface card or flat cable

Step 3

Connect the HT-ICE to the host machine using the printer cable

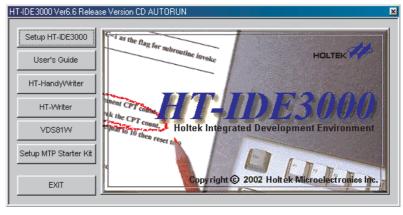
The LED on the HT-ICE should now be lit, if not, there is an error and your dealer should be contacted.

Caution

Exercise care when using the power adapter. It is strongly recommended that only the power adapter supplied by Holtek be used. First plug the power adapter to the power connector of the HT-ICE before connecting to the PC.

Software Installation

It is recommended that the latest version of the HT-IDE3000 software should first be downloaded from the Holtek website and installed, however the version provided on the supplied CD ROM can also be installed. A window similar to the following will be displayed.





I/O Type MTP MCU with EEPROM

By selecting the "Setup HT-IDE3000" option and following the on screen installation instructions the full development system software can be installed.

The setup process will create four subdirectories under the directory which was chosen for the software installation. These directories have the names, BIN, INCLUDE, LIB and SAMPLE. The BIN subdirectory contains all the system executables .EXE files, dynamic link libraries .DLL files and the configuration .CFG and .FMT files for all the supported MCU devices. The INCLUDE subdirectory contains all the include .H and .INC files provided by Holtek. The LIB subdirectory contains the library .LIB files provided by Holtek. The SAMPLE subdirectory contains a number of sample programs.

When the computer has been restarted and the HT-IDE3000 software run for the first time, the system will request certain user information as shown in the figure. Select appropriate area and fill in the company name and ID. The HT-IDE3000 provider can be requested to supply an ID number.





Chapter 6

Quick Start

6

This chapter gives a brief description of using HT-IDE3000 to develop an application project.

Step 1 – Create a New Project

- Click on Project menu and select New command
- Enter your project name and select an MCU from the combo box
- Click OK button and the system will ask you to setup the configuration options
- Setup all configuration options and click Save button

Step 2 – Add Source Program Files to the Project

- Create your source files by using File/New command
- Write your program and save them with a file name, say TEST.ASM
- Click on Project menu and select Edit command
- An Edit Project dialog will ask you to add/delete files to/from the project
- Select a source file name, say TEST.ASM, and click Add button
- · Click OK button after you setup all files in the project

Step 3 – Build the Project

- Click on Project menu and select Build command
- The system will assemble/compile all source files in the project
 - If there are some errors in the programs, double click on the error message line and the system will prompt you the position where the error happened.
 - If all the program files are error free, the system will create a Task file and download to the HT-ICE for debug.
- You may repeat this step before you finish debugging your programs

Step 4 - Programming the MTP Device

- Build the project for creating the .MTP file
- Click on Tools menu and select the Writer command to program the MTP devices





Appendix





Appendix A

Device Characteristic Graphics

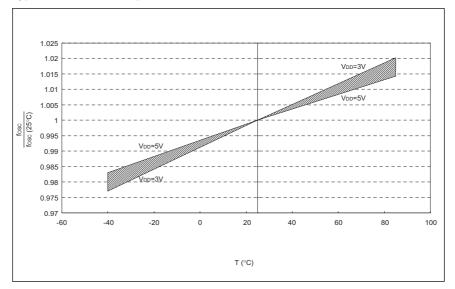


The following characteristic graphics depicts typical device behavior. The data presented here is a statistical summary of data gathered on units from different lots over a period of time. This is for information only and the figures were not tested during manufacturing.

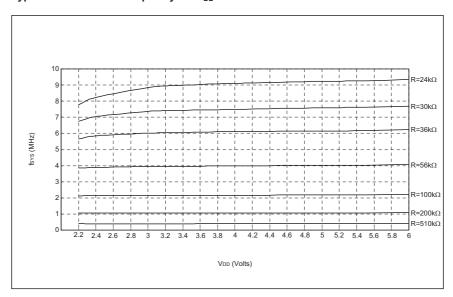
In some of the graphs, the data exceeding the specified operating range are shown for information purposes only. The device will operate properly only within the specified range.



Typical RC OSC vs. Temperature

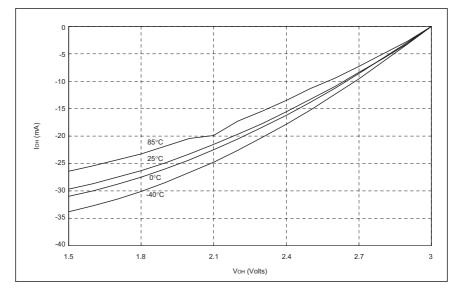


Typical RC Oscillator Frequency vs. V_{DD}

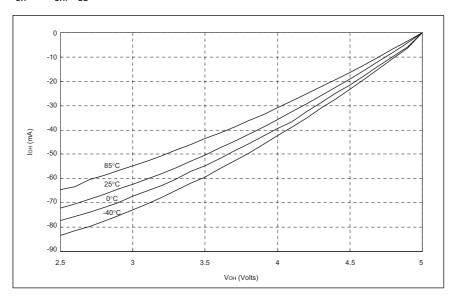




 I_{OH} vs. V_{OH} , V_{DD} =3V

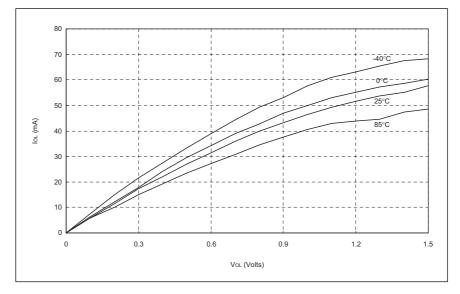


I_{OH} vs. V_{OH}, V_{DD}=5V

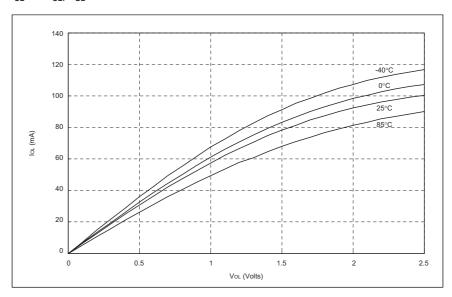




 I_{OL} vs. V_{OL} , V_{DD} =3V

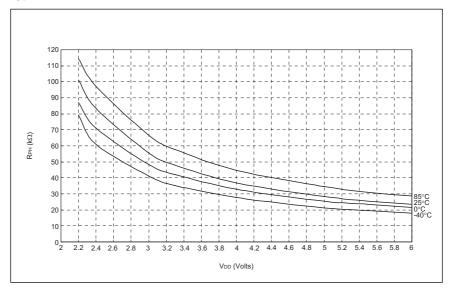


 I_{OL} vs. V_{OL} , V_{DD} =5V

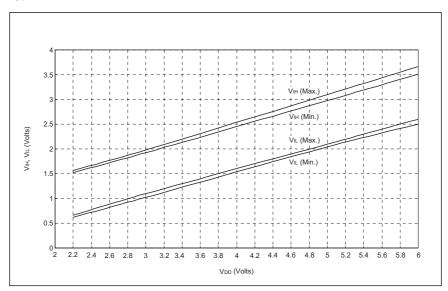




Typical R_{PH} vs. V_{DD}

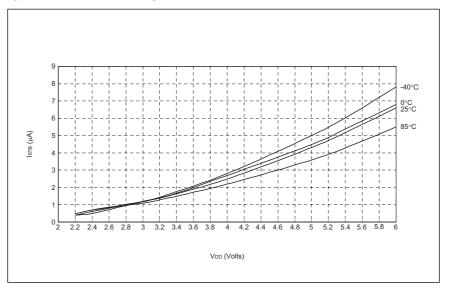


Typical $V_{IH},\,V_{IL}$ vs. V_{DD} in -40°C to +85°C

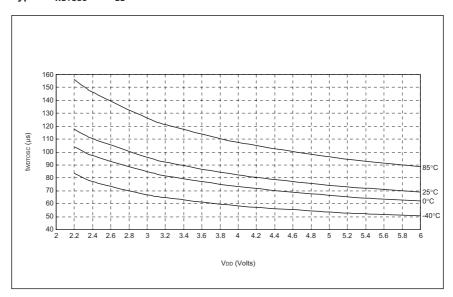




Typical I_{STB} vs. V_{DD} Watchdog Enable

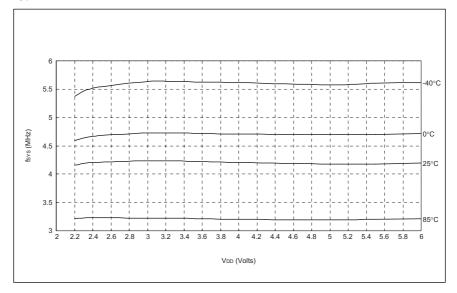


Typical t_{WDTOSC} vs. V_{DD}

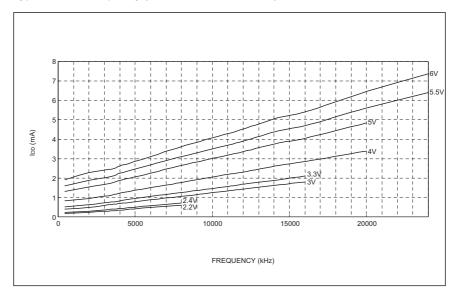




Typical Internal RC OSC vs. V_{DD}

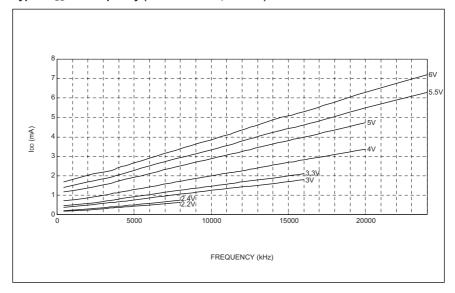


Typical I_{DD} vs. Frequency (External Clock, Ta=-40°C)

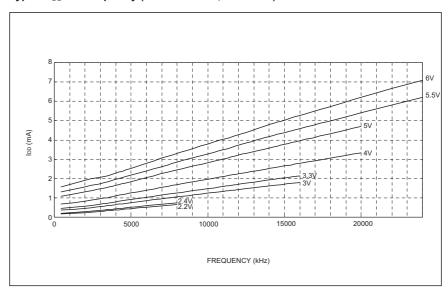




Typical I_{DD} vs. Frequency (External Clock, Ta=0°C)

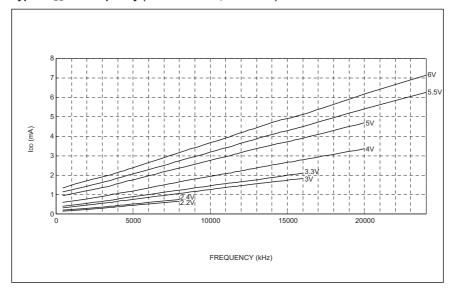


Typical I_{DD} vs. Frequency (External Clock, Ta=+25 $^{\circ}$ C)

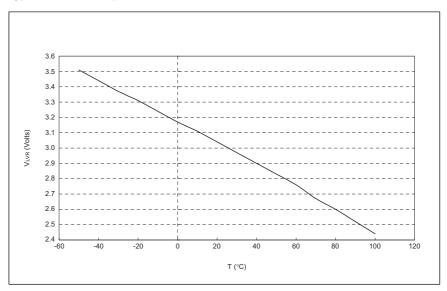


Appendix A Device Characteristic Graphics

Typical I_{DD} vs. Frequency (External Clock, Ta=+85°C)



Typical V_{LVR} vs. Temperature







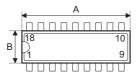
Appendix B

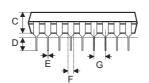
Package Information





18-pin DIP (300mil) Outline Dimensions



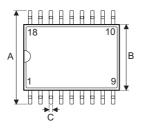


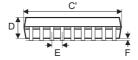


Complete I	Dimensions in mil				
Symbol	Min.	Nom.	Max.		
Α	895		915		
В	240	_	260		
С	125	_	135		
D	125	_	145		
E	16	_	20		
F	50	_	70		
G	_	100	_		
Н	295	_	315		
I	335	_	375		
α	0°	_	15°		



18-pin SOP (300mil) Outline Dimensions



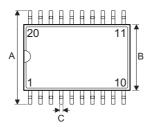


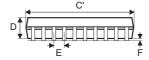


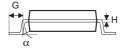
Complete	Dimensions in mil				
Symbol	Min.	Max.			
Α	394	_	419		
В	290	_	300		
С	14	_	20		
C'	447	_	460		
D	92	_	104		
E	_	50	_		
F	4	_	_		
G	32	_	38		
Н	4	_	12		
α	0°	_	10°		



20-pin SSOP (150mil) Outline Dimensions



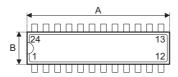


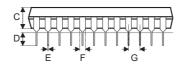


Quantita I	Dimensions in mil				
Symbol	Min.	Max.			
Α	228	_	244		
В	150	_	158		
С	8	_	12		
C'	335	_	347		
D	49	_	65		
E	_	25	_		
F	4	_	10		
G	15	_	50		
Н	7	_	10		
α	0°	_	8°		



24-pin SKDIP (300mil) Outline Dimensions



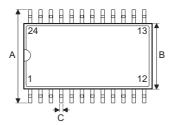


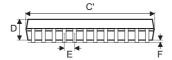


Complete I	Dimensions in mil				
Symbol	Min.	Nom.	Max.		
Α	1235	_	1265		
В	255	_	265		
С	125	_	135		
D	125	_	145		
E	16	_	20		
F	50	_	70		
G	_	100	_		
Н	295	_	315		
1	345	_	360		
α	0°	_	15°		



24-pin SOP (300mil) Outline Dimensions



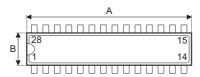


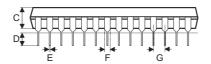


Symbol	Dimensions in mil		
	Min.	Nom.	Max.
А	394	_	419
В	290	_	300
С	14	_	20
C'	590	_	614
D	92	_	104
E	_	50	_
F	4	_	_
G	32	_	38
Н	4	_	12
α	0°	_	10°



28-pin SKDIP (300mil) Outline Dimensions



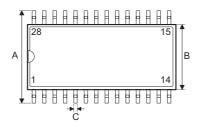


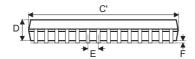


Complete I	Dimensions in mil		
Symbol	Min.	Nom.	Max.
Α	1375	_	1395
В	278	_	298
С	125	_	135
D	125	_	145
E	16	_	20
F	50	_	70
G	_	100	_
Н	295	_	315
I	330	_	375
α	0°	_	15°



28-pin SOP (300mil) Outline Dimensions





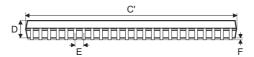


0	Dimensions in mil		
Symbol	Min.	Nom.	Max.
Α	394	_	419
В	290	_	300
С	14	_	20
C'	697	_	713
D	92	_	104
E	_	50	_
F	4	_	_
G	32	_	38
Н	4	_	12
α	0°	_	10°



48-pin SSOP (300mil) Outline Dimensions



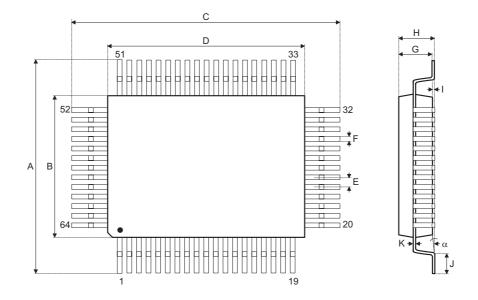




Symbol	Dimensions in mil		
	Min.	Nom.	Max.
Α	395	_	420
В	291	_	299
С	8	_	12
C'	613	_	637
D	85	_	99
E	_	25	_
F	4	_	10
G	25	_	35
Н	4	_	12
α	0°	_	8°



64-pin QFP (14×20) Outline Dimensions



Symbol	Dimensions in mm		
	Min.	Nom.	Max.
Α	18.80	_	19.20
В	13.90	_	14.10
С	24.80	_	25.20
D	19.90	_	20.10
E	_	1	_
F	_	0.40	_
G	2.50	_	3.10
Н	_	_	3.40
I	_	0.10	_
J	1.15	_	1.45
К	0.10	_	0.20
α	0°	_	7°





Holtek Semiconductor Inc. (Headquarters)

No.3, Creation Rd. II, Science Park, Hsinchu, Taiwan

Tel: 886-3-563-1999 Fax: 886-3-563-1189 http://www.holtek.com.tw

Holtek Semiconductor Inc. (Taipei Sales Office)

4F-2, No. 3-2, YuanQu St., Nankang Software Park, Taipei 115, Taiwan Tel: 886-2-2655-7070

Fax: 886-2-2655-7373

Fax: 886-2-2655-7383 (International sales hotline)

Holtek Semiconductor Inc. (Shanghai Sales Office) 7th Floor, Building 2, No.889, Yi Shan Rd., Shanghai, China 200233

Tel: 86-21-6485-5560 Fax: 86-21-6485-0313 http://www.holtek.com.cn

Holtek Semiconductor Inc. (Shenzhen Sales Office)

5/F, Unit A, Productivity Building, Cross of Science M 3rd Road and Gaoxin M 2nd Road, Science Park, Nanshan District,

Shenzhen, China 518057

Tel: 86-755-8616-9908, 86-755-8616-9308

Fax: 86-755-8616-9533

Holtek Semiconductor Inc. (Beijing Sales Office)

Suite 1721, Jinyu Tower, A129 West Xuan Wu Men Street, Xicheng District, Beijing, China 100031

Tel: 86-10-6641-0030, 86-10-6641-7751, 86-10-6641-7752

Fax: 86-10-6641-0125

Holtek Semiconductor Inc. (Chengdu Sales Office)

709, Building 3, Champagne Plaza, No.97 Dongda Street, Chengdu, Sichuan, China 610016

Tel: 86-28-6653-6590 Fax: 86-28-6653-6591

Holmate Semiconductor, Inc. (North America Sales Office)

46729 Fremont Blvd., Fremont, CA 94538

Tel: 1-510-252-9880 Fax: 1-510-252-9885 http://www.holmate.com

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